

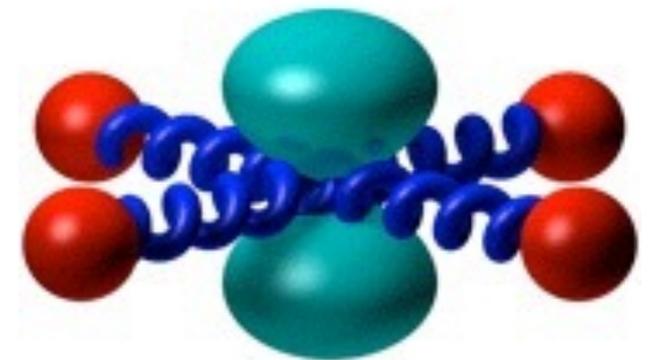
# Multiscale modelling of materials chemomechanics: brittle fracture of oxides and semiconductors

James Kermode

Department of Physics  
King's College London

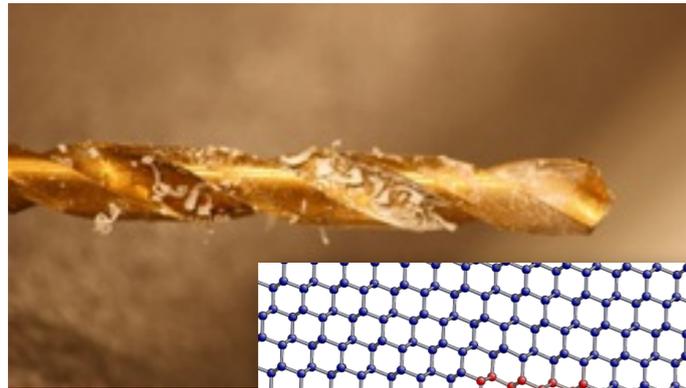
**KING'S**  
*College*  
**LONDON**

University of London

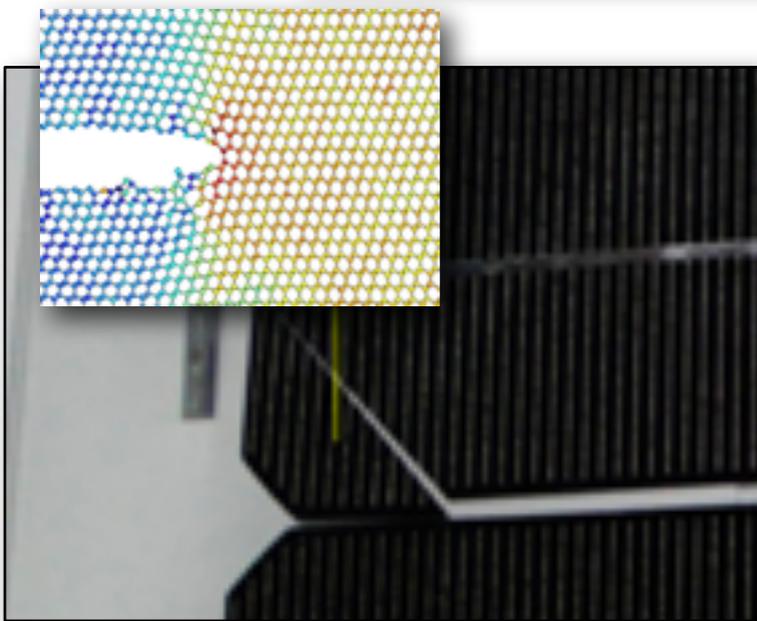
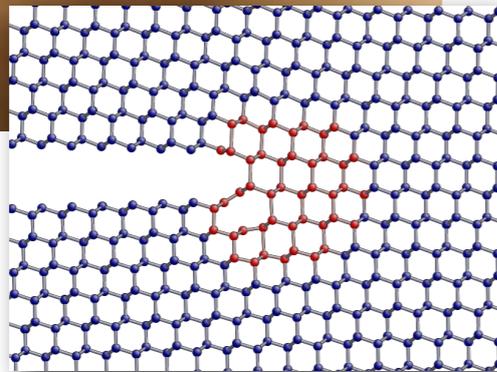


# Multiscale Modelling of "Chemomechanical" Materials Failure Processes

## Covalent Materials



Diamond

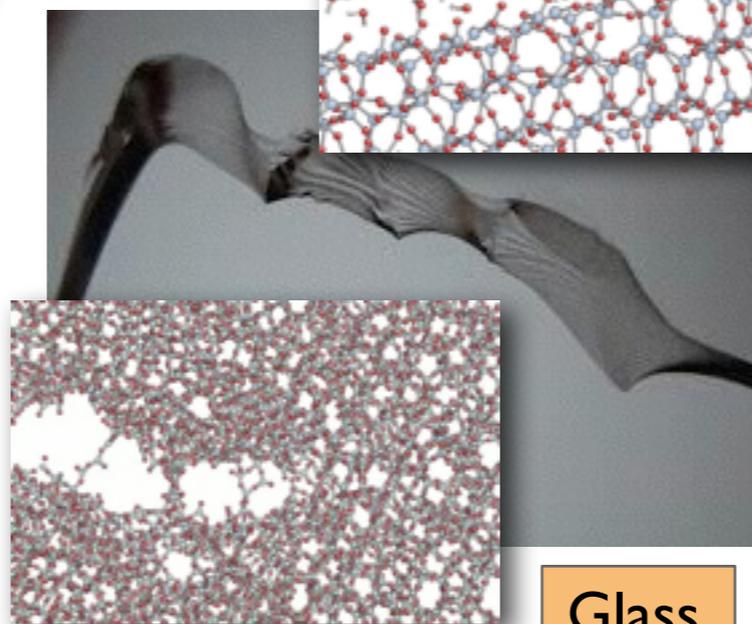
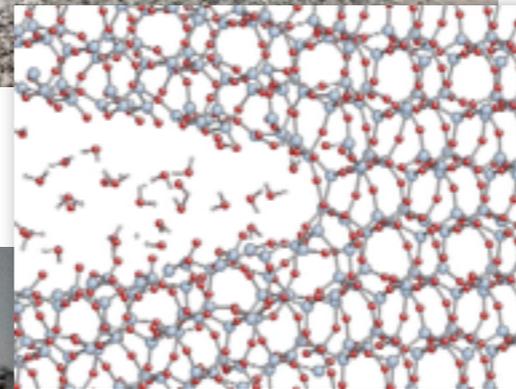


Silicon Photovoltaics

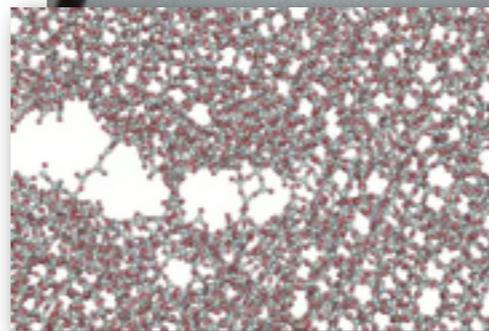
## Oxides



Rocks



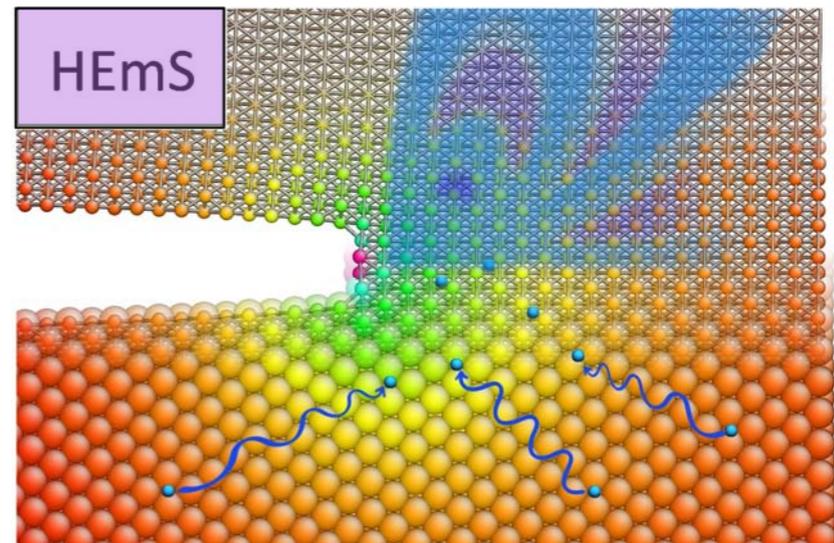
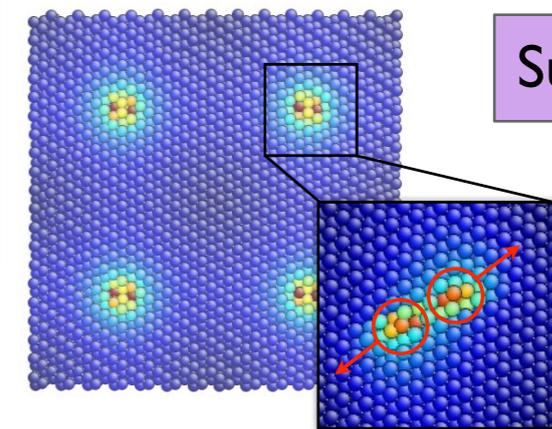
Glass



## Metals

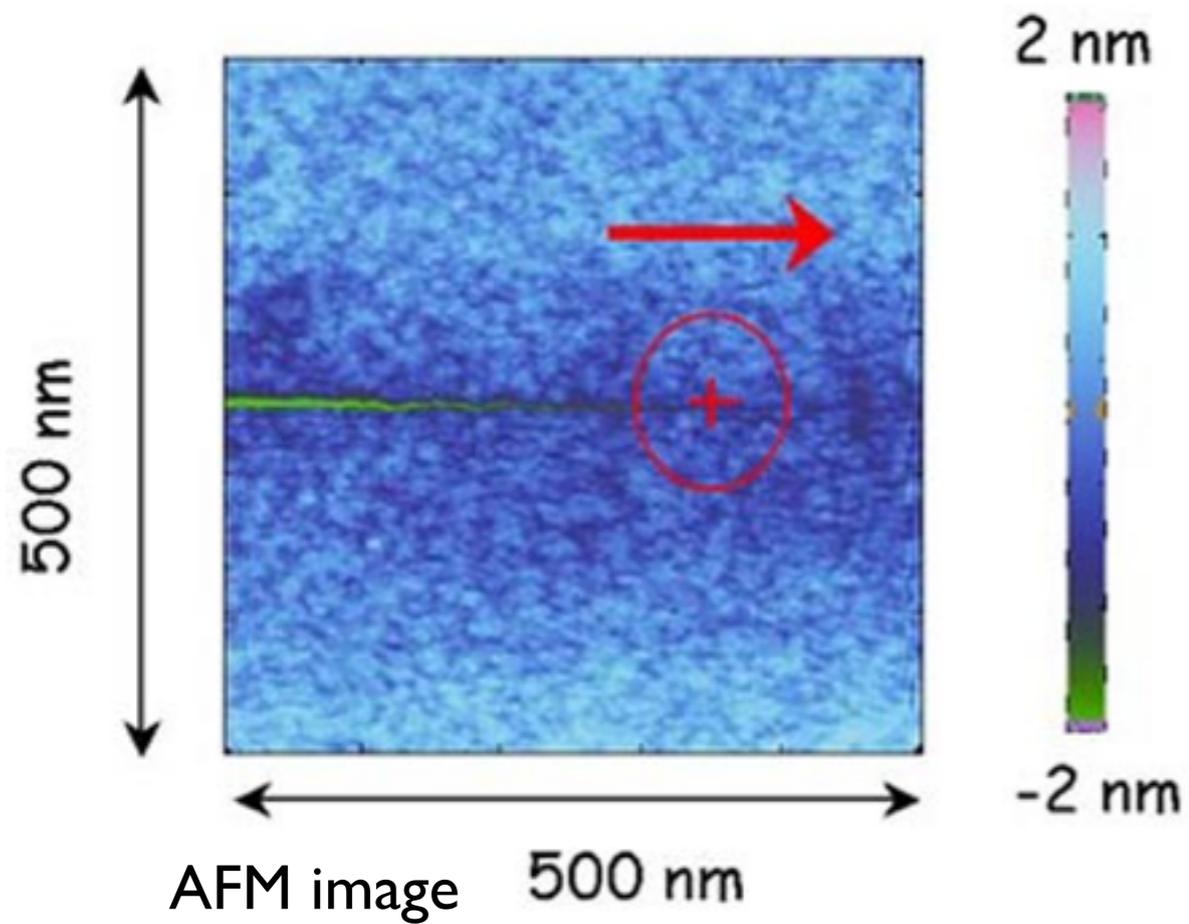


Superalloys

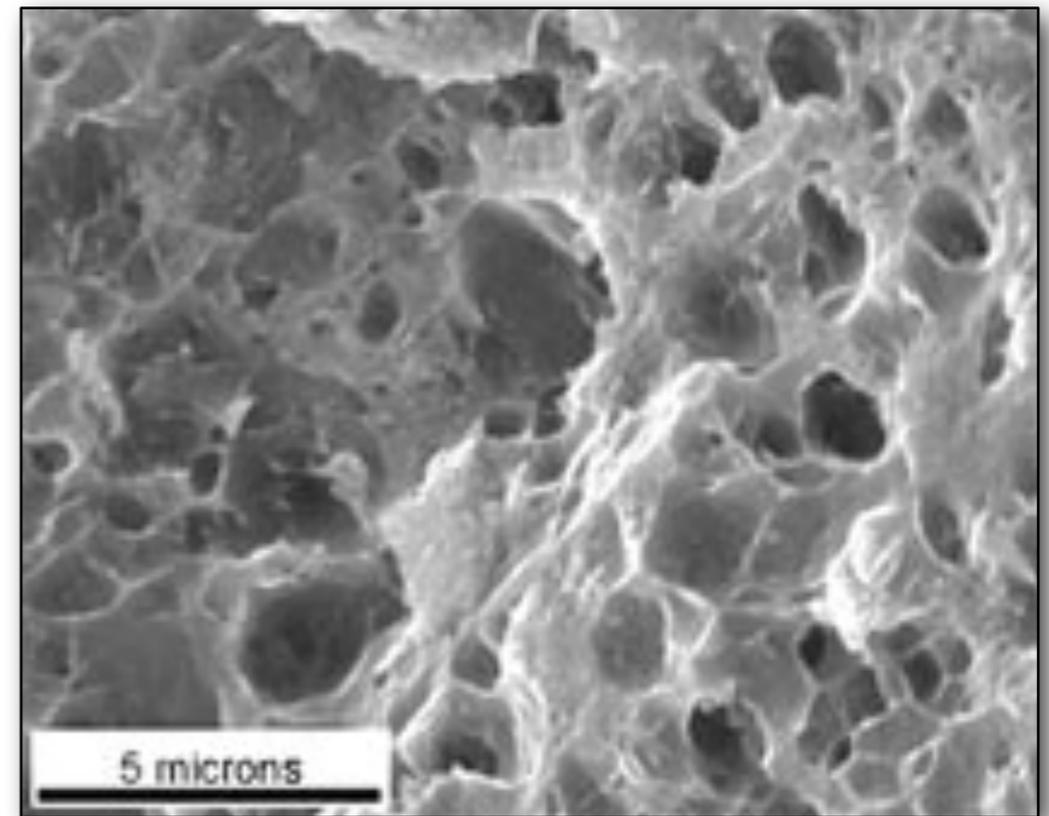


# Fracture at the Microscale

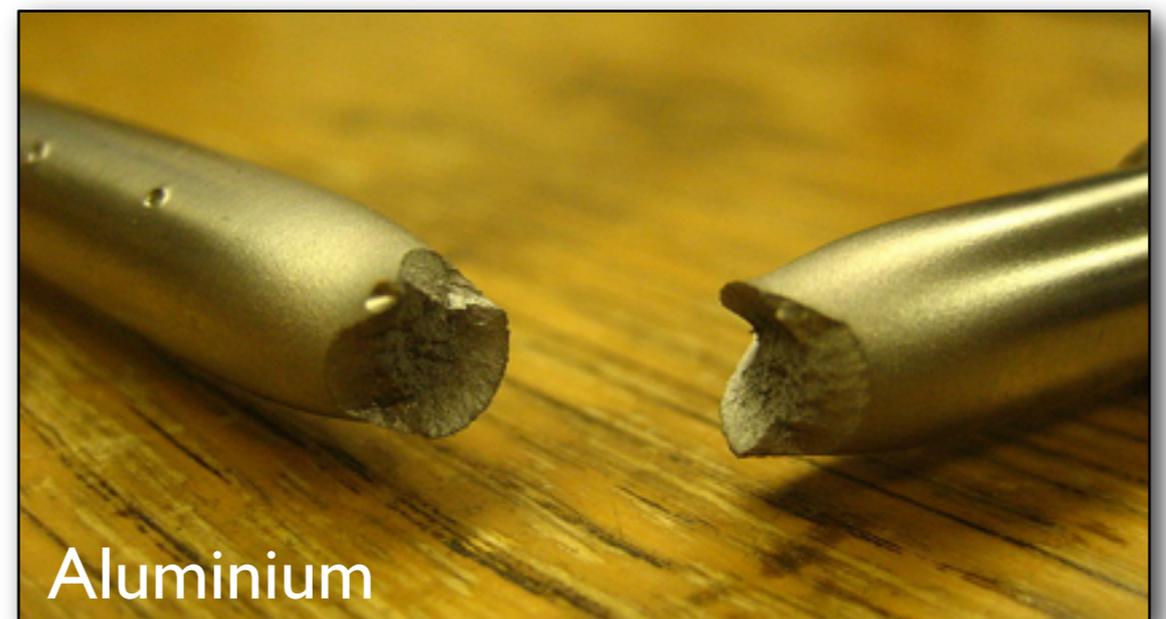
## Brittle Fracture



## Ductile Fracture

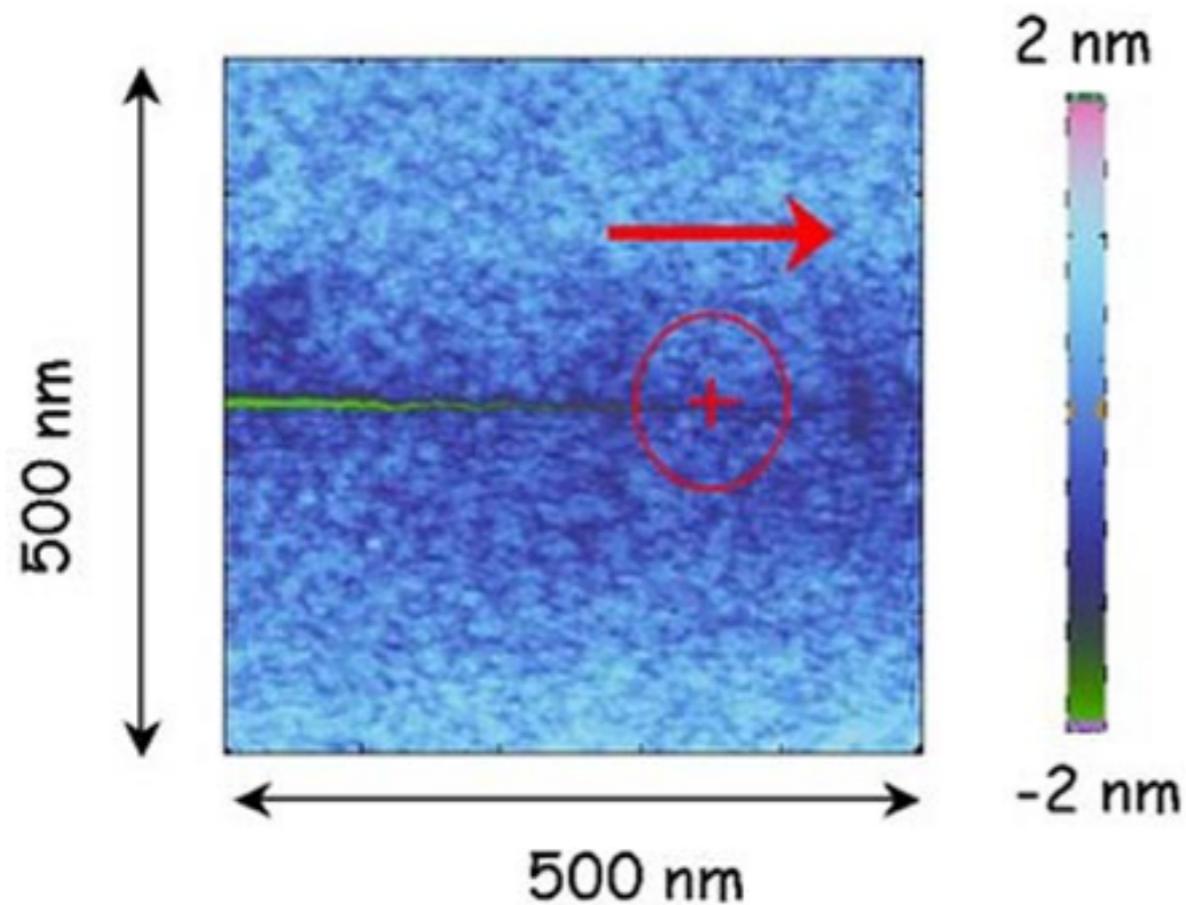


SEM image

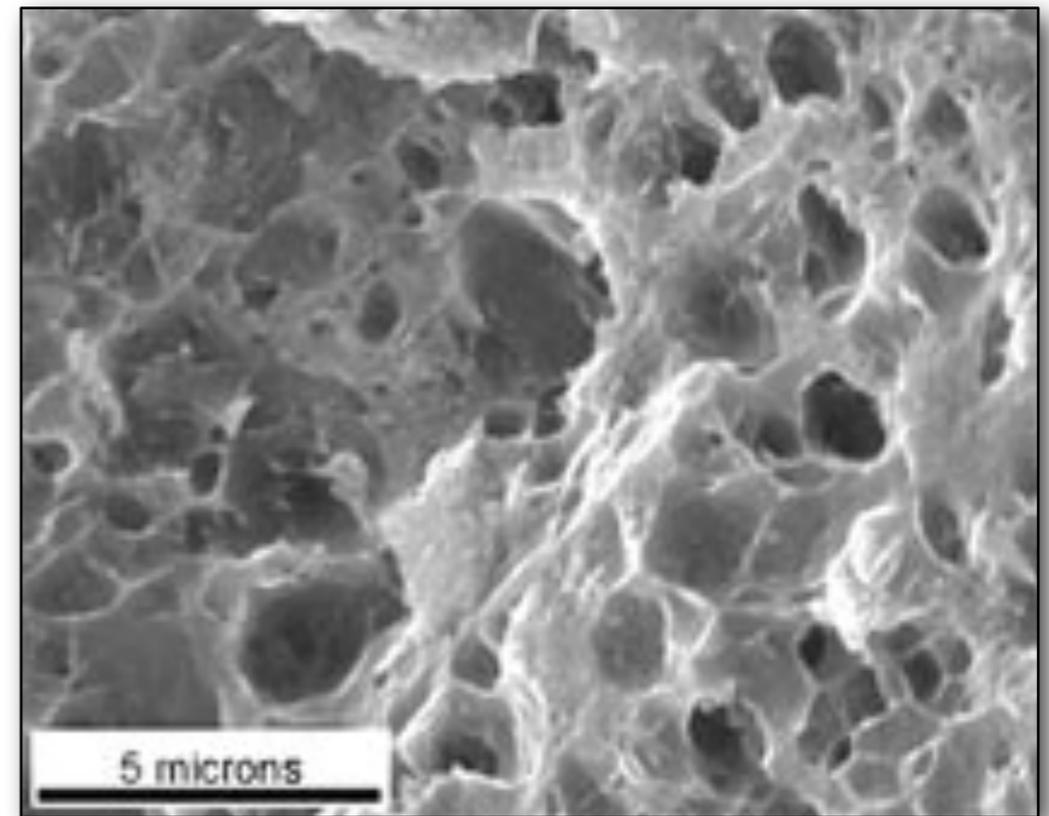


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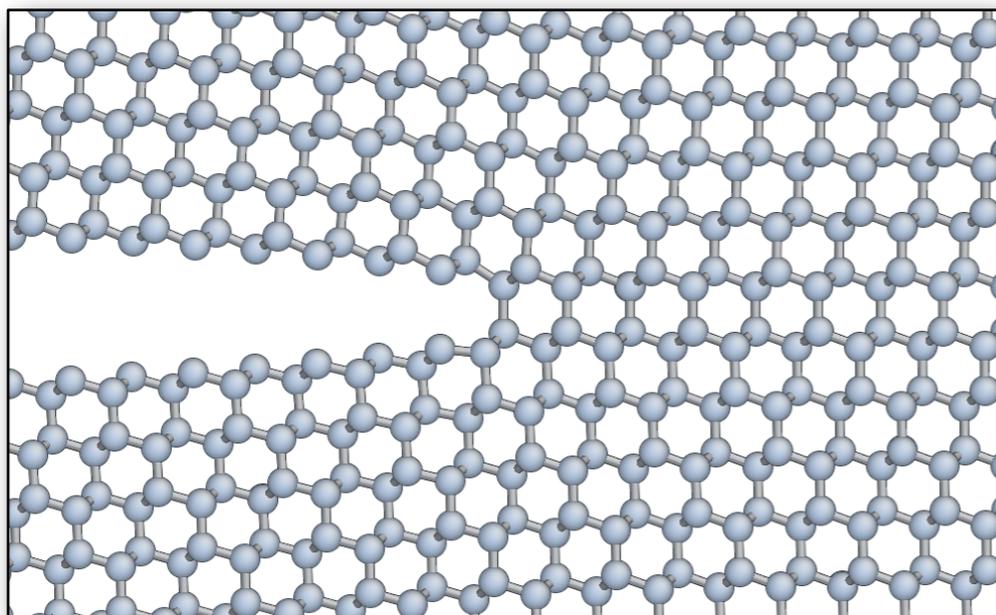
## Brittle Fracture



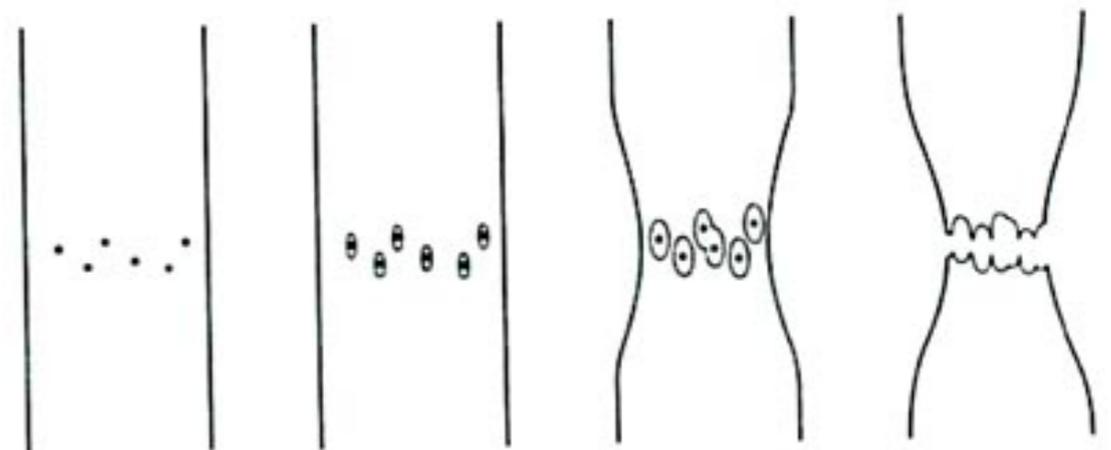
## Ductile Fracture



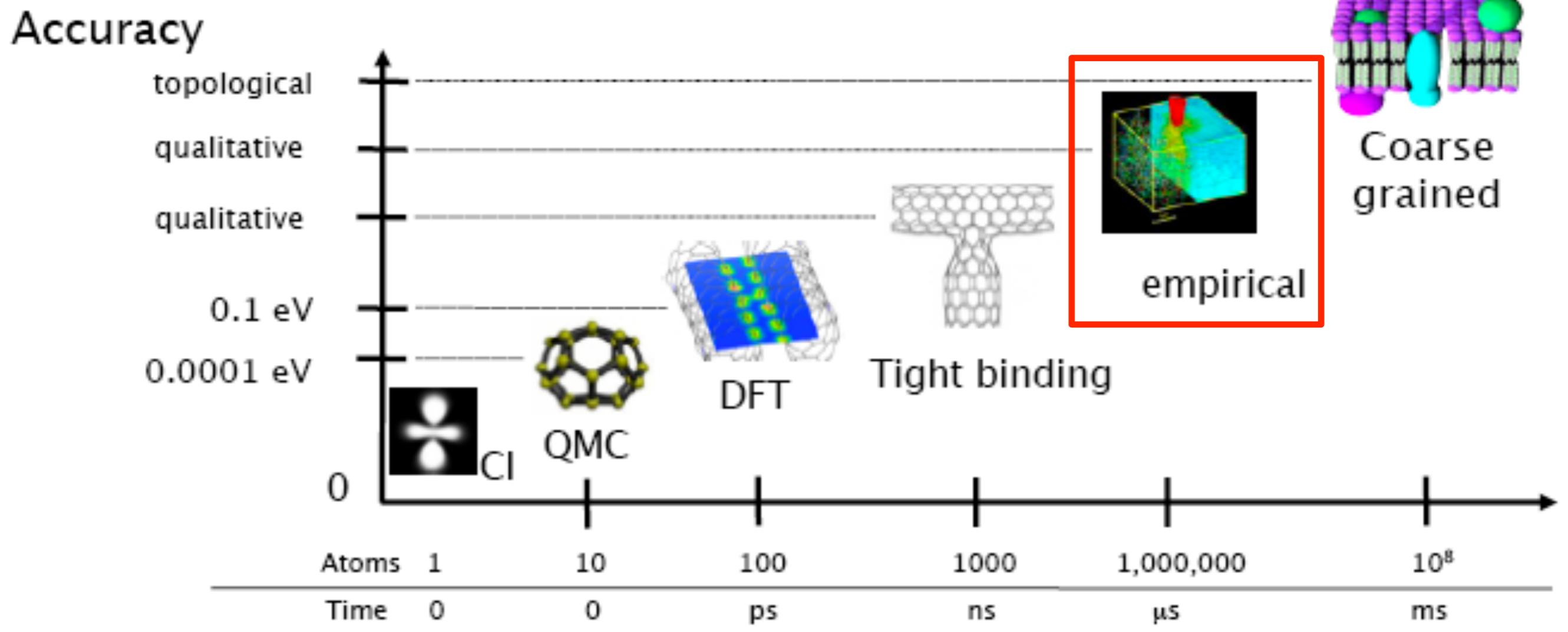
## Cleavage in brittle fracture



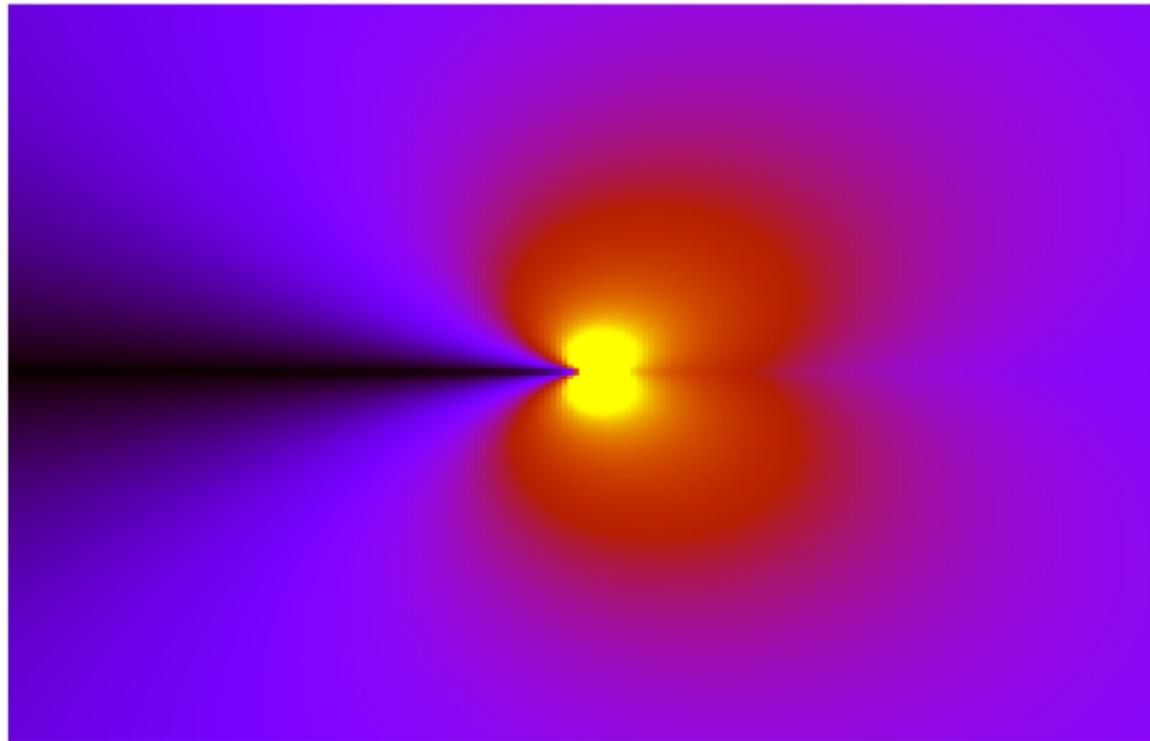
## Void nucleation, growth and coalescence in ductile fracture



# Multiscale Materials Modelling – empirical MD

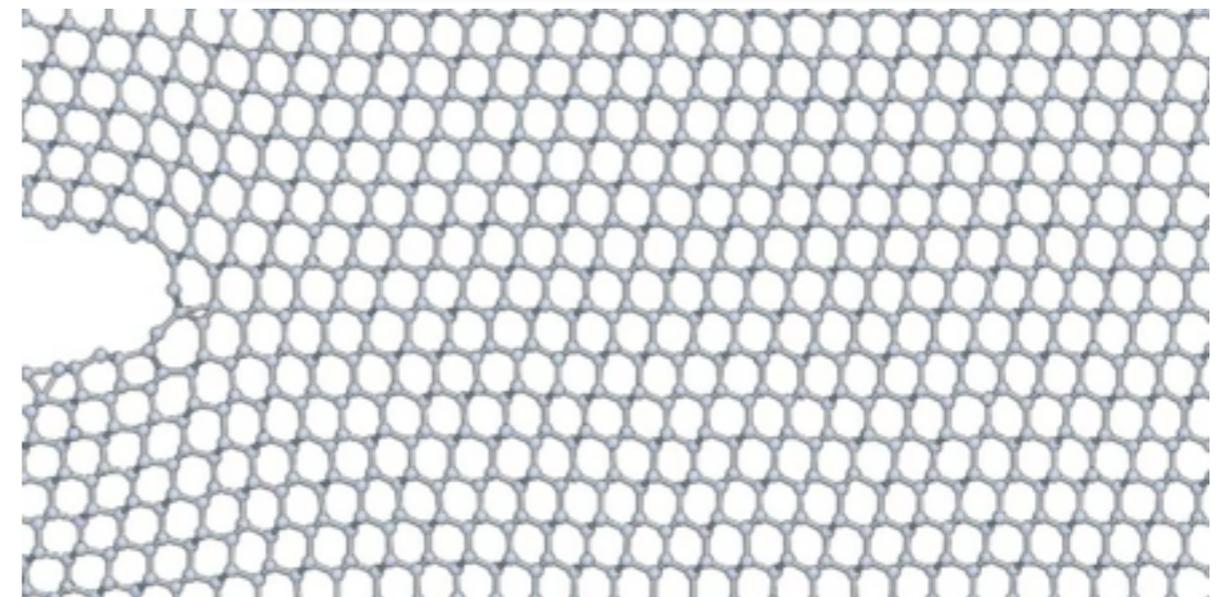
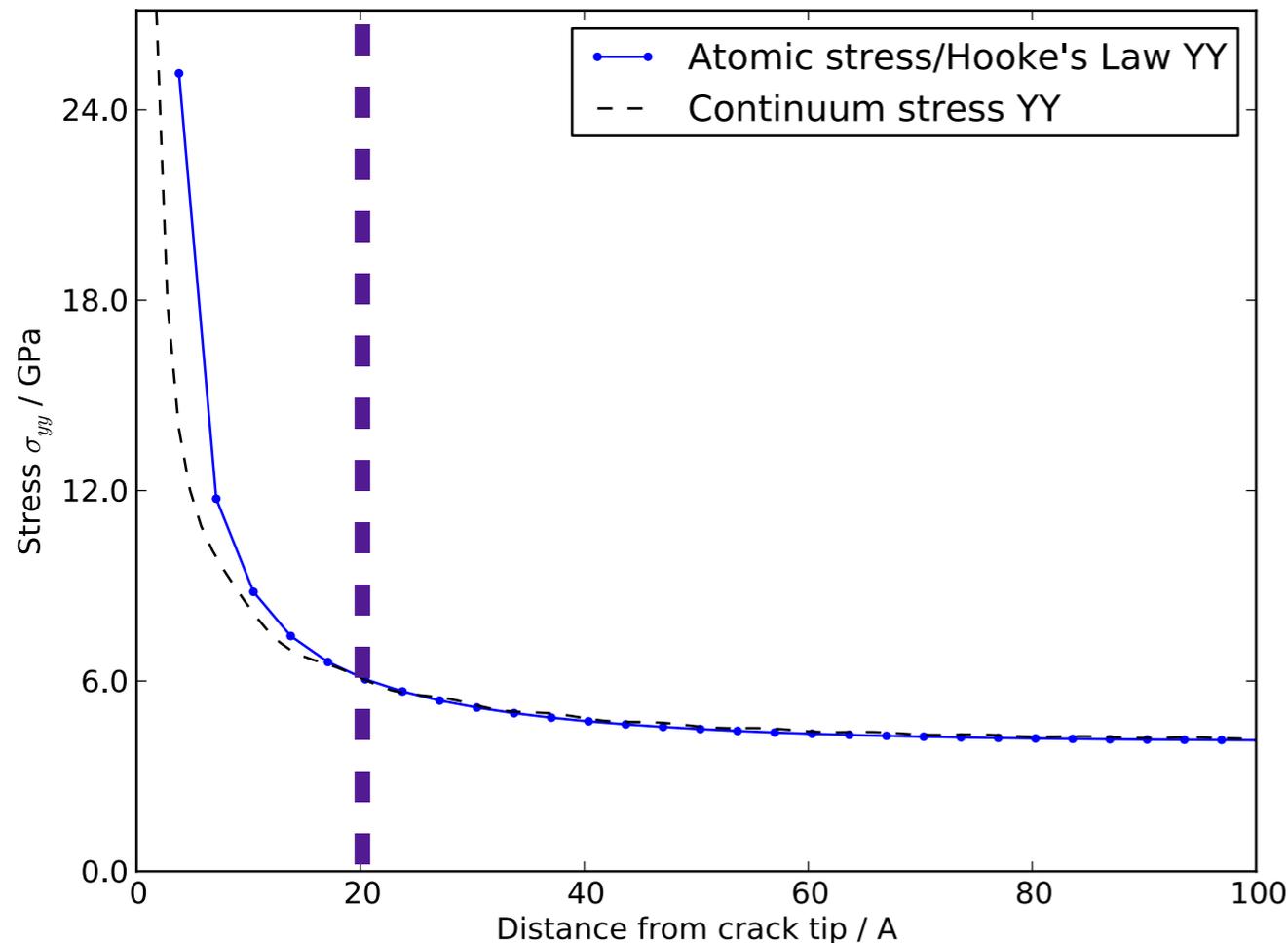
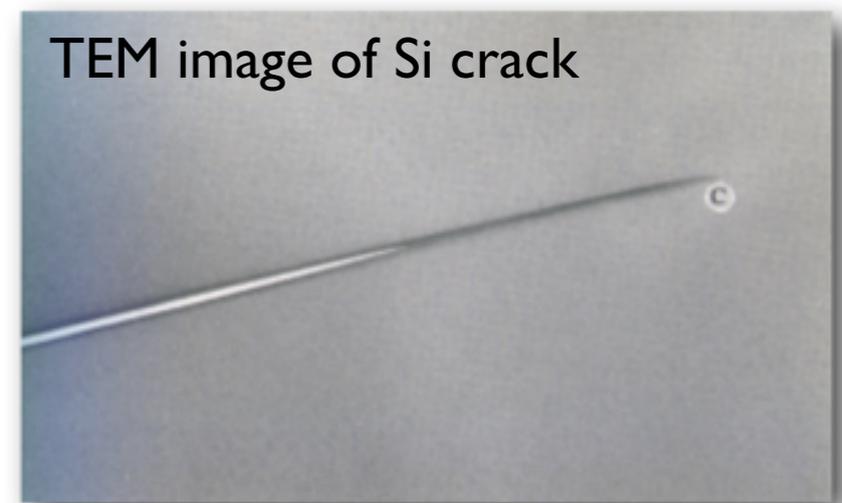


# Matching of MD and continuum scale fracture modelling



Irwin solution for  $\sigma_{yy}$  near a crack tip

Divergence of stress field near a crack tip  $\sigma \sim \frac{1}{\sqrt{r}}$



20  $\text{\AA}$  = 2 nm

Fracture of silicon with Stillinger-Weber potential

# Multiscale Materials Modelling – QM/MM coupling

Accuracy

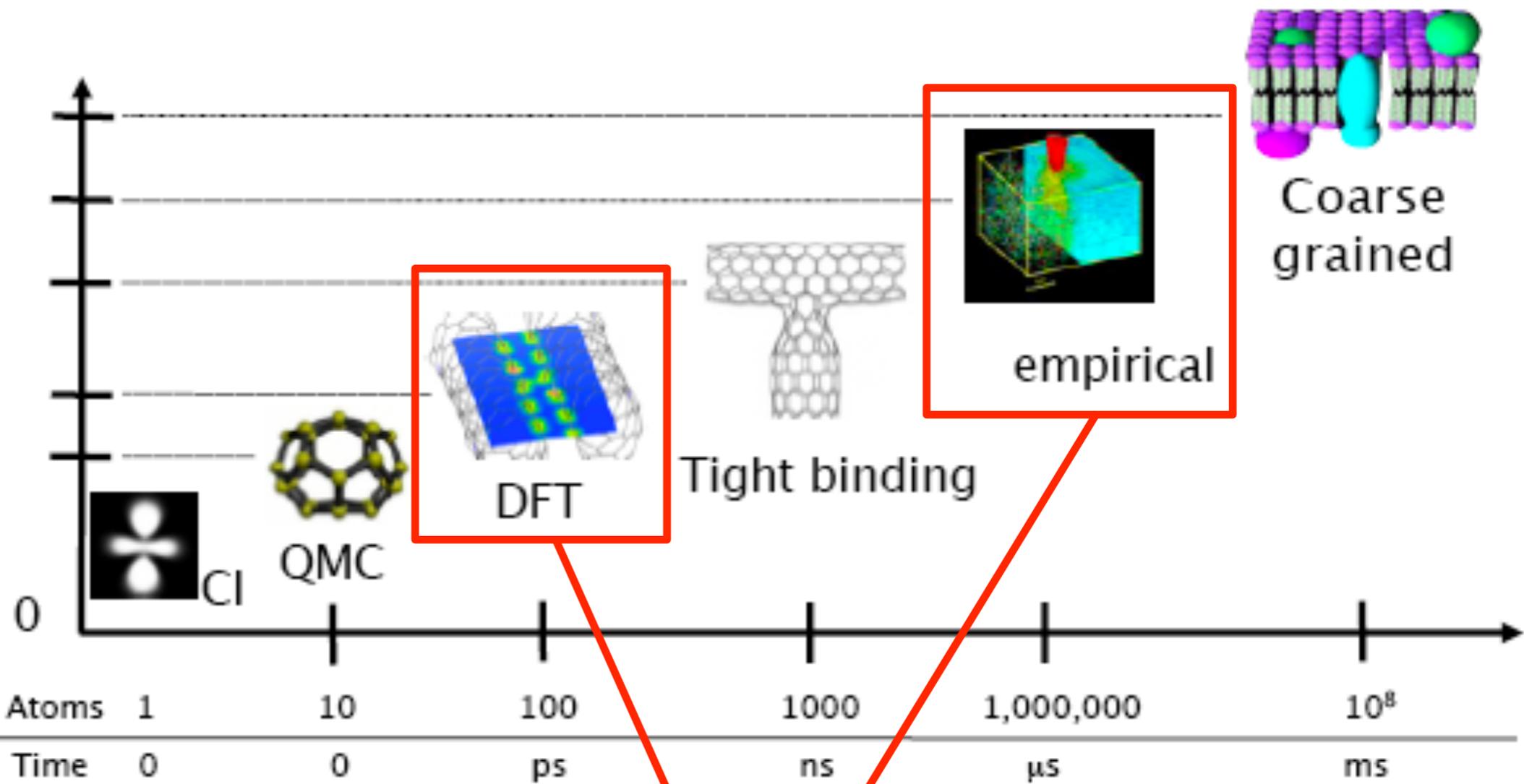
topological

qualitative

qualitative

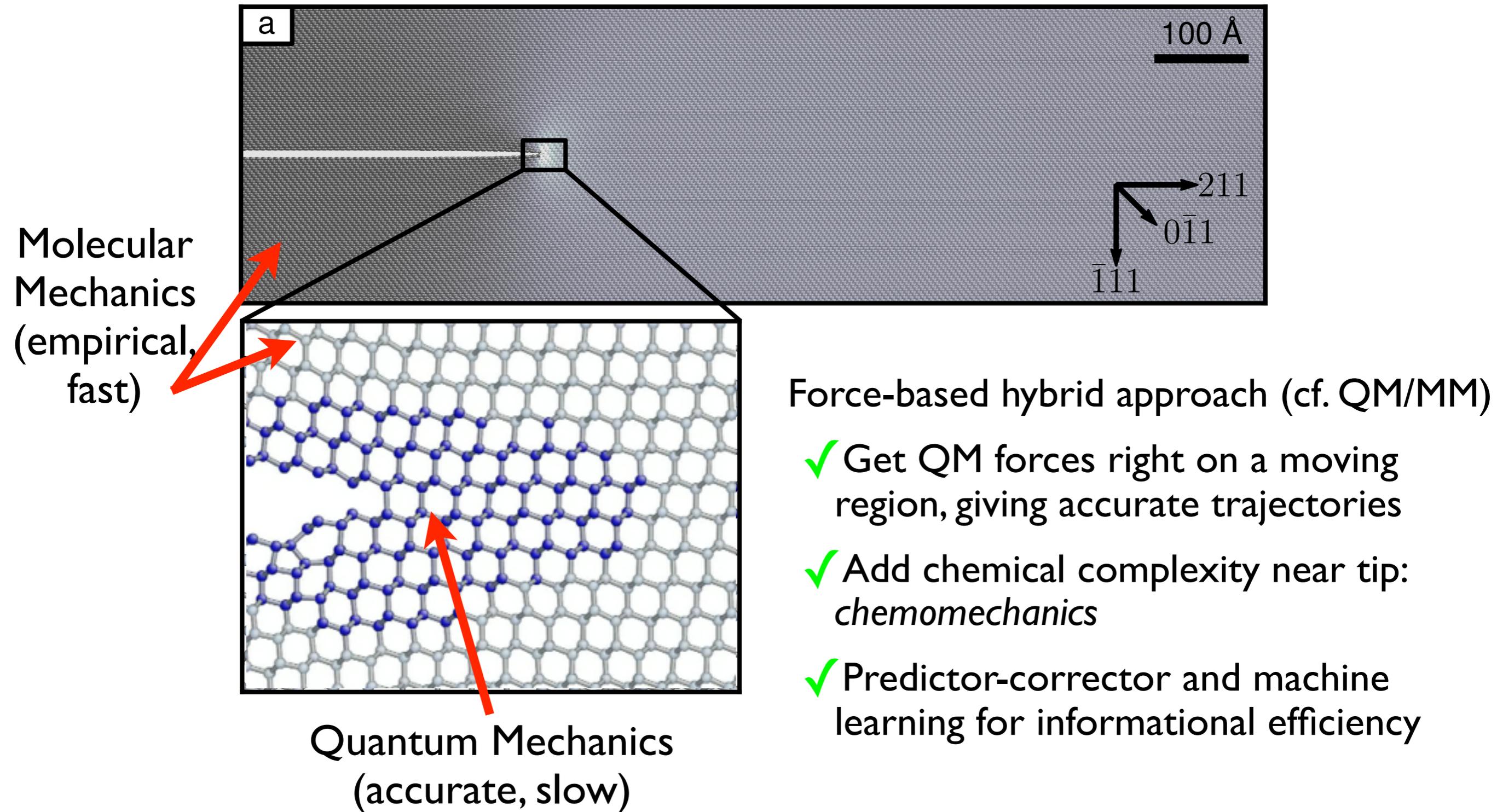
0.1 eV

0.0001 eV



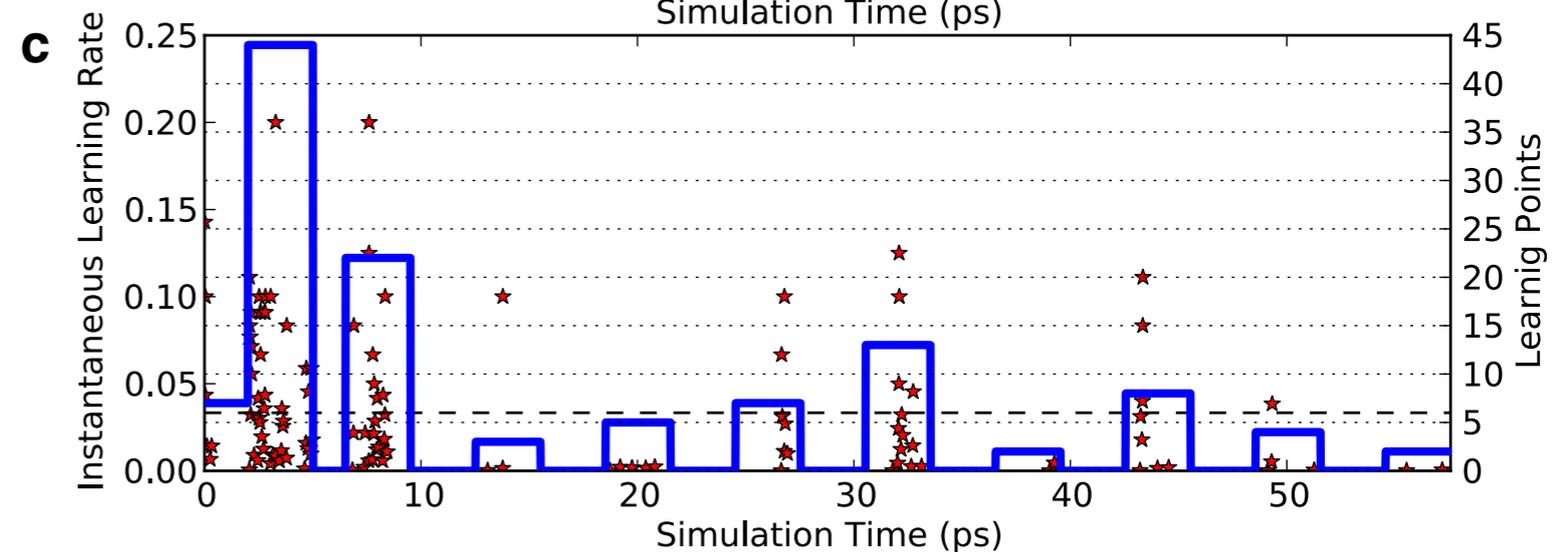
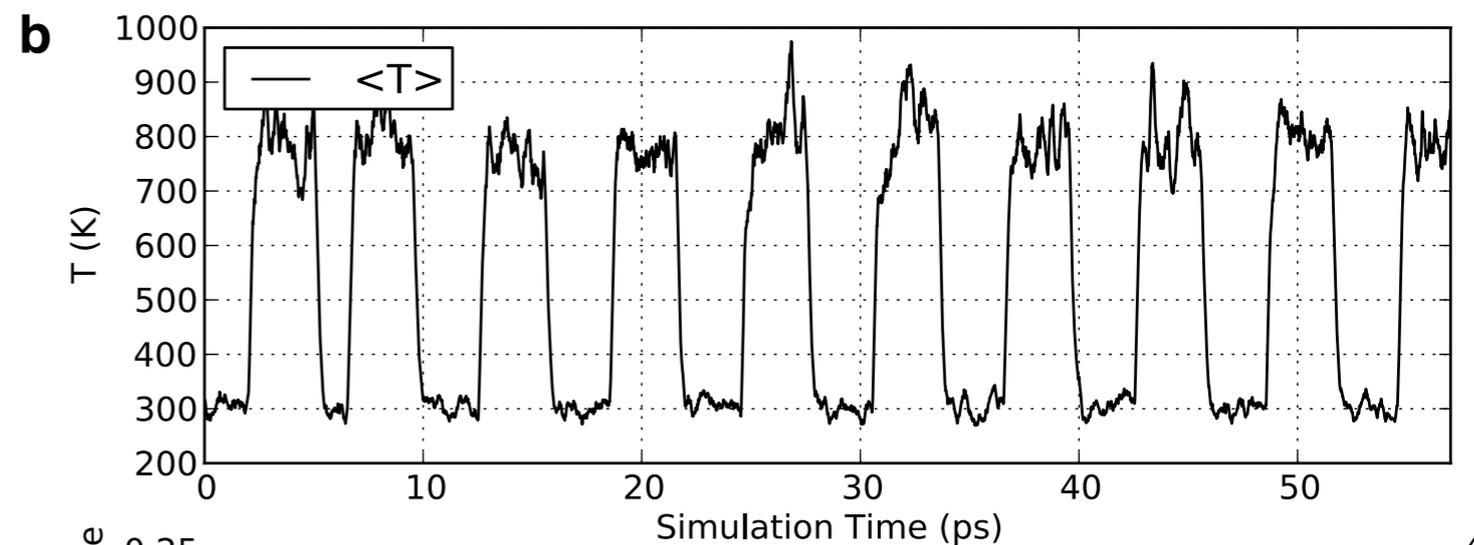
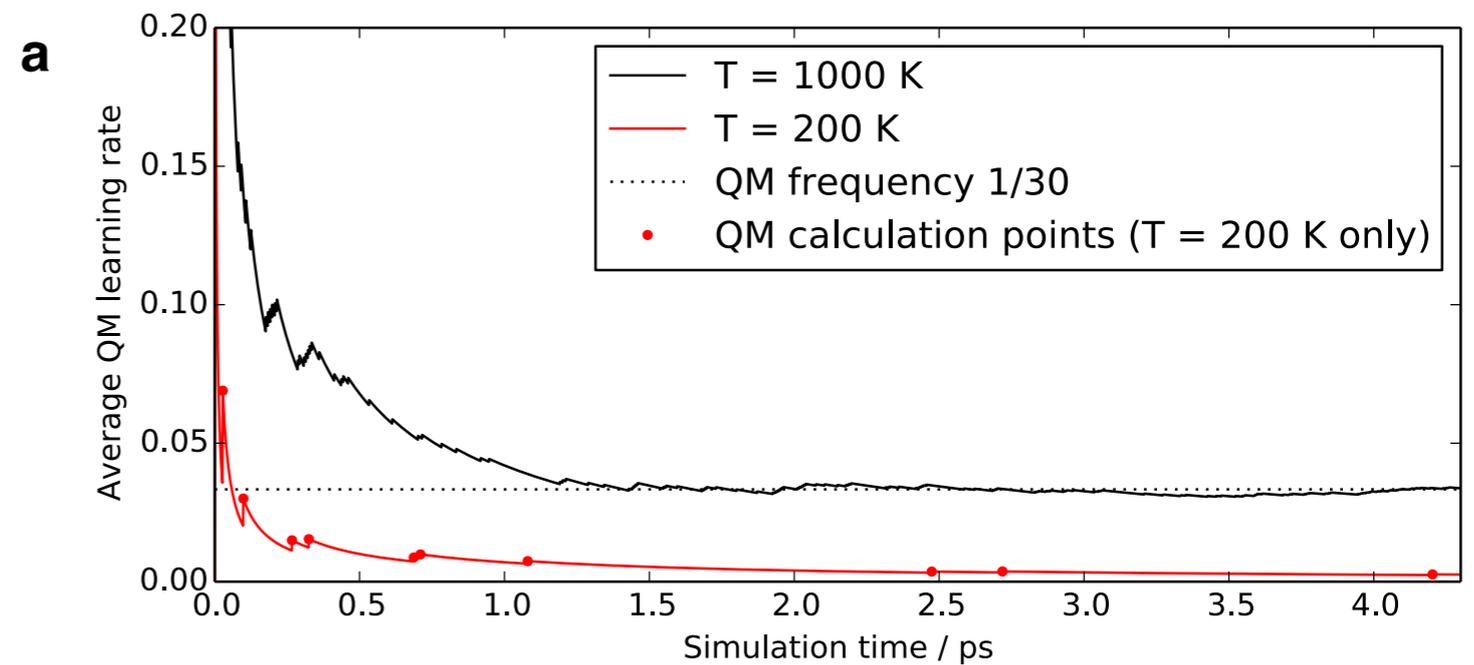
Simultaneous coupling

# Multiscale Materials Modelling – ‘Learn on the Fly’ scheme



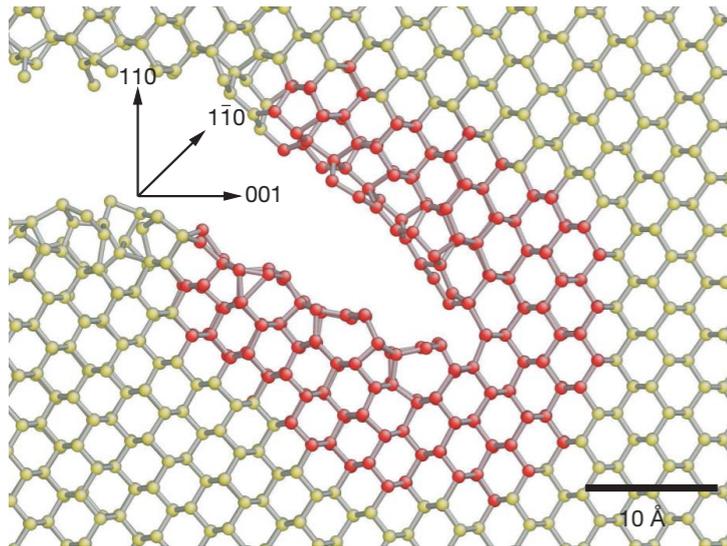
# Multiscale Materials Modelling – new machine learning scheme

- Forces on atoms are:
  - *Either* predicted by ML using Bayesian inference
  - *Or*, if necessary, computed on-the-fly and added to a growing ML database
- e.g. bulk Si at low and high temperatures:
  - High  $T$  – only need QM calc every 30 time steps
  - Low  $T$  – long periods where nothing new happens ( $> 1$  ps)
- Alternating between 300 K and 800 K – fewer QM calculations needed on 2nd and subsequent cycles



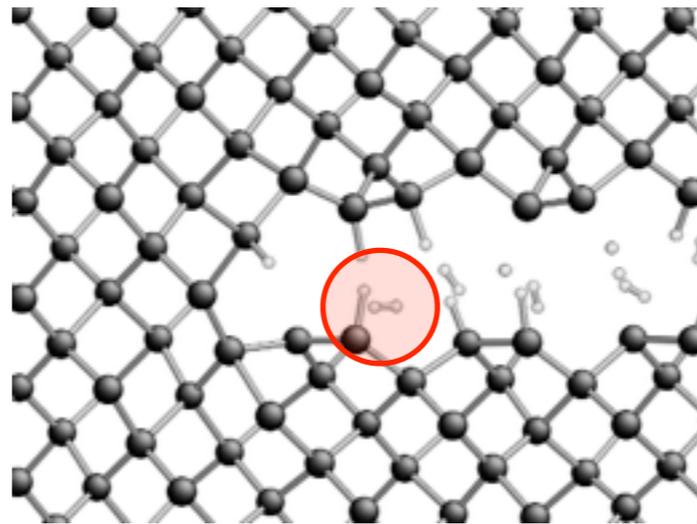
# Overview of Fracture Modelling Applications

## Dynamical instabilities in Si



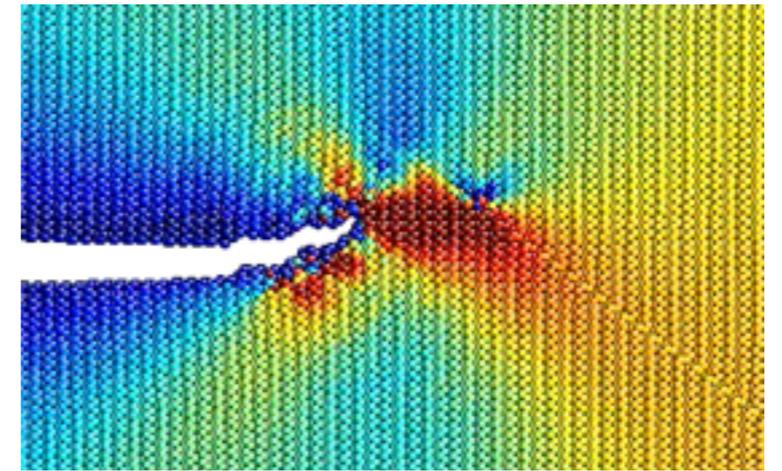
JR Kermode *et al.*  
Nature **455** 1224 (2008)

## H induced 'SmartCut'



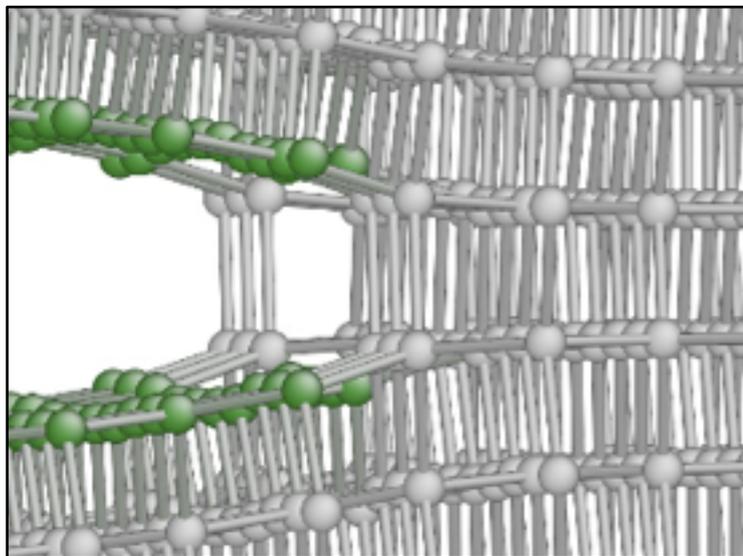
G Moras *et al.* Phys. Rev. Lett.  
**105**, 075502 (2010)

## Crack-dislocation interactions



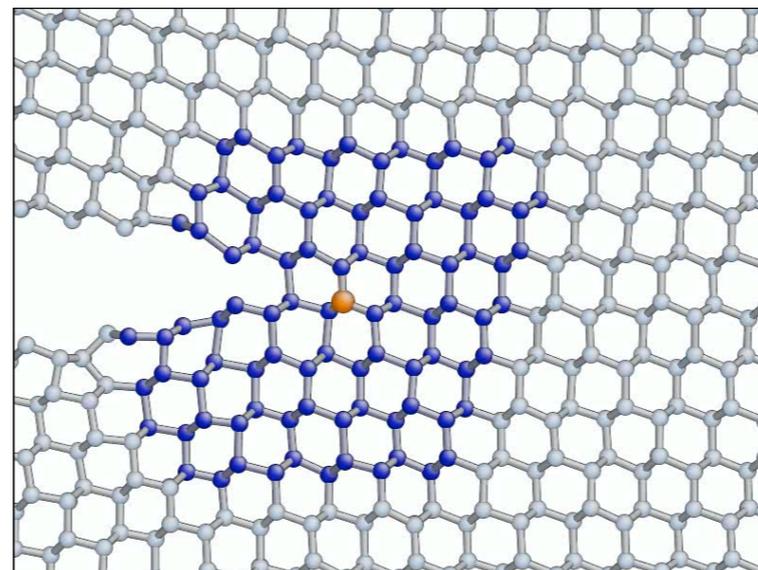
C Gattinoni, JR Kermode and  
A De Vita, *In prep* (2014)

## Three dimensional effects



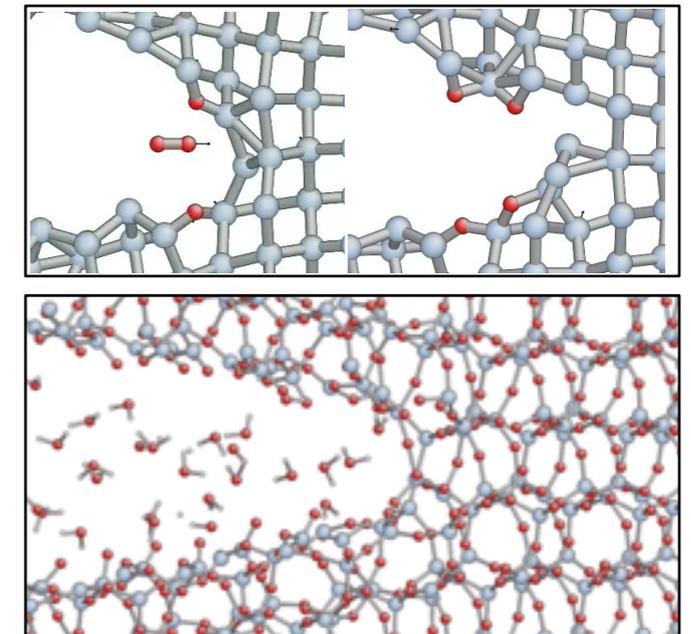
JR Kermode, A. Glazier, G Csányi,  
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## Crack-impurity scattering



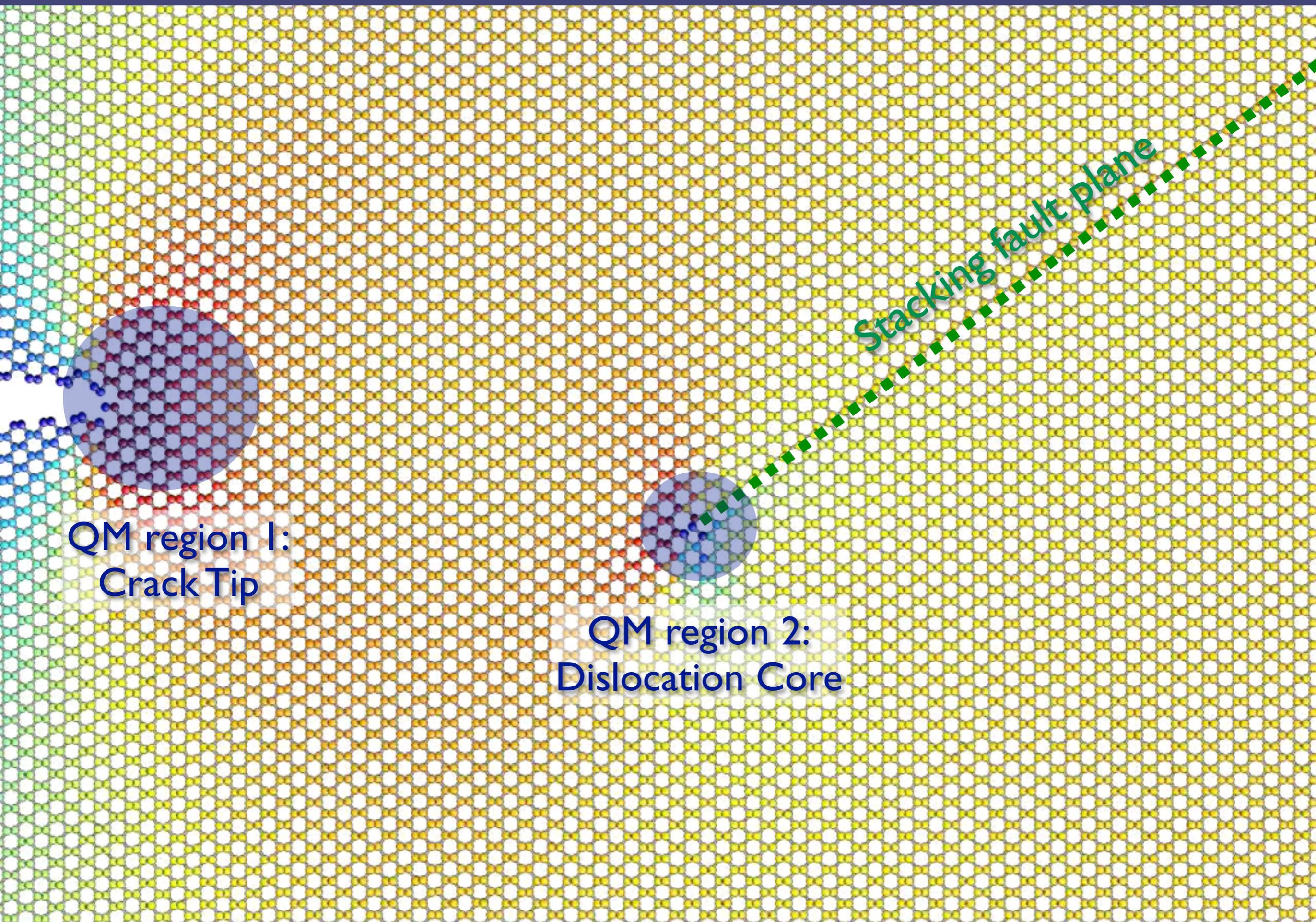
JR Kermode, L Ben-Bashat, F Atrash,  
JJ Cilliers, D Sherman and A. De Vita.,  
Nat. Commun. **4** 2441 (2013)

## Stress corrosion cracking



A Glazier, G Peralta, JR Kermode,  
A De Vita and D Sherman, Phys. Rev. Lett.,  
**112** 115501 (2014).

# Crack/dislocation interactions – LOTF simulation



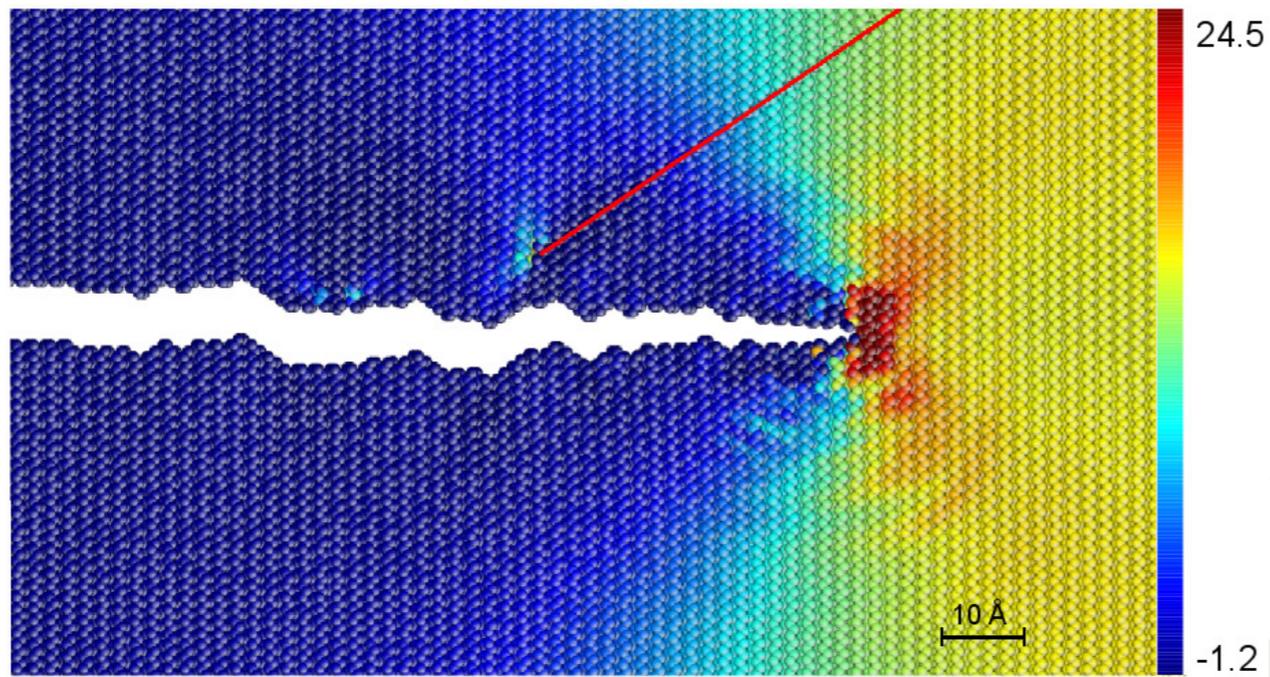
QM region 1:  
Crack Tip

QM region 2:  
Dislocation Core

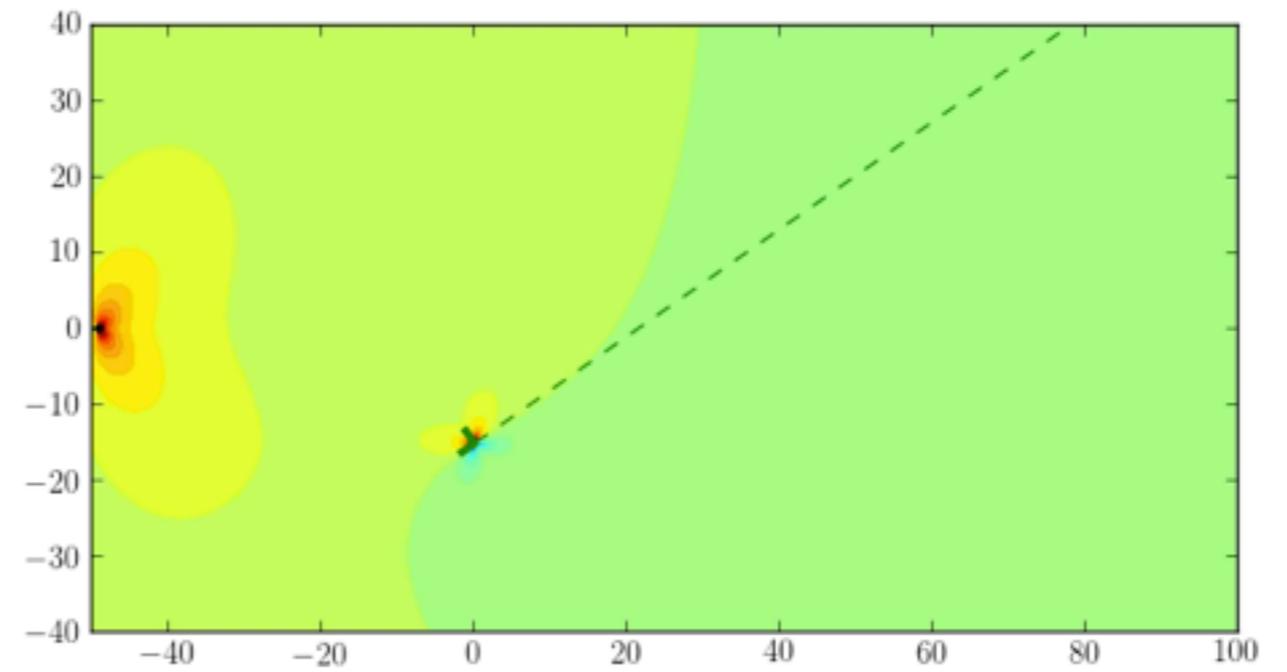
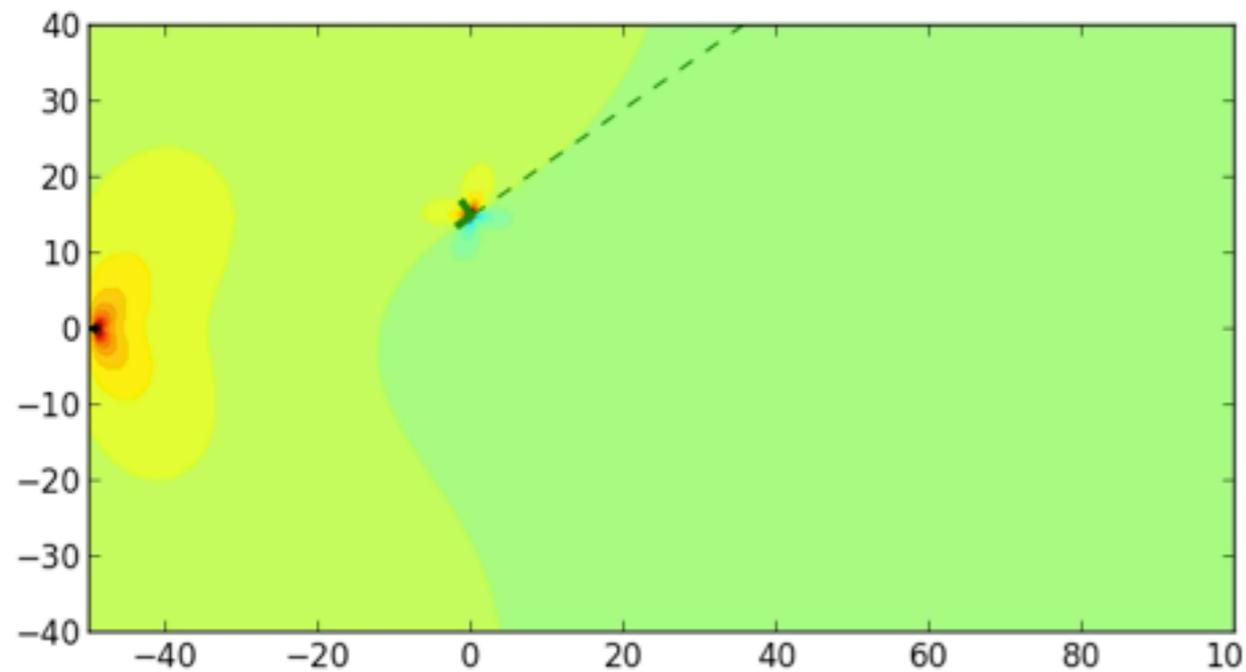
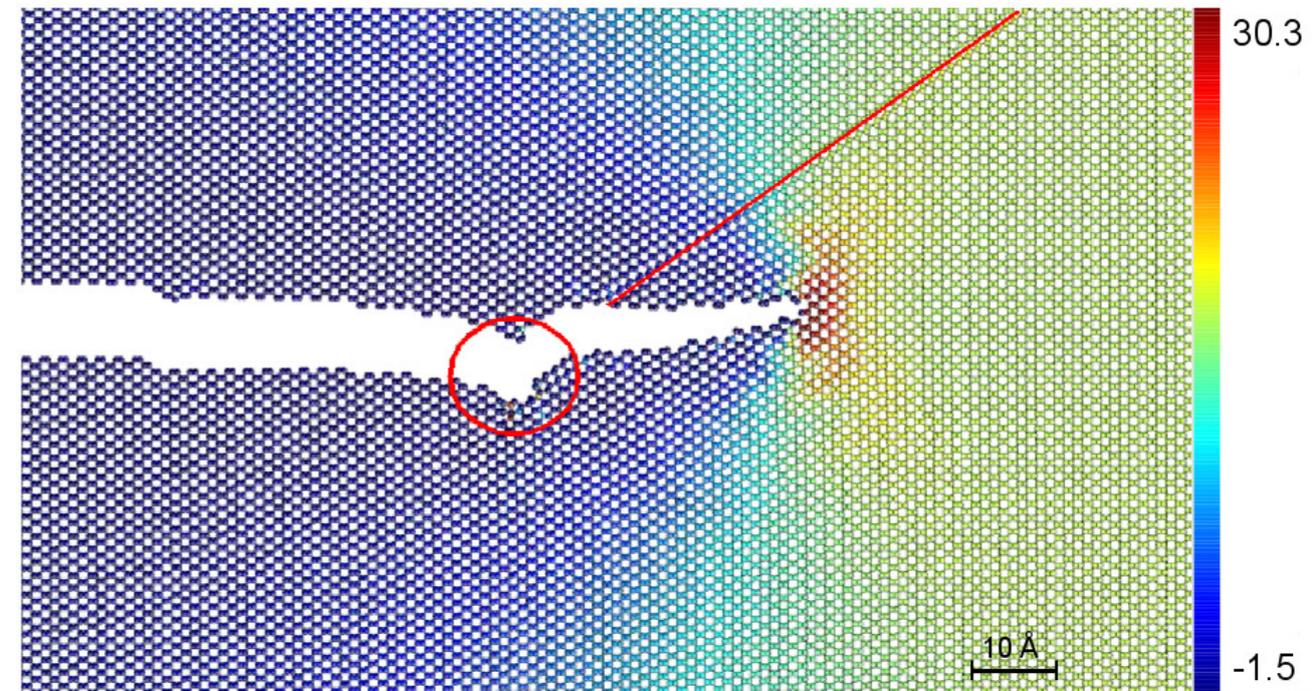
Stacking fault plane

# Crack/dislocation interactions – coarse-graining and upscaling

## Dislocation core above crack

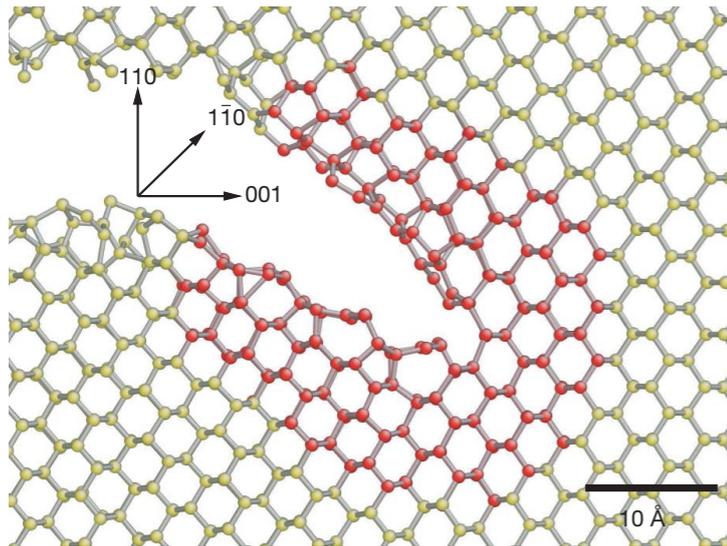


## Dislocation core below crack



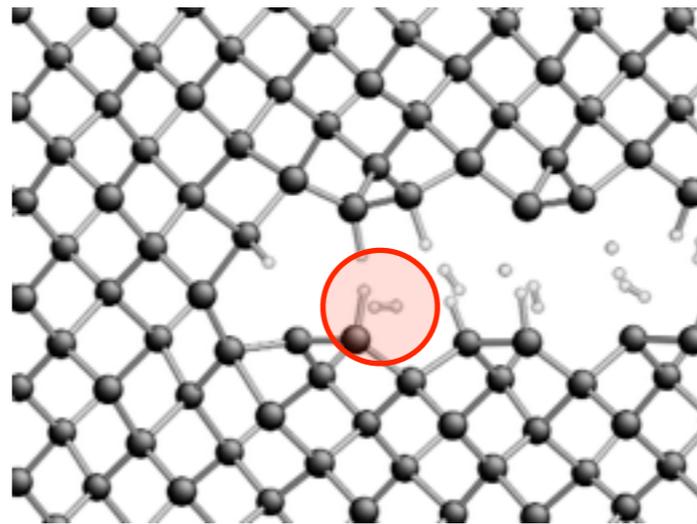
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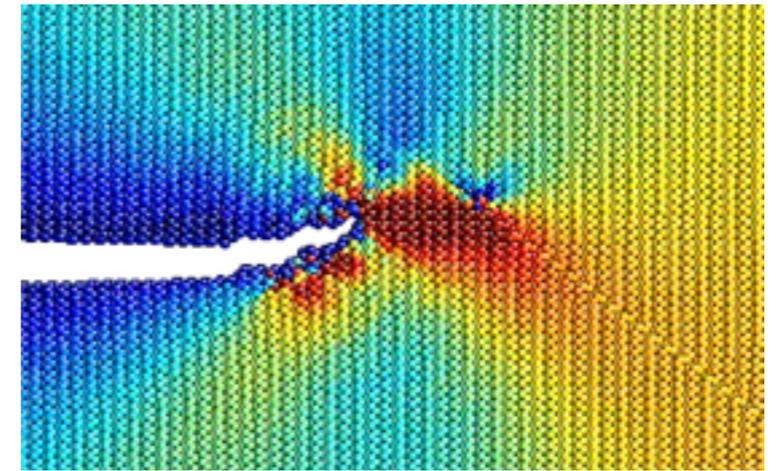
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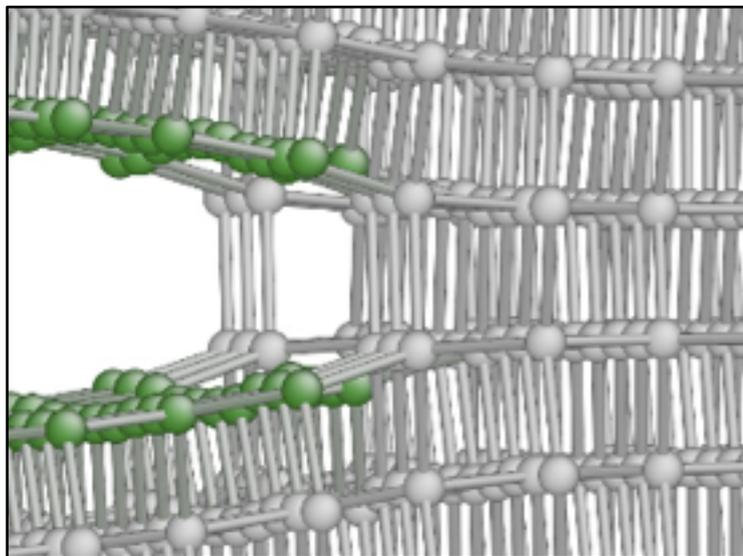
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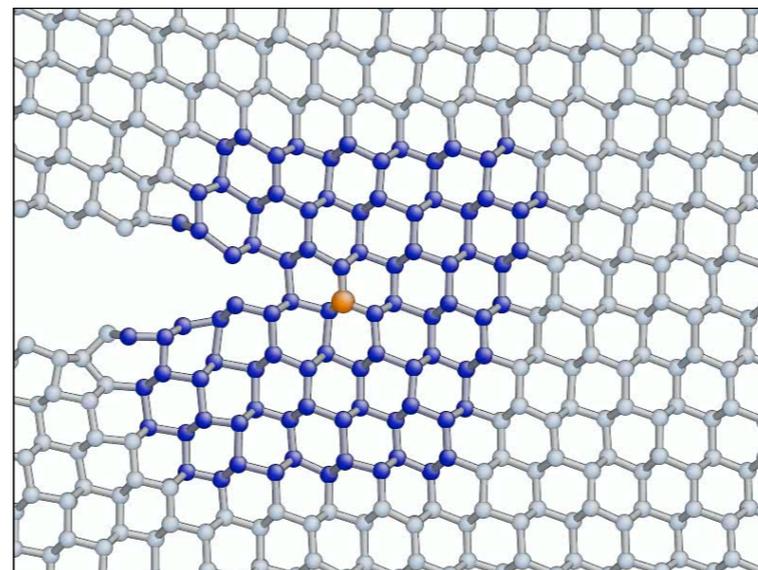
C Gattinoni, JR Kermode and  
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## Three dimensional effects



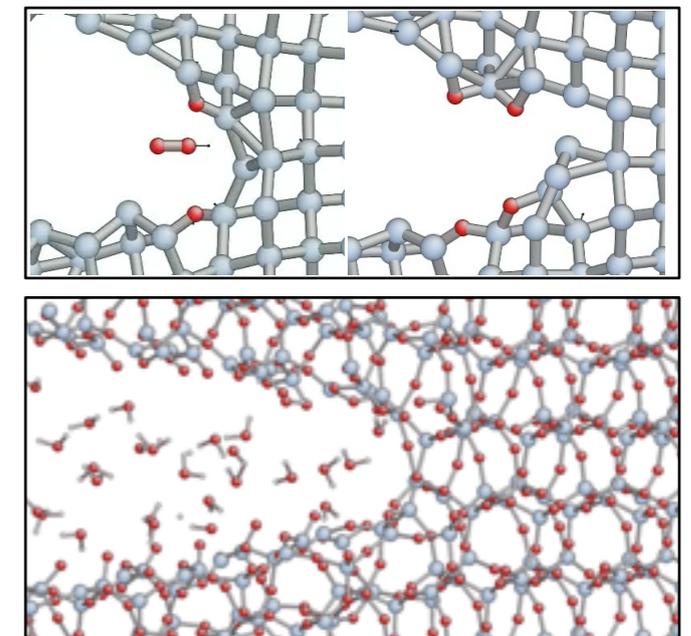
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## Crack-impurity scattering



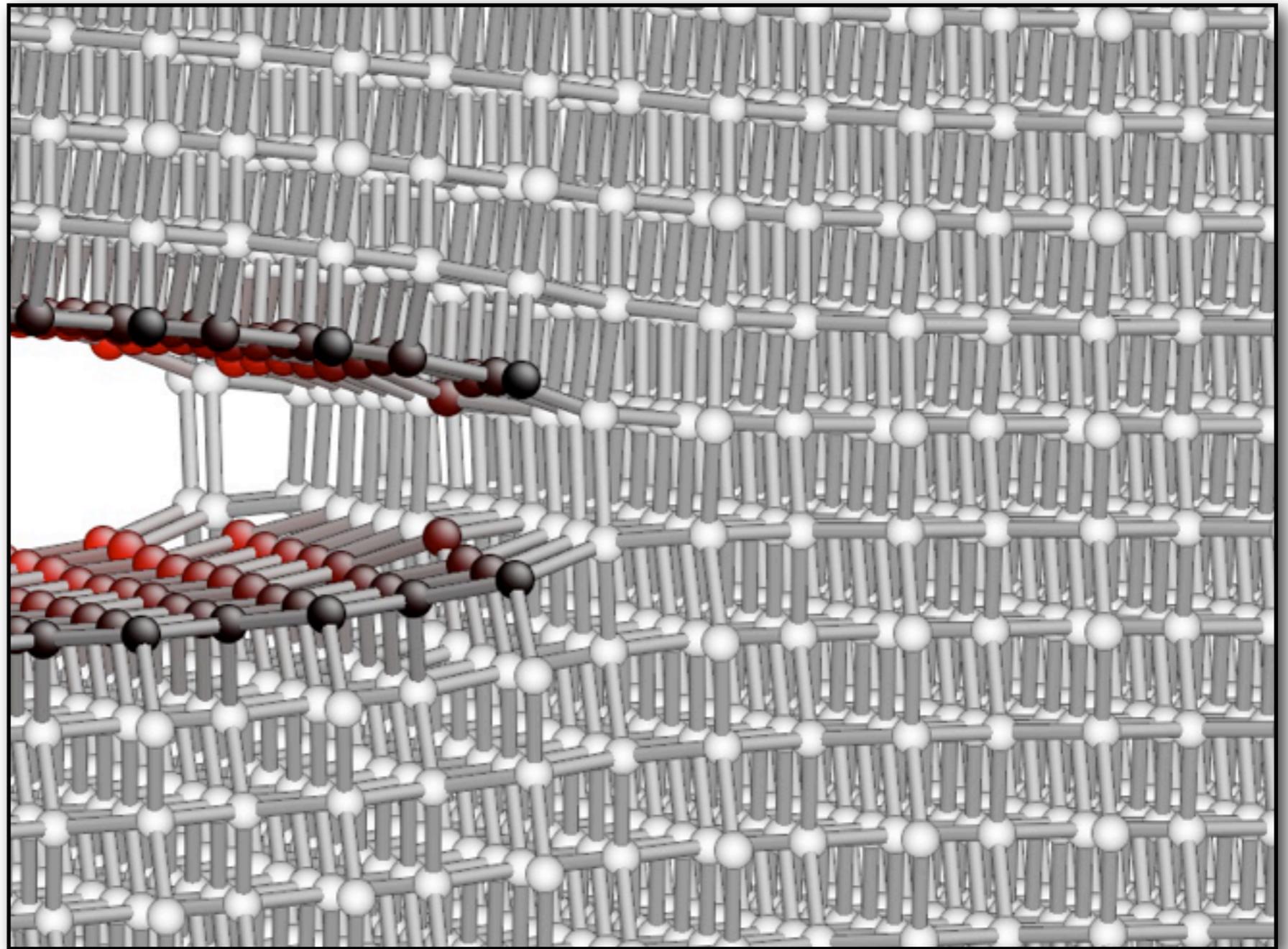
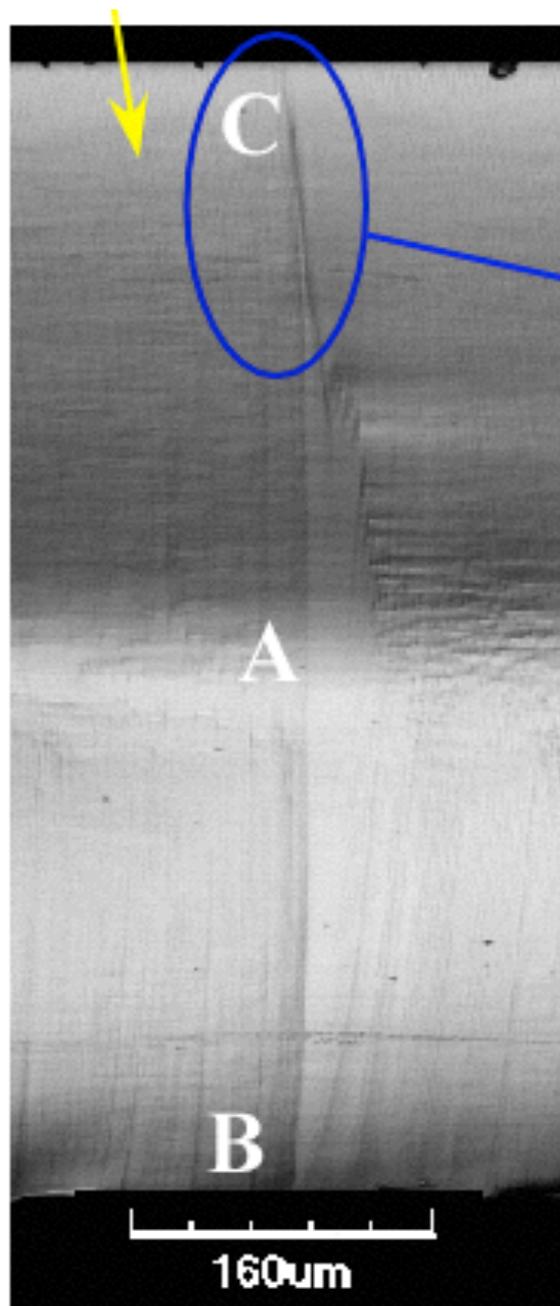
JR Kermode, L Ben-Bashat, F Atrash,  
JJ Cilliers, D Sherman and A. De Vita.,  
Nat. Commun. **4** 2441 (2013)

## Stress corrosion cracking



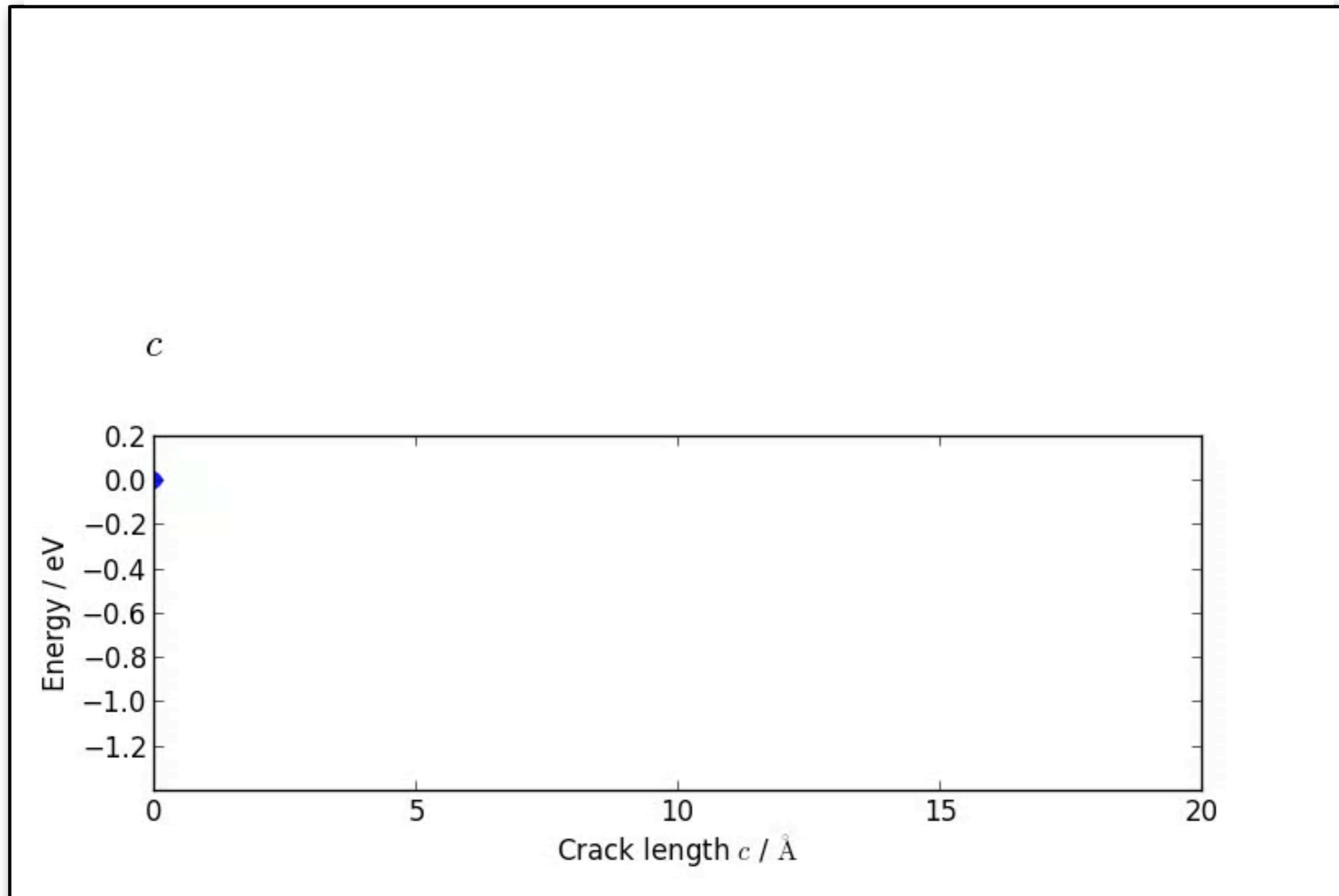
A Glazier, G Peralta, JR Kermode,  
A De Vita and D Sherman, Phys. Rev. Lett.,  
**112** 115501 (2014).

# Crack speed measurements in 3D simulations



Experiments: Anna Glazier and Dov Sherman, Technion, Israel

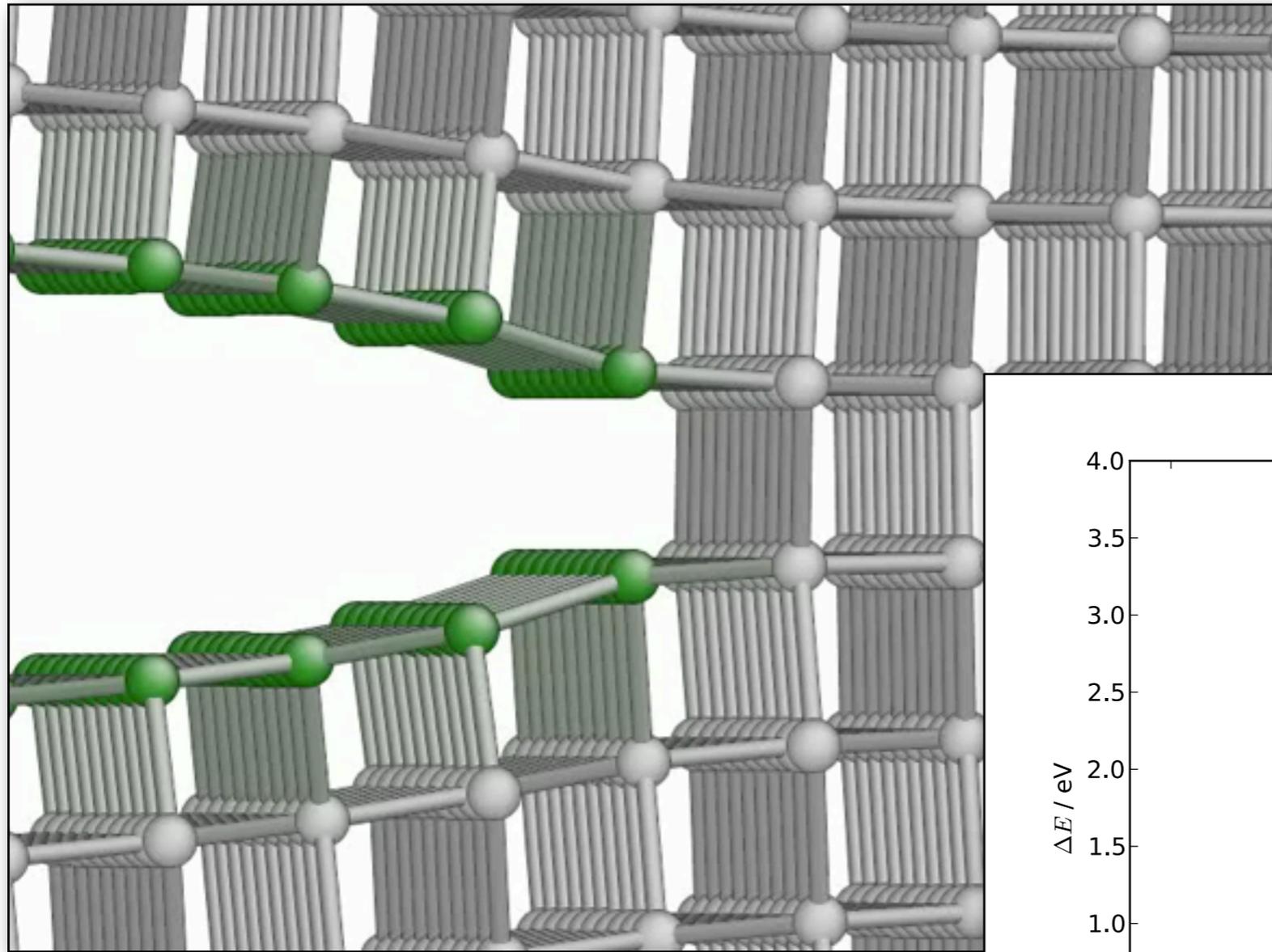
# Energetics of Fracture – atomistic picture



$$E_{qs} = (-G + 2\gamma)c - \frac{\gamma_t a_x}{\pi} \sin \frac{2\pi c}{a_x}$$

Sinclair, J. E., & Lawn, B. R. Proc. R. Soc. Lond. **329** 83 (1972).

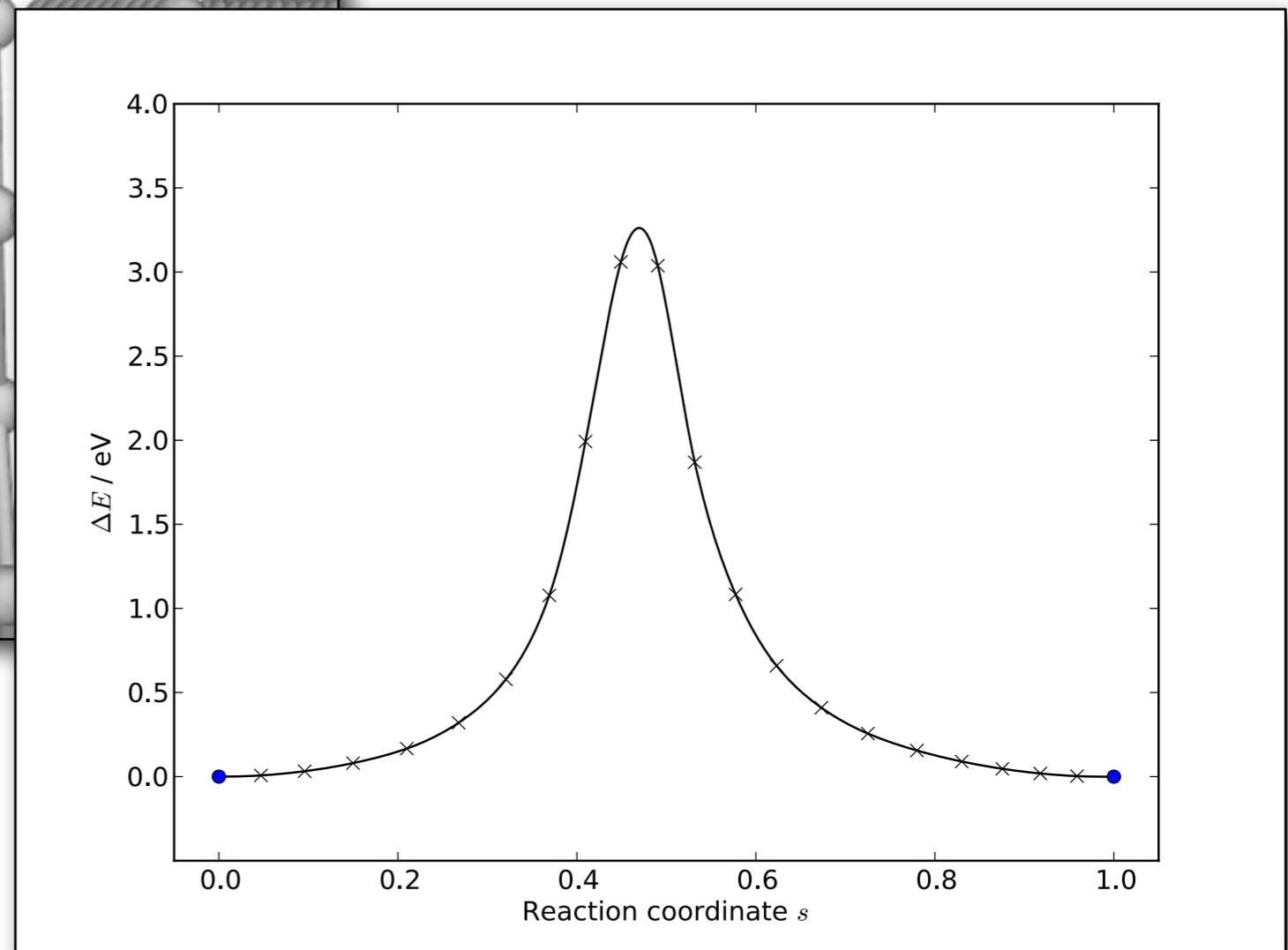
# 3D fracture – simultaneous bond rupture



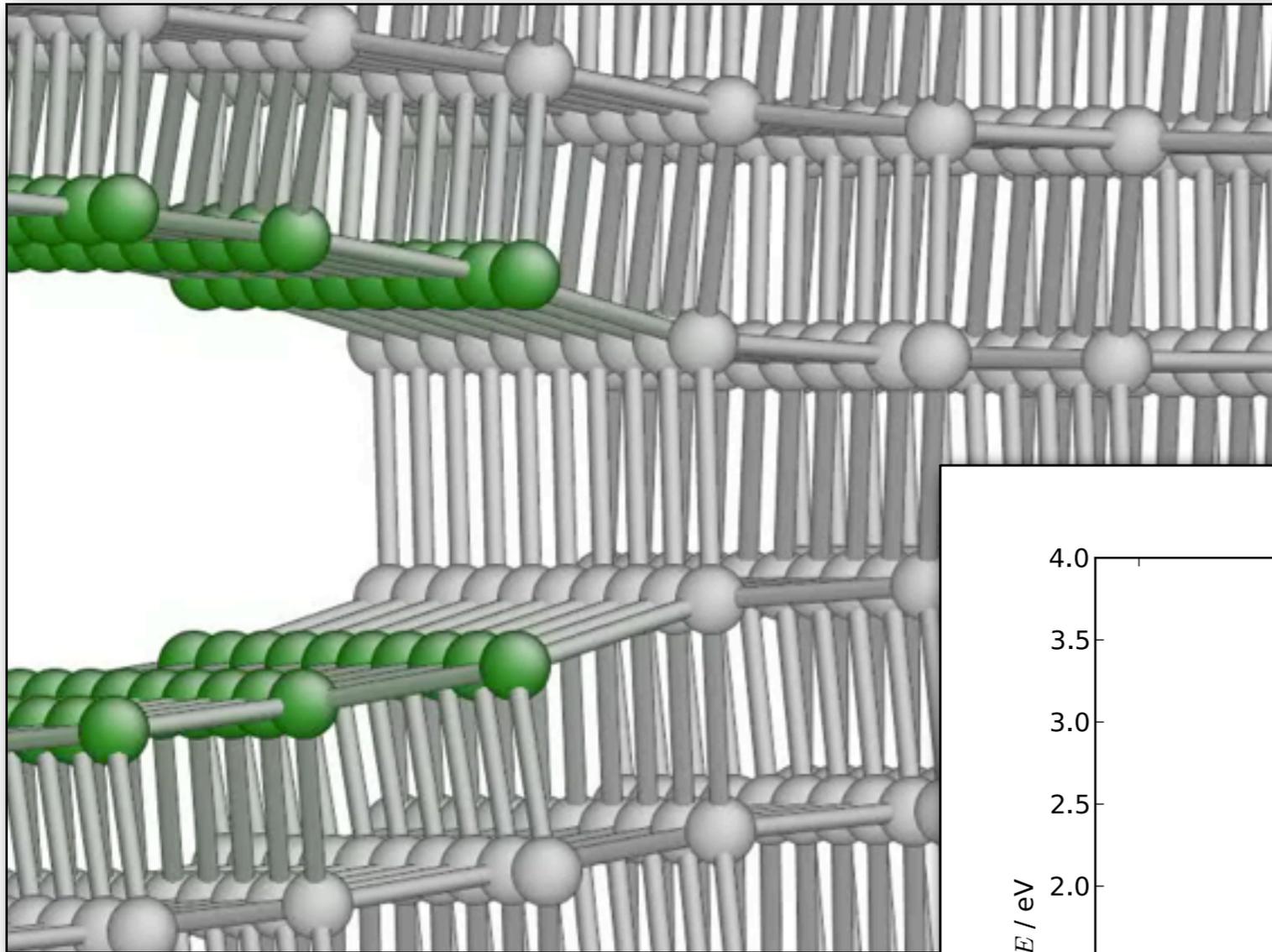
10 layers and  $\sim 100,000$  atoms  
Periodic along  $z$

Griffith critical load

Classical NEB calculation



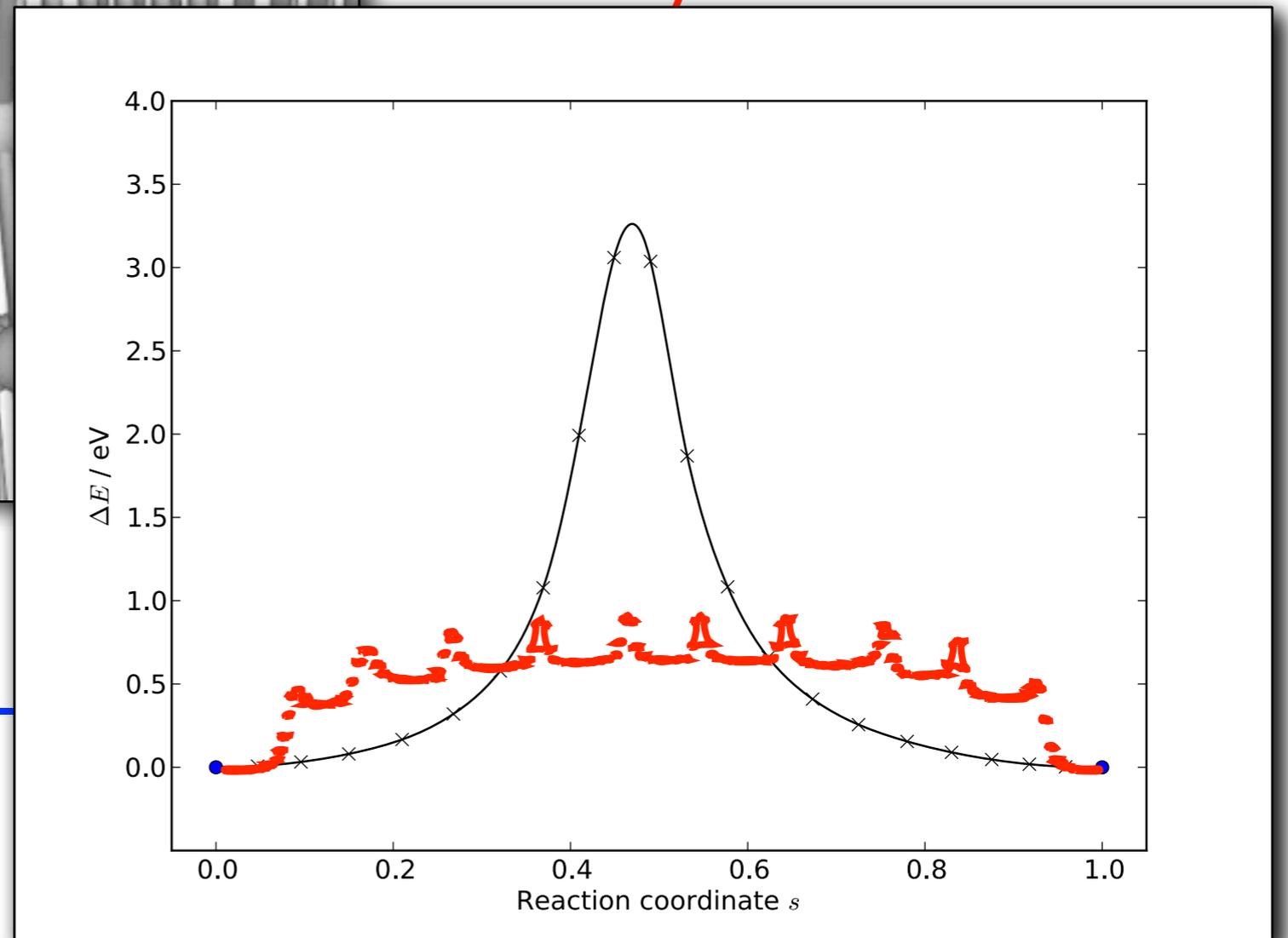
# 3D fracture – sequential bond rupture



10 layers and  $\sim 100,000$  atoms  
Periodic along  $z$

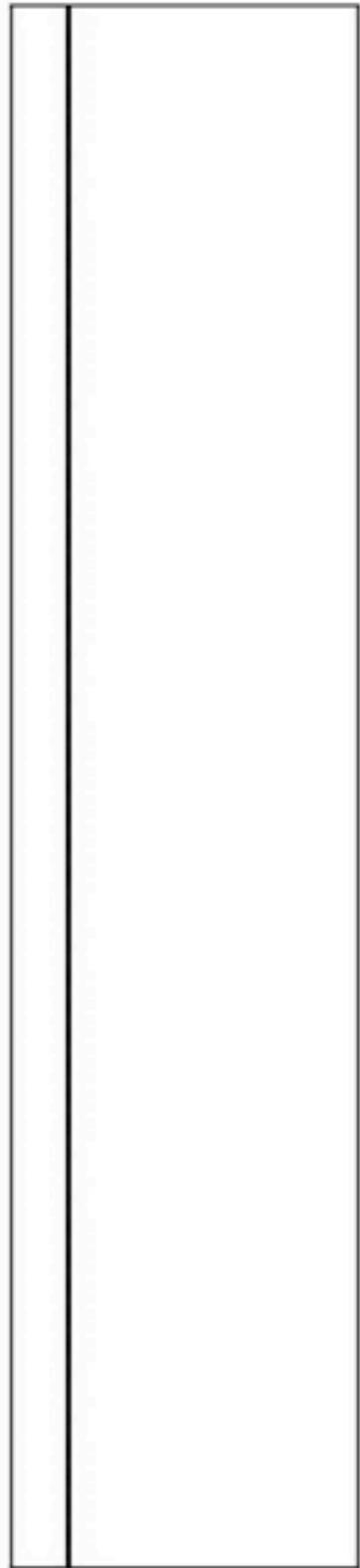
Kink advance barrier  
Griffith critical load

Classical NEB calculation  
Kink pair  
formation barrier

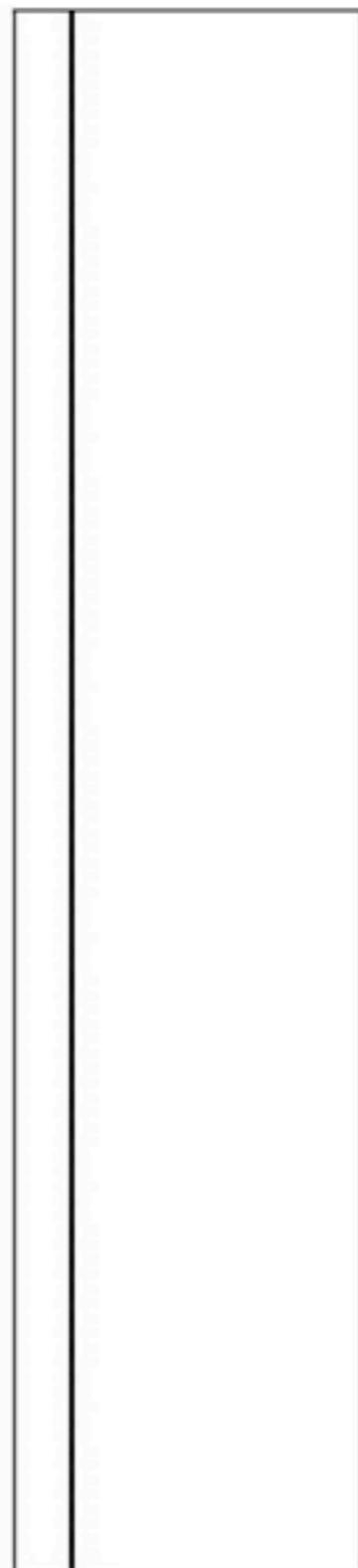


# Crack speed measurements in 3D simulations

Mesoscale kinetic Monte Carlo of kink motion

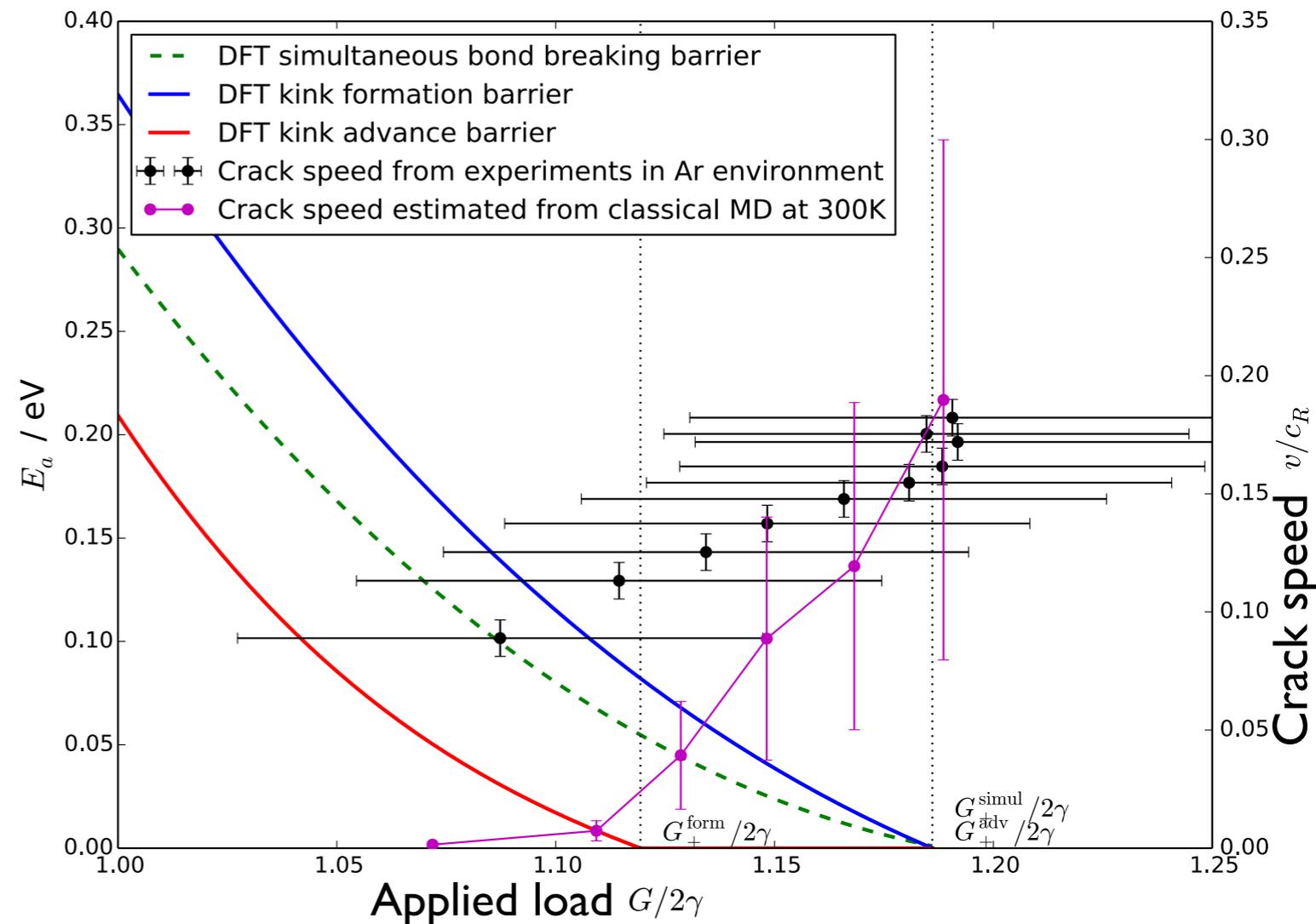


*Low load, slow*



*High load, fast*

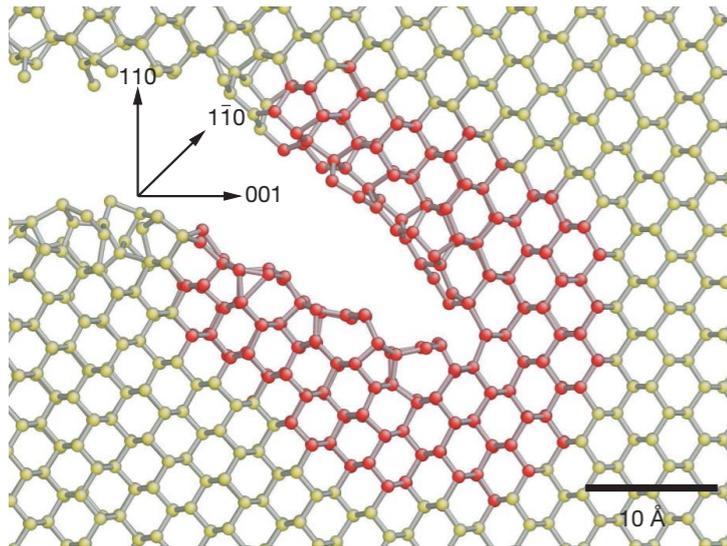
## Crack energy-speed relationship



Experiments: Anna Glazier and Dov Sherman

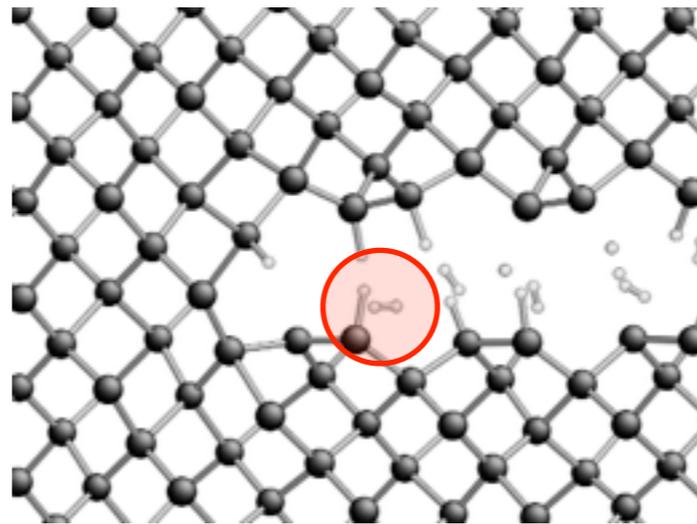
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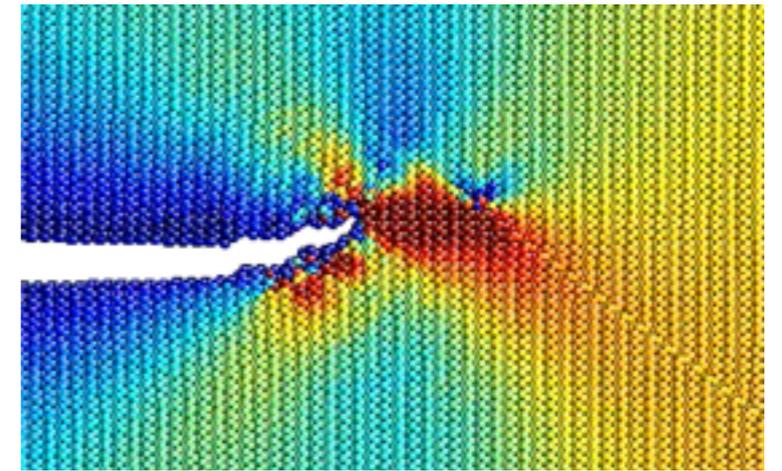
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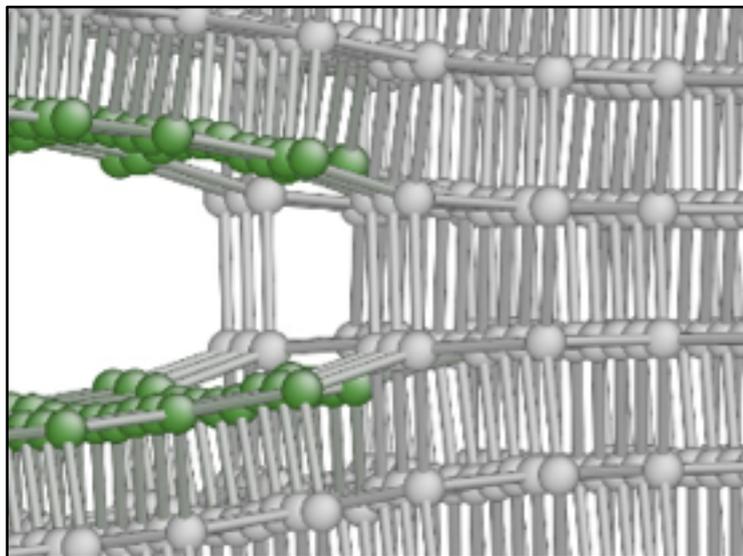
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## Crack-dislocation interactions



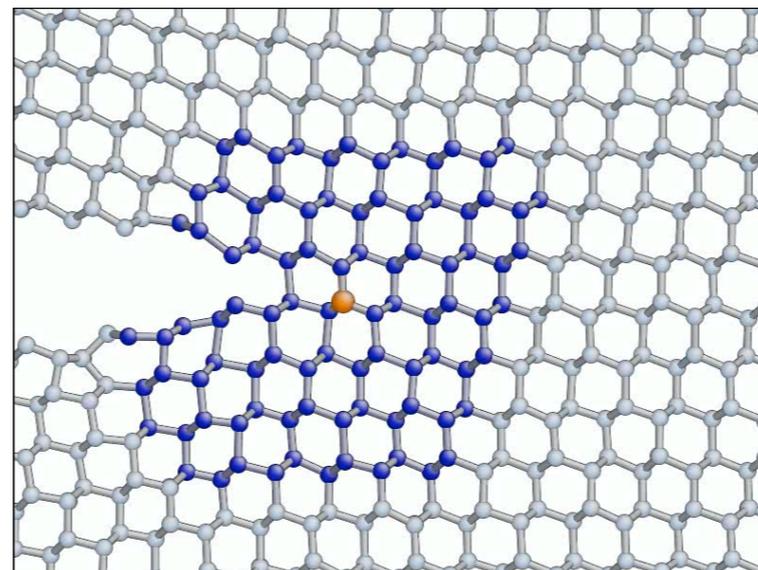
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## Three dimensional effects



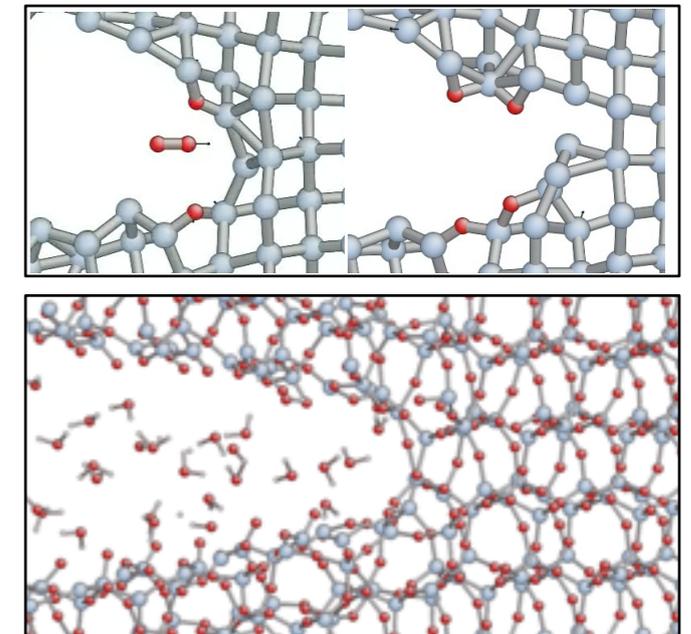
JR Kermode, A. Glazier, G Csányi,  
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## Crack-impurity scattering



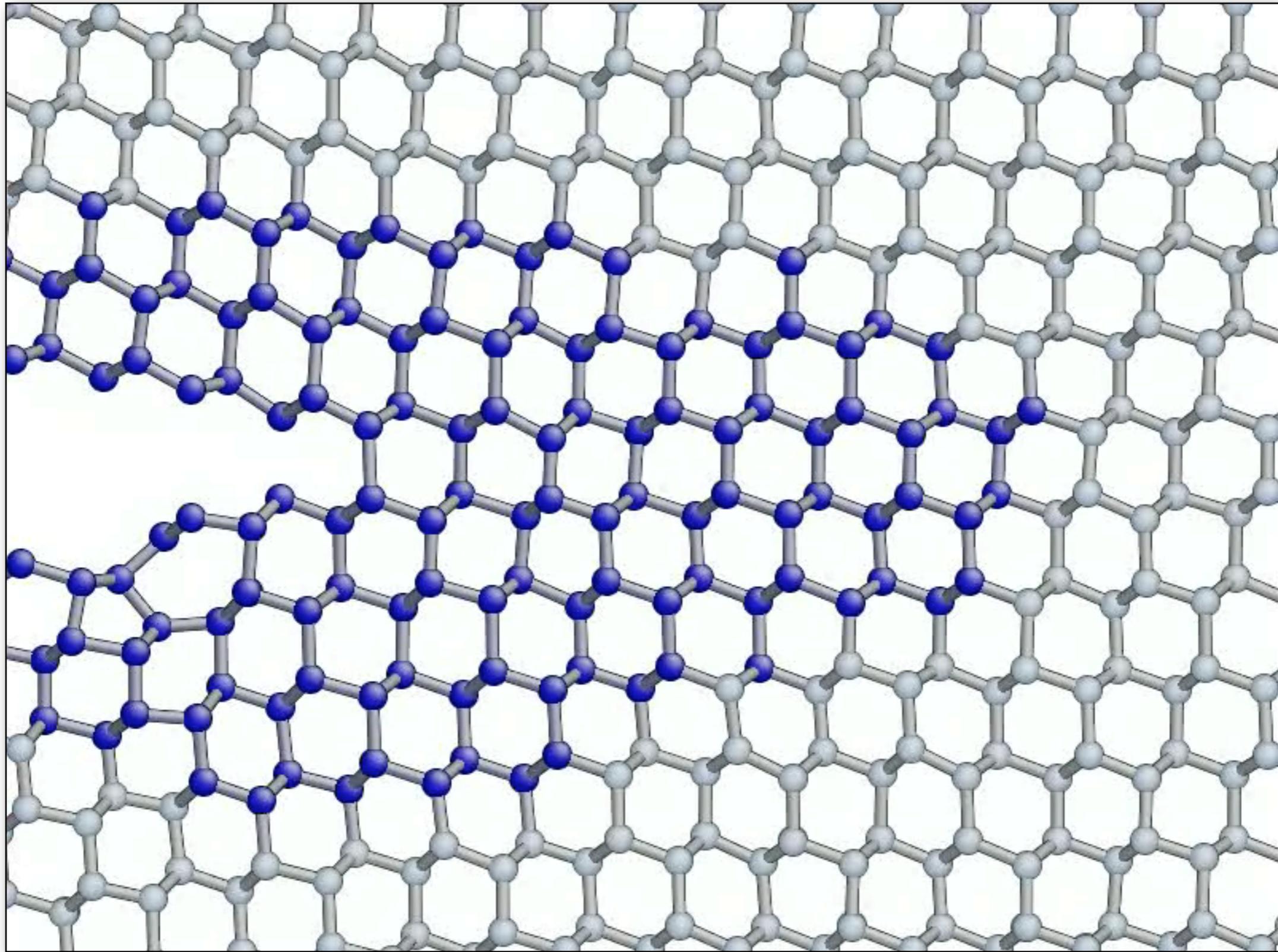
JR Kermode, L Ben-Bashat, F Atrash,  
JJ Cilliers, D Sherman and A. De Vita.,  
Nat. Commun. **4** 2441 (2013)

## Stress corrosion cracking

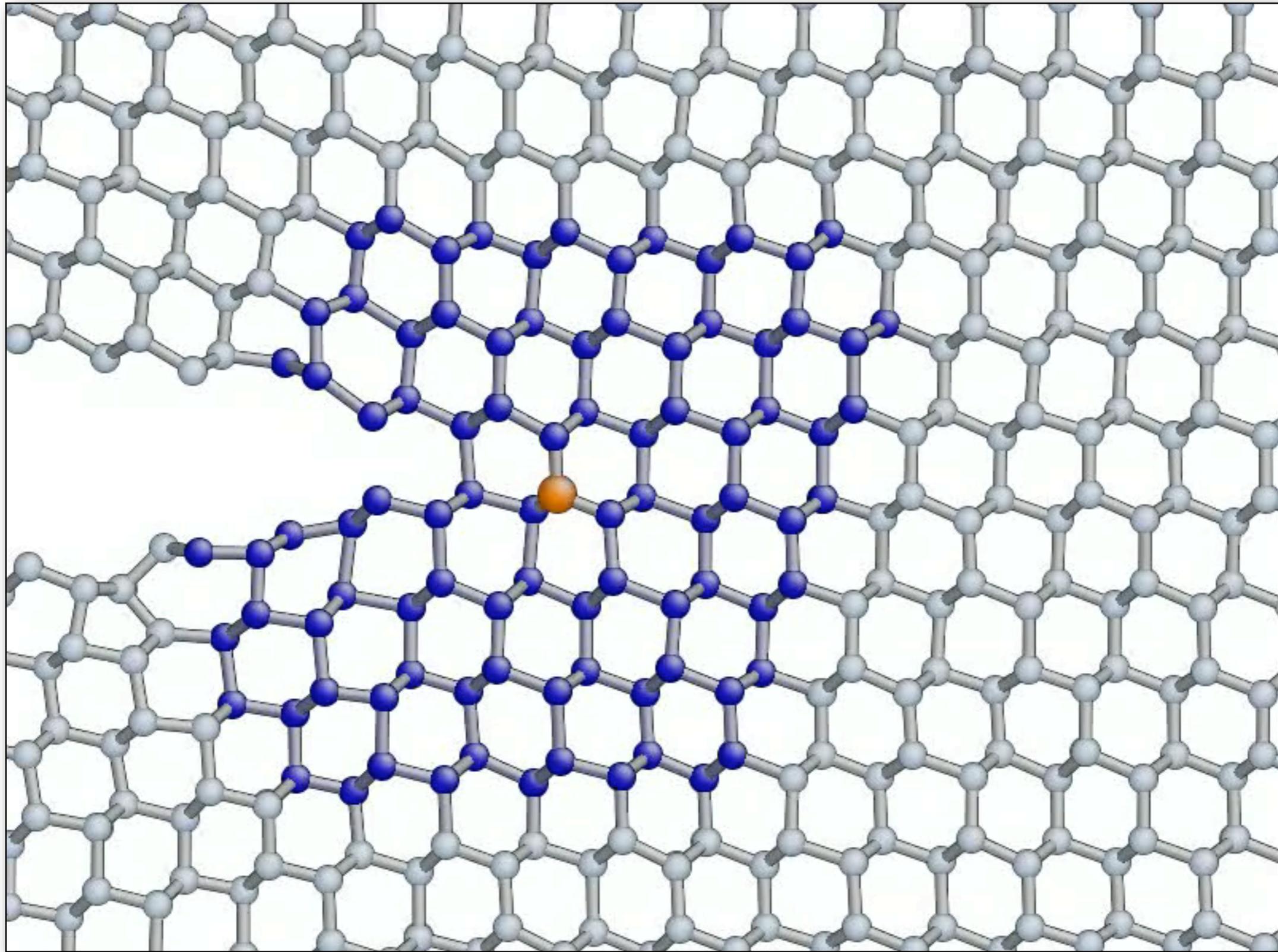


A Glazier, G Peralta, JR Kermode,  
A De Vita and D Sherman, Phys. Rev. Lett.,  
**112** 115501 (2014).

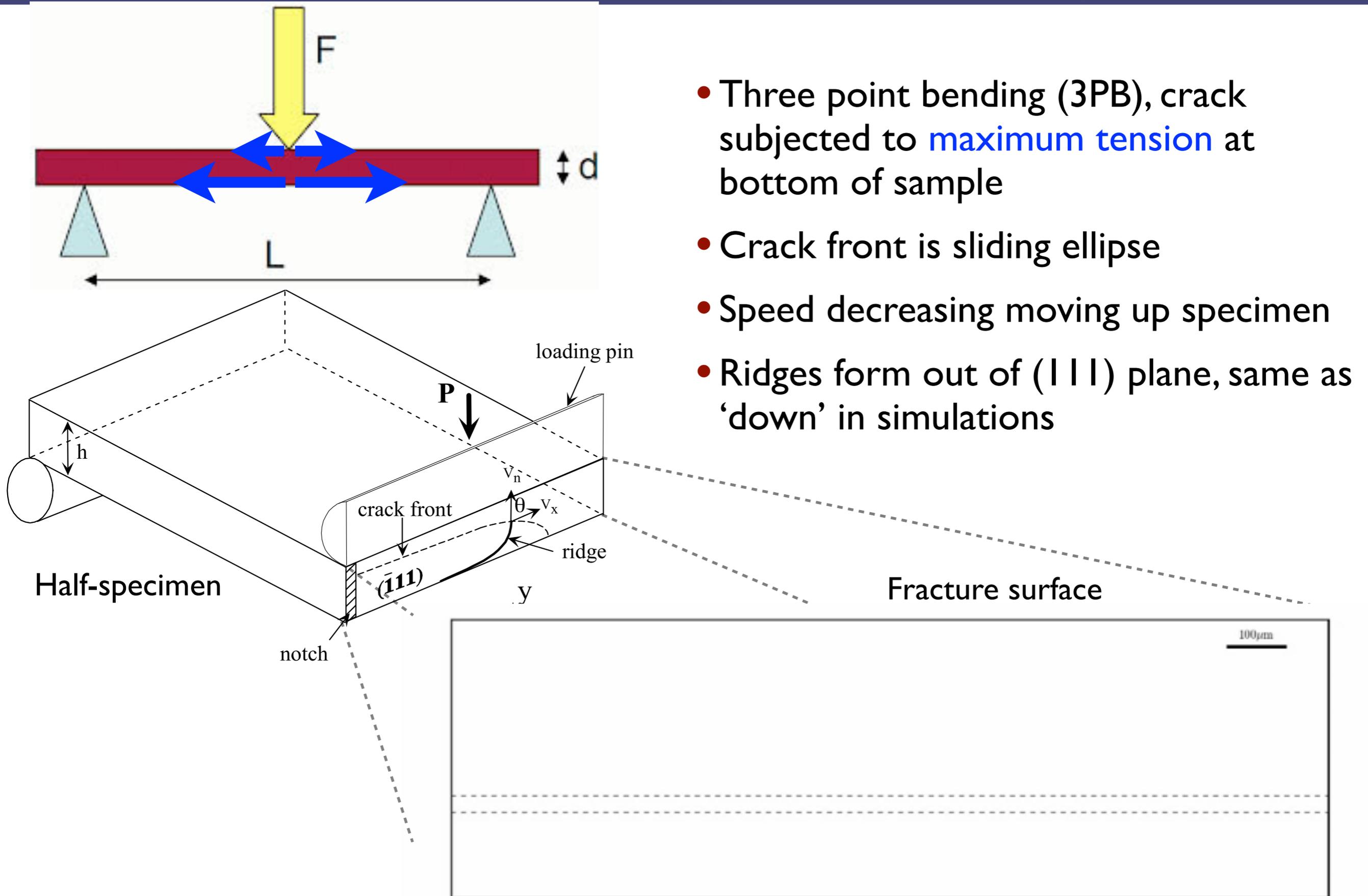
# Crack propagation vs. chemical impurities – simulation



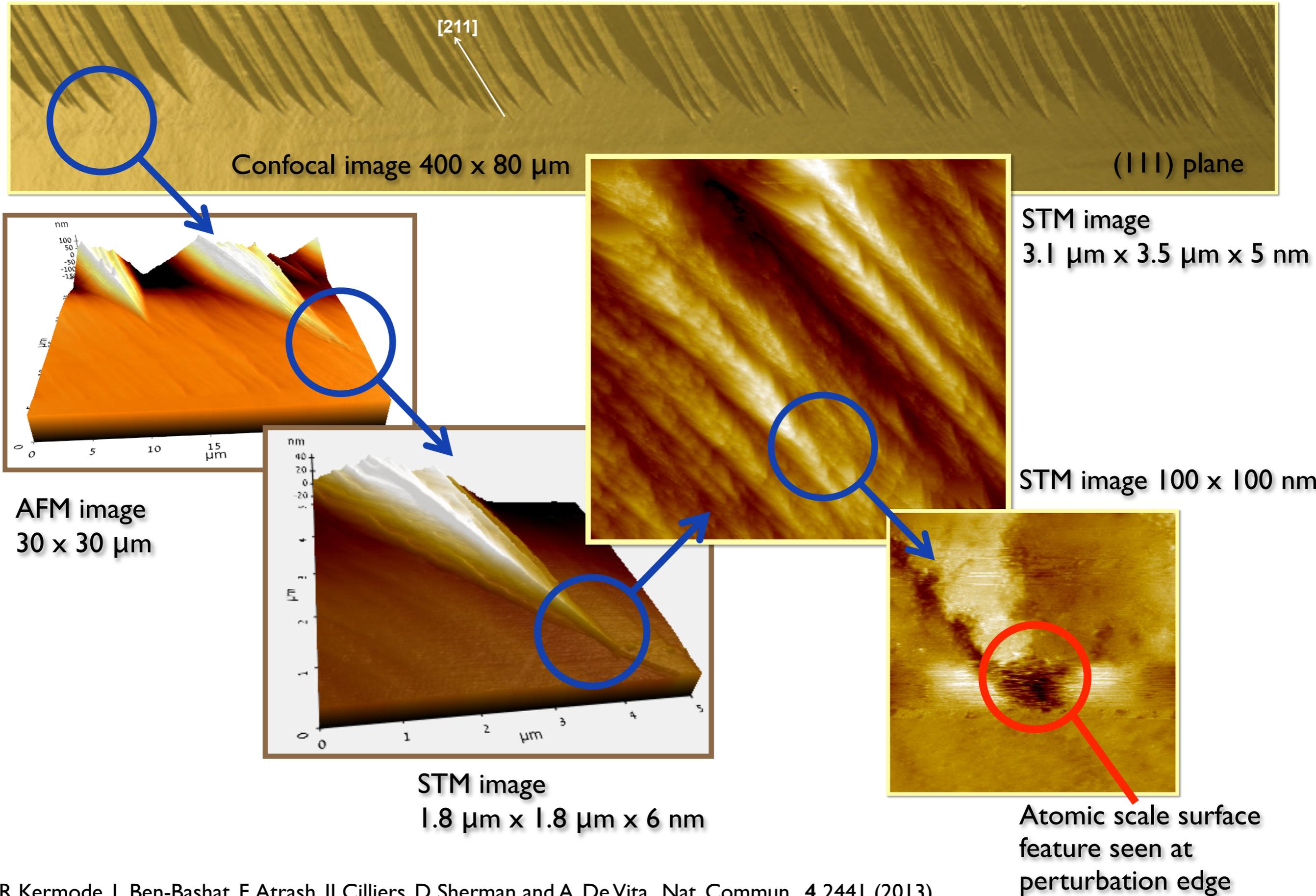
# Crack propagation vs. chemical impurities – simulation



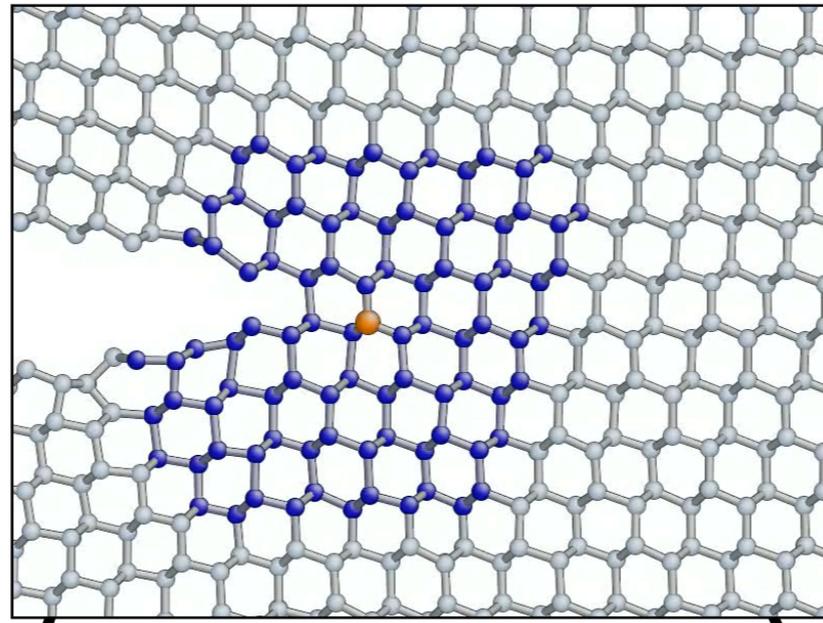
# Interaction between crack tips and point defects – experiments



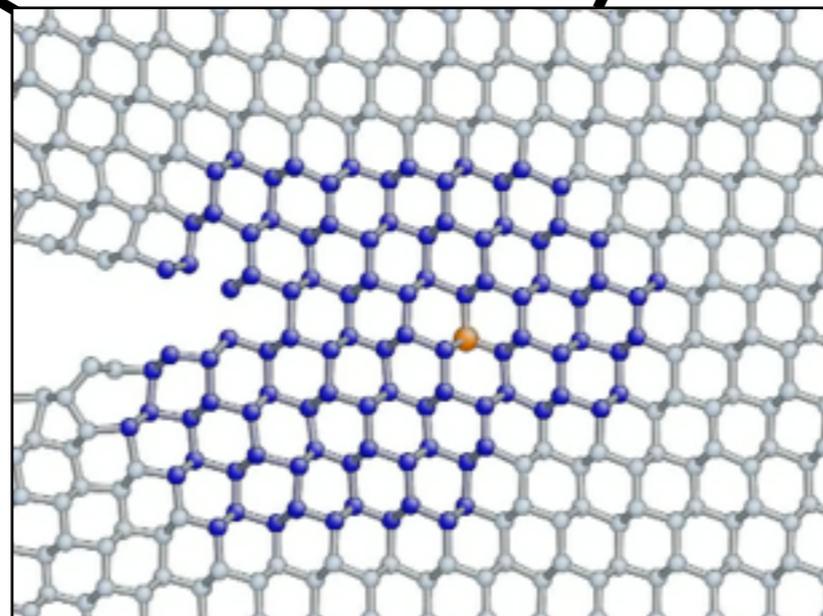
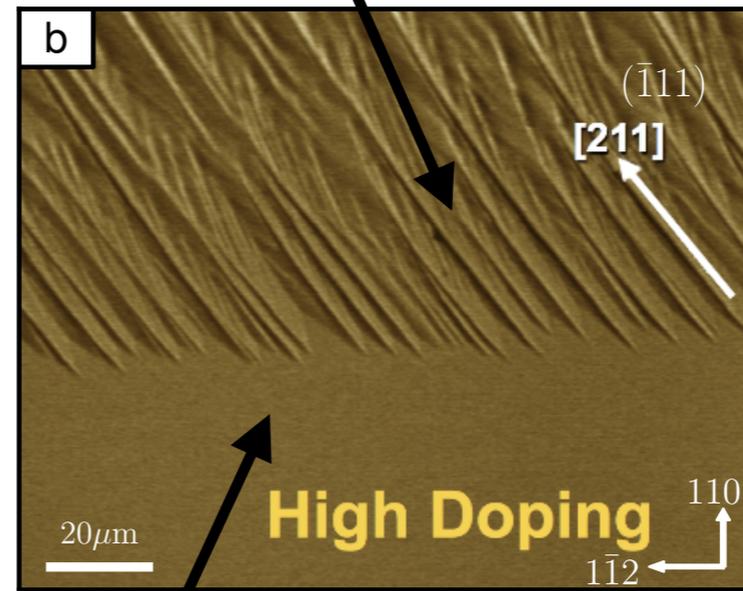
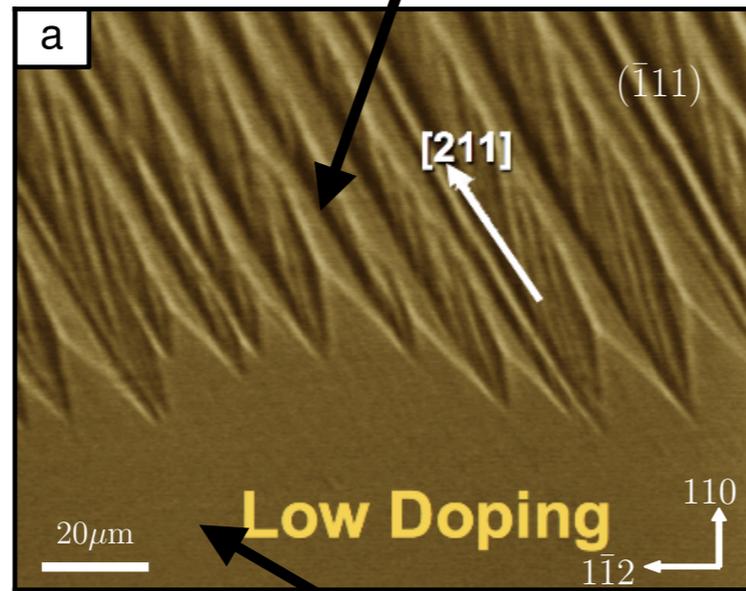
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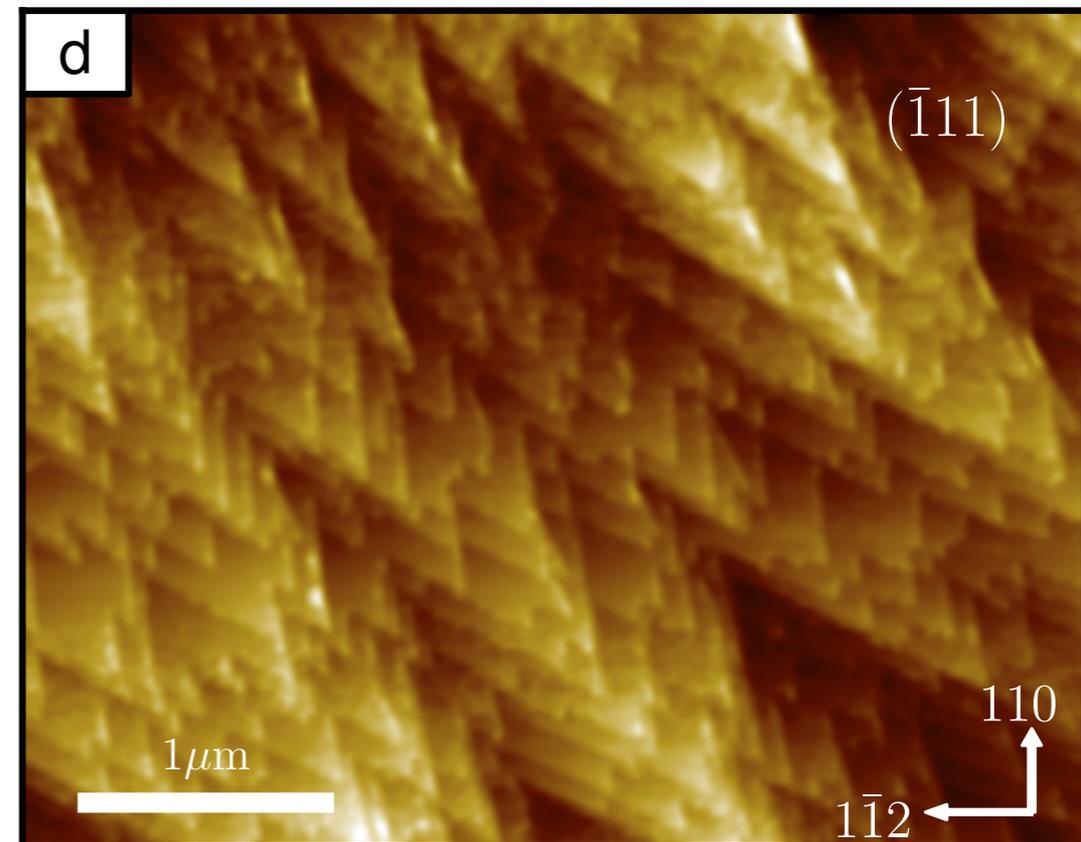
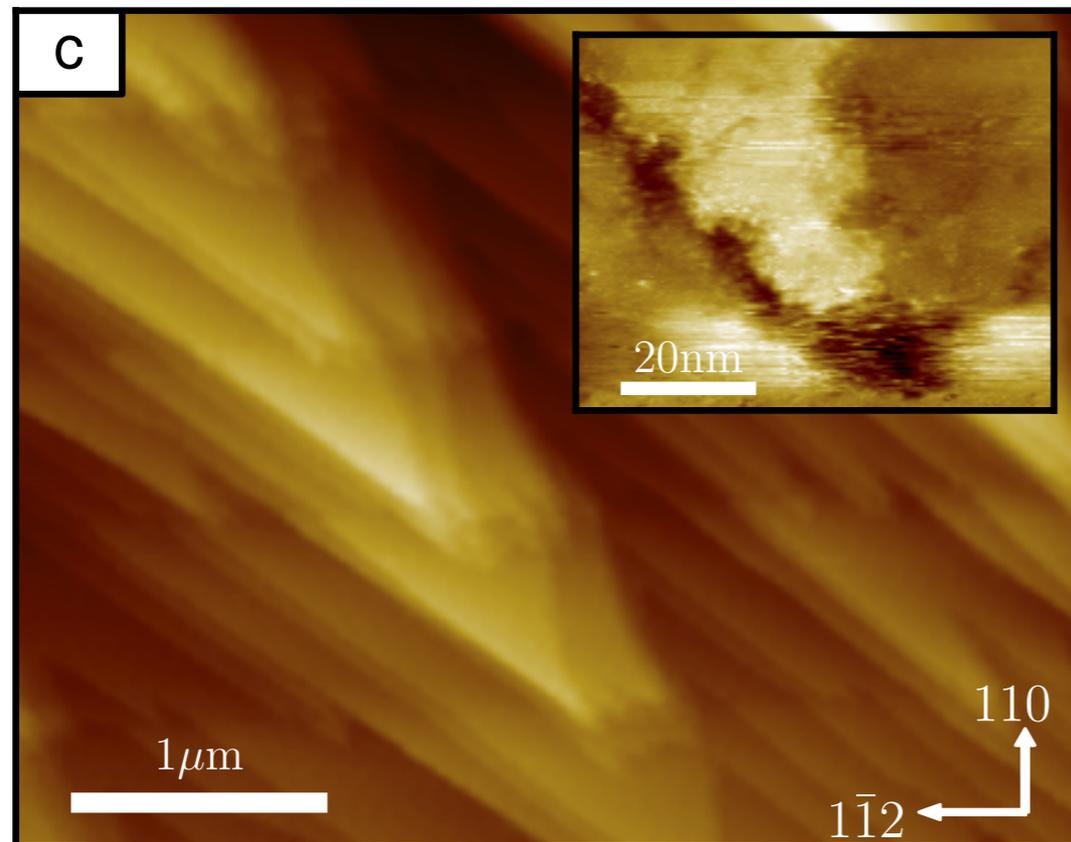
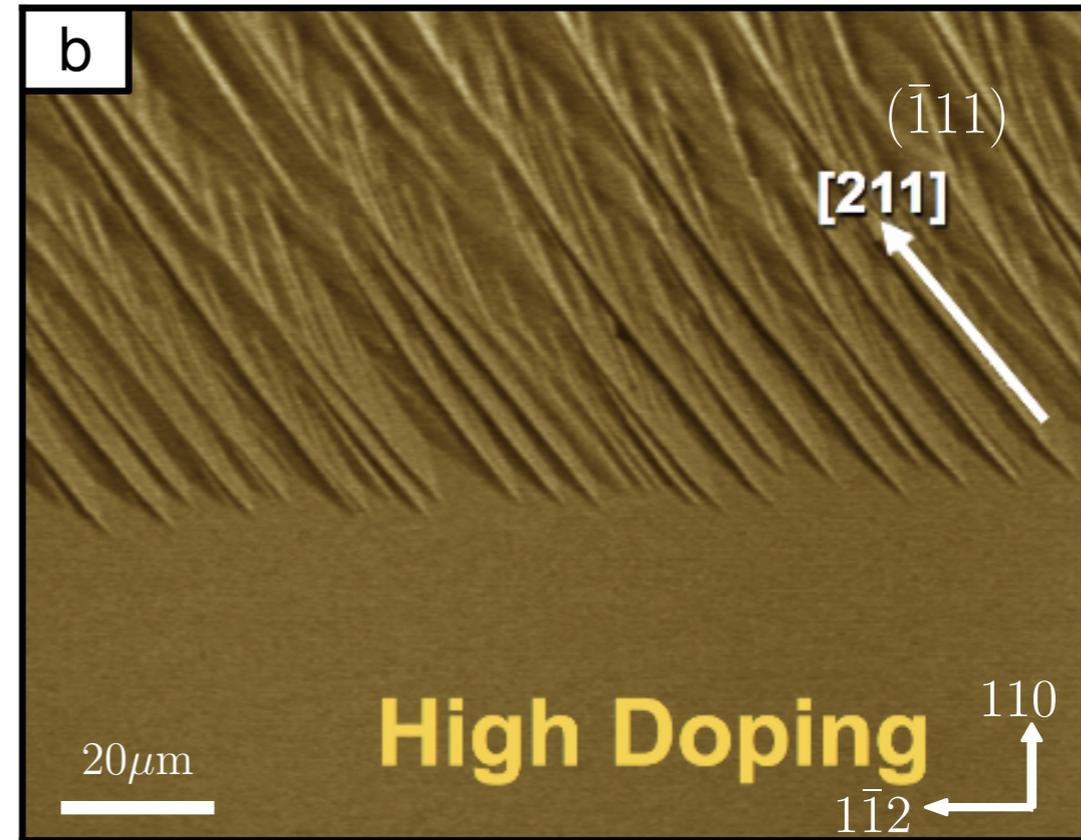
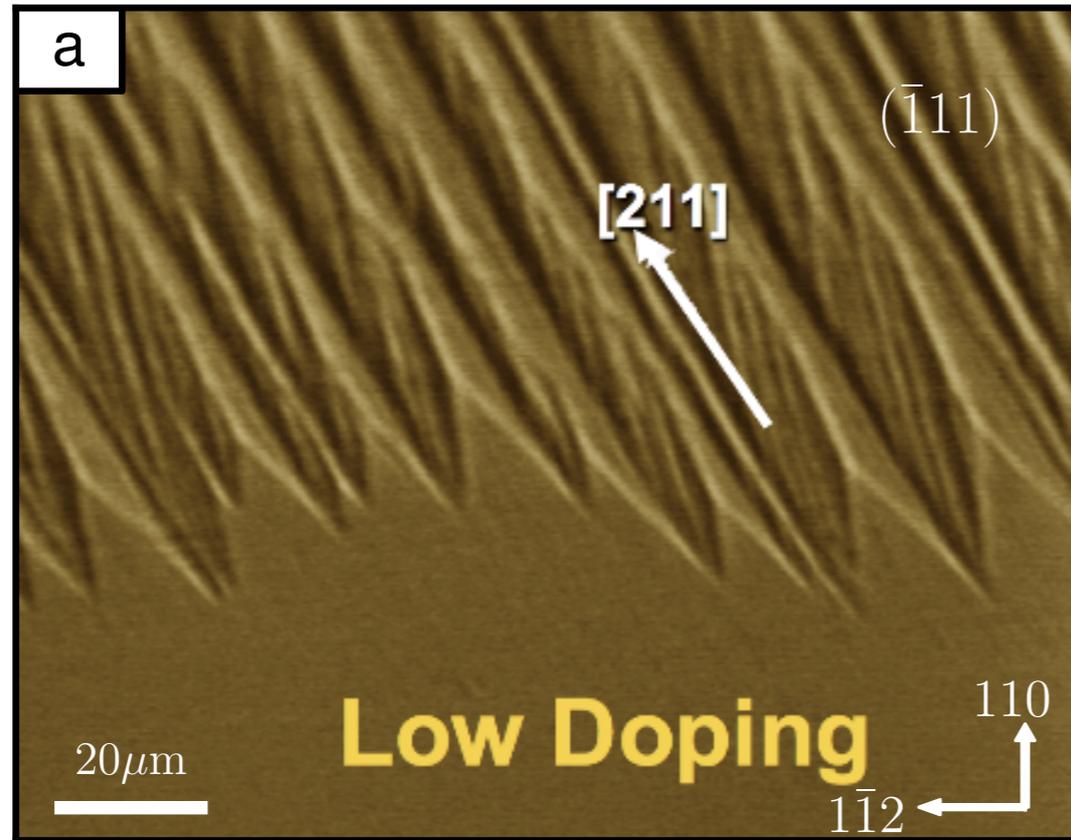
# Crack propagation vs. chemical impurities – experiment and theory



Decreasing crack speed,  
Increasing chance of interaction with B dopants



# Interaction between crack tips and point defects – experiments

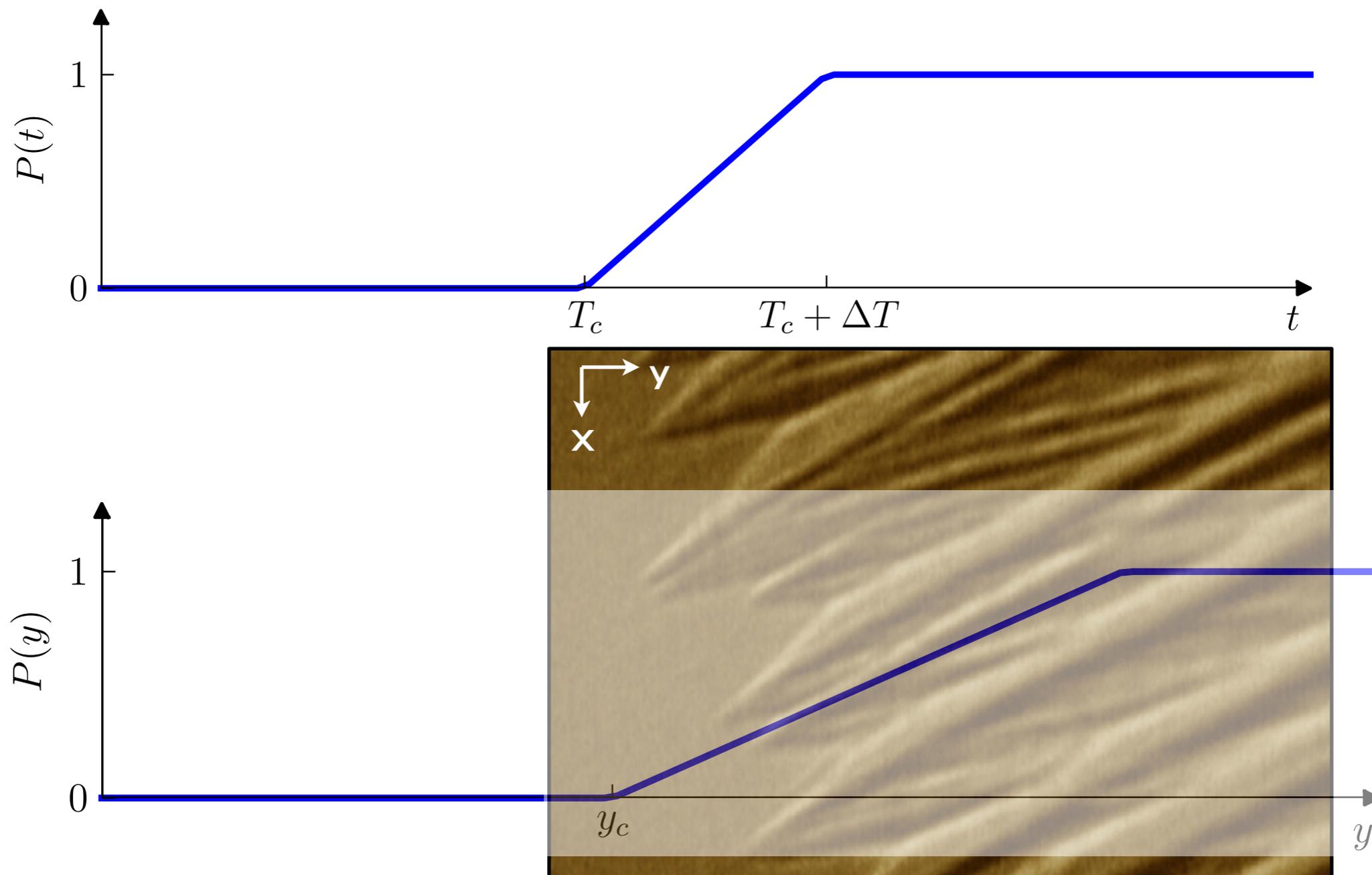


# Interaction between crack tips and point defects – model

Going back to our DFT simulations, two time scales are important:

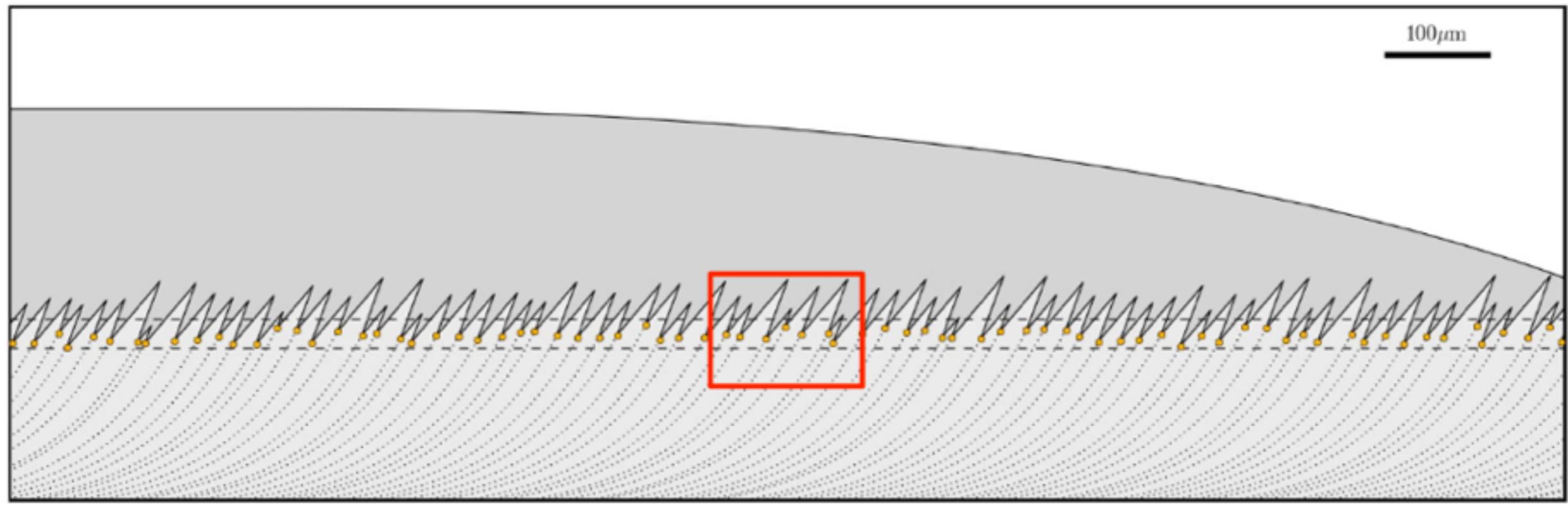
- Minimum time for deflection process to occur  $T_c$
- Time for crack to advance by one bond  $a/v_c$

$T_c$  is 'blurred' by period  $\Delta T$  of phonon mode that triggers deflection

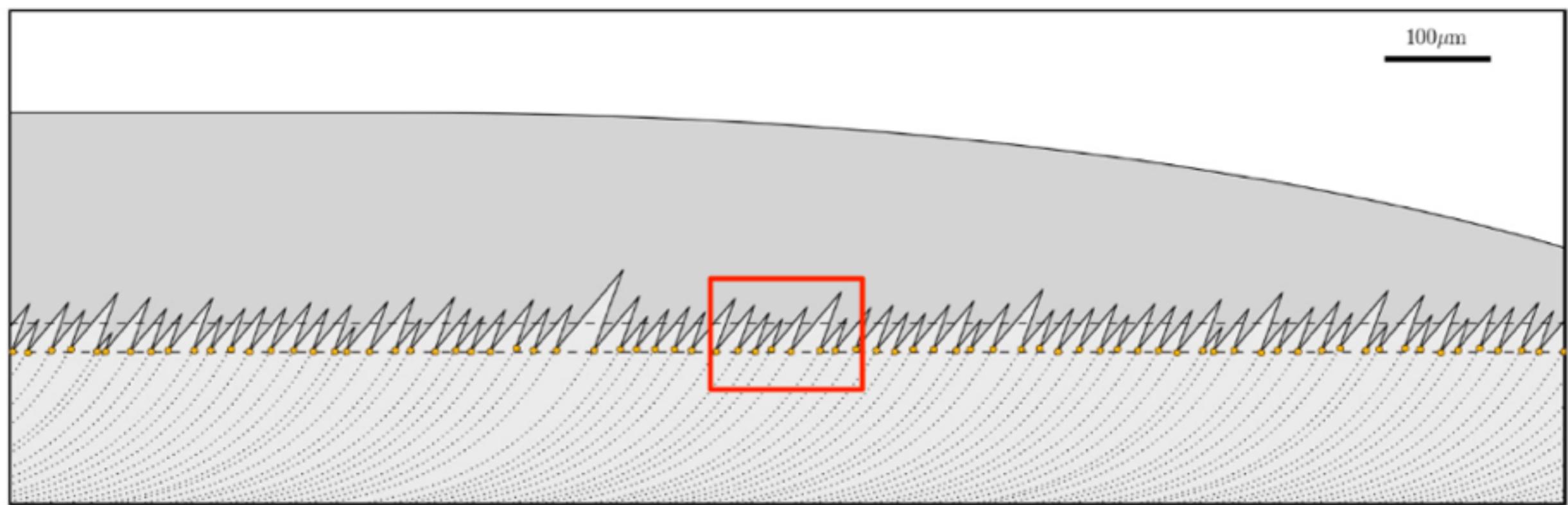


# Interaction between crack tips and point defects – model

Low doping

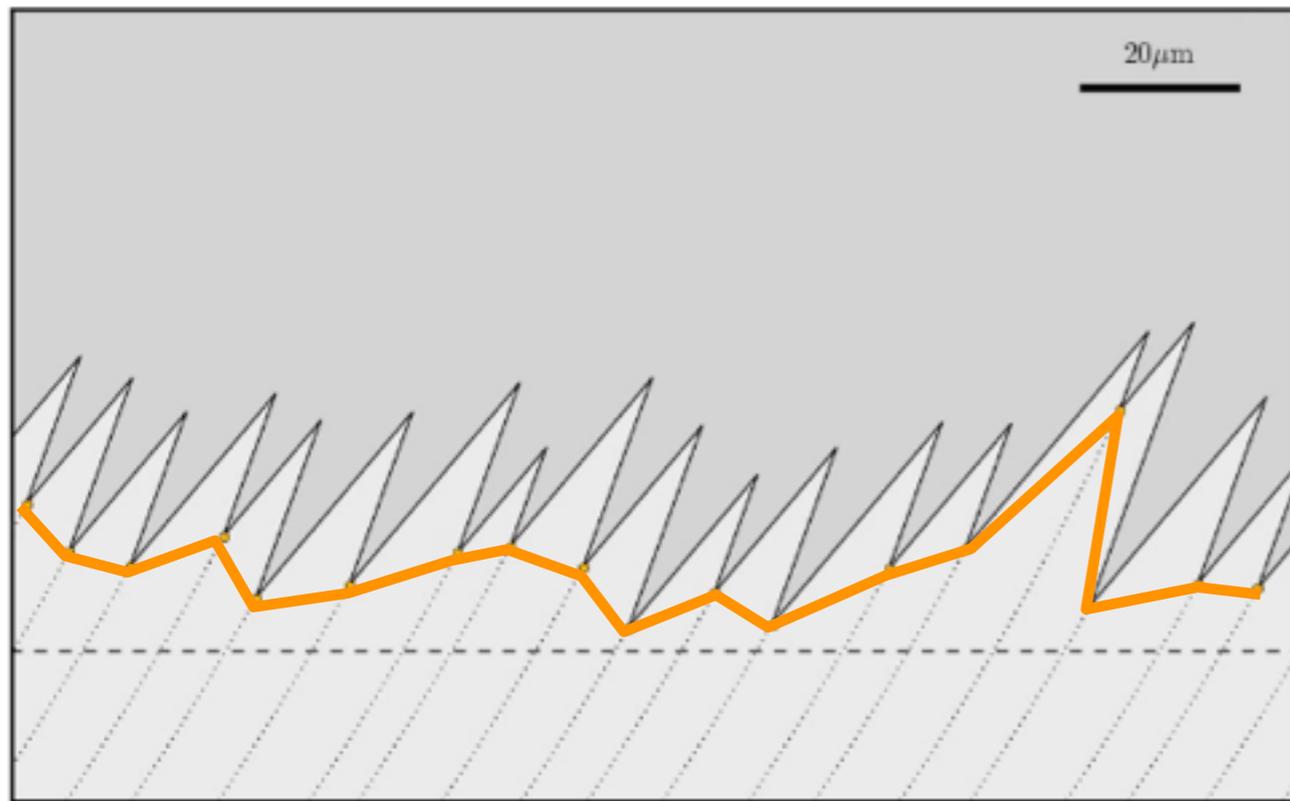


High doping



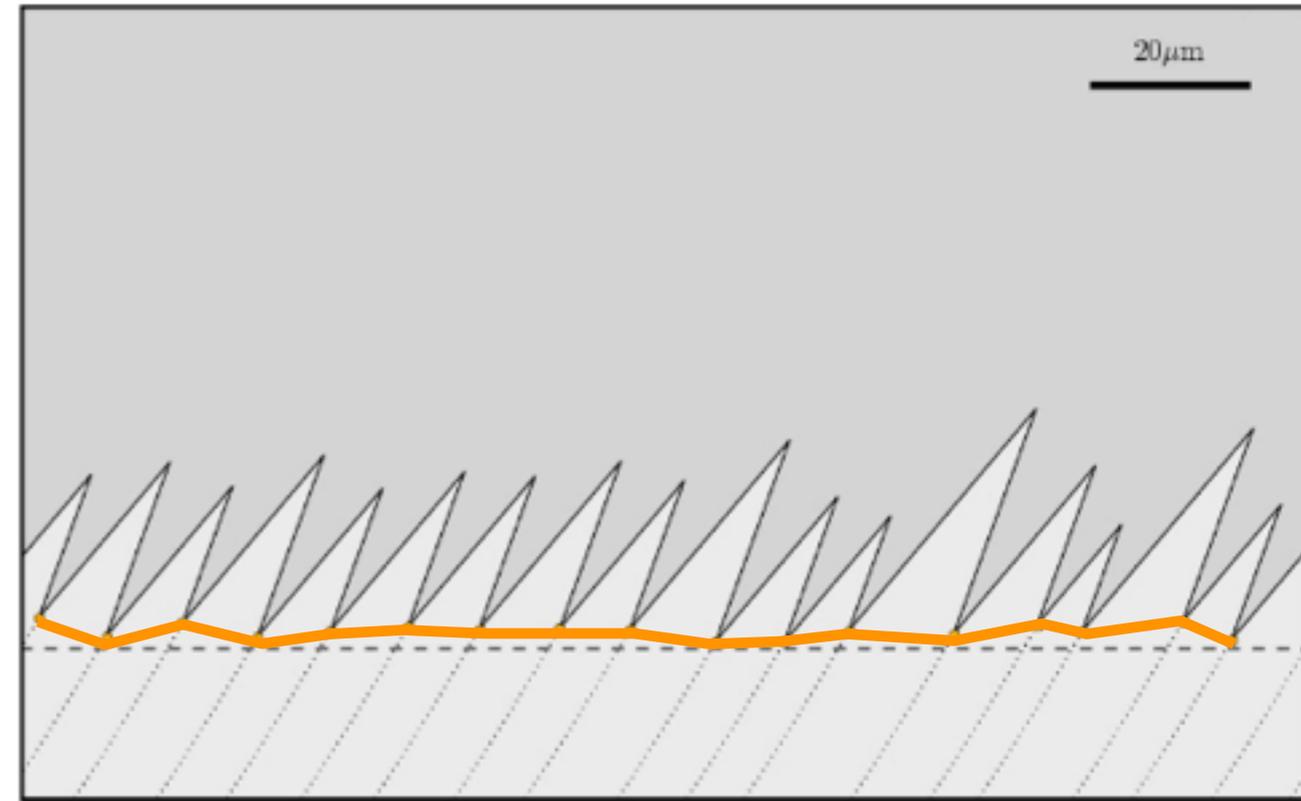
# Crack propagation vs. chemical impurities – mesoscale model

Low doping



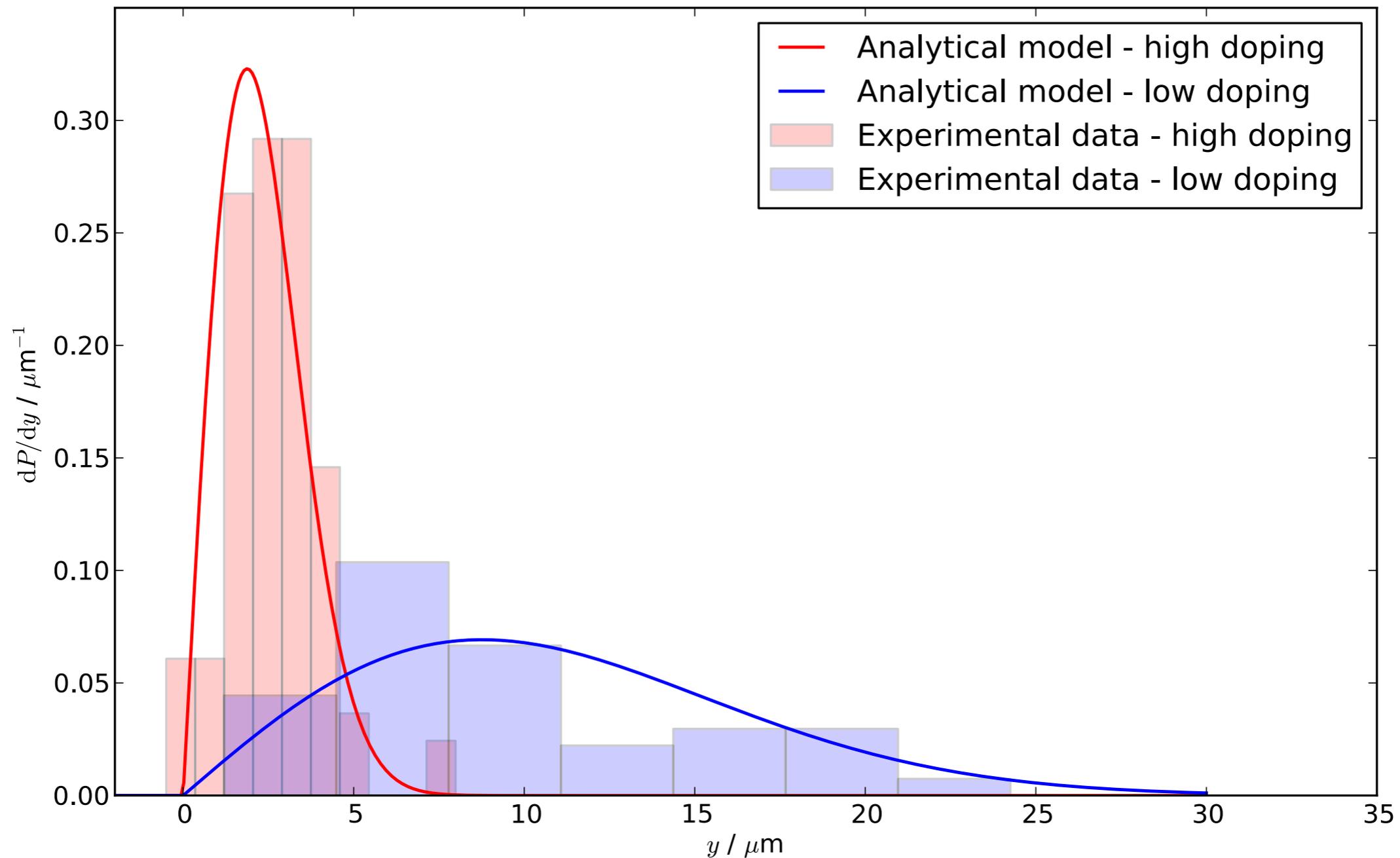
Roughness ~ 10 micron

High doping



Roughness ~ 2 micron

# Interaction between crack tips and point defects – model vs. expt.

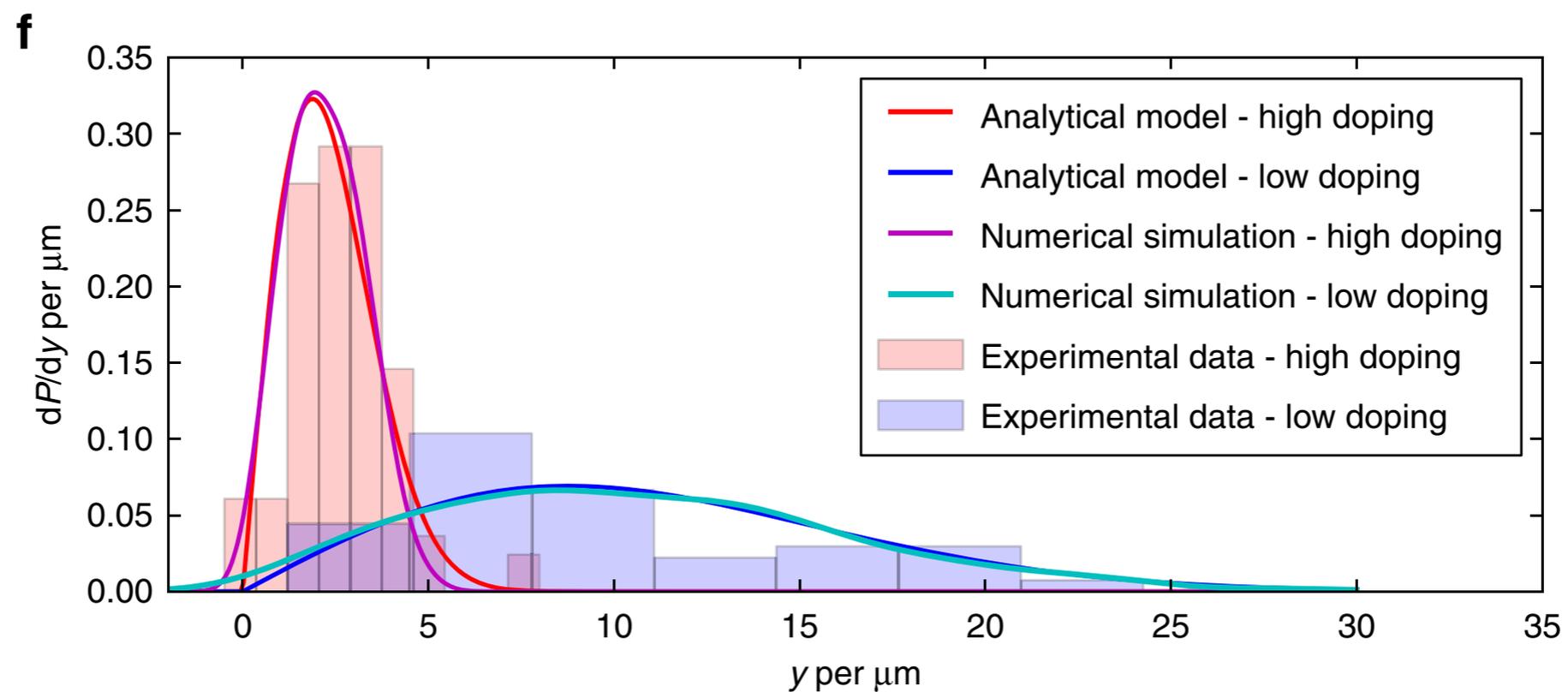
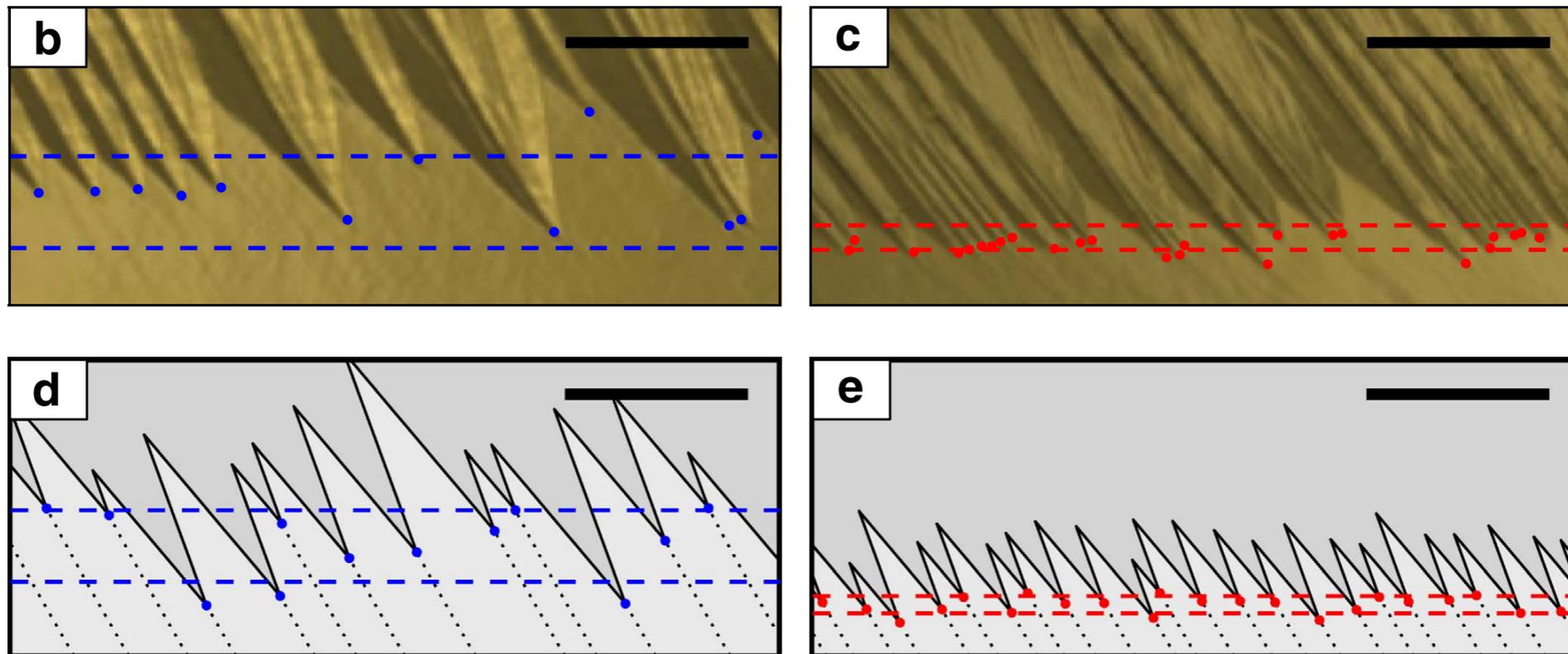


$$\frac{dR}{dy} = \frac{y}{\sigma^2} \exp\left(-\frac{y^2}{2\sigma^2}\right) \quad \sigma = \sqrt{\frac{\Delta T v_c^3}{\alpha n' a g}}$$

# Crack propagation vs. chemical impurities – experiment and theory

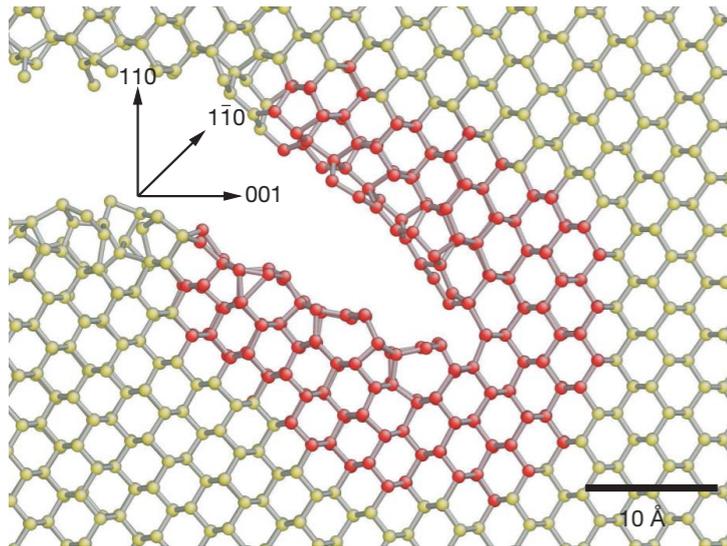
Low doping

High doping



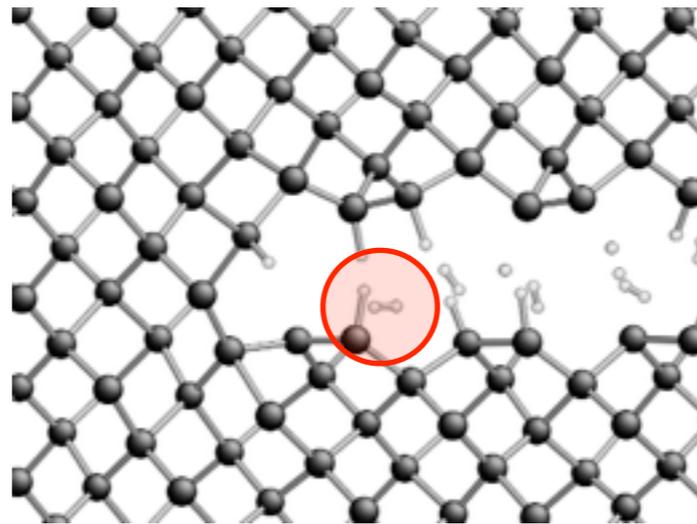
# Overview of Fracture Modelling Applications

## Dynamical instabilities in Si



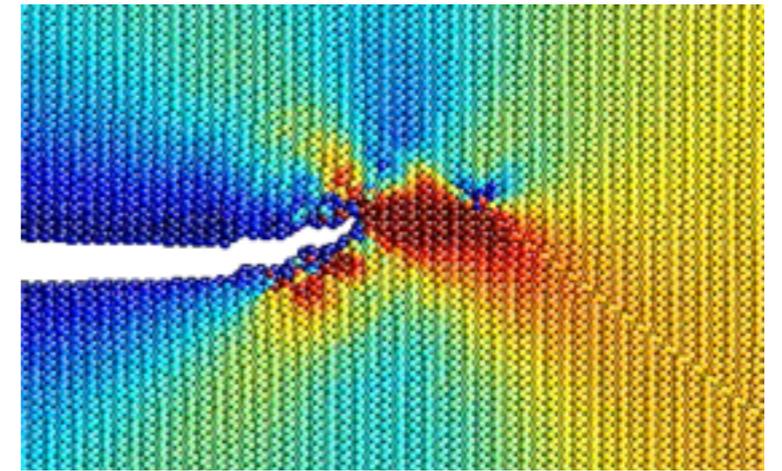
JR Kermode *et al.*  
Nature **455** 1224 (2008)

## H induced 'SmartCut'



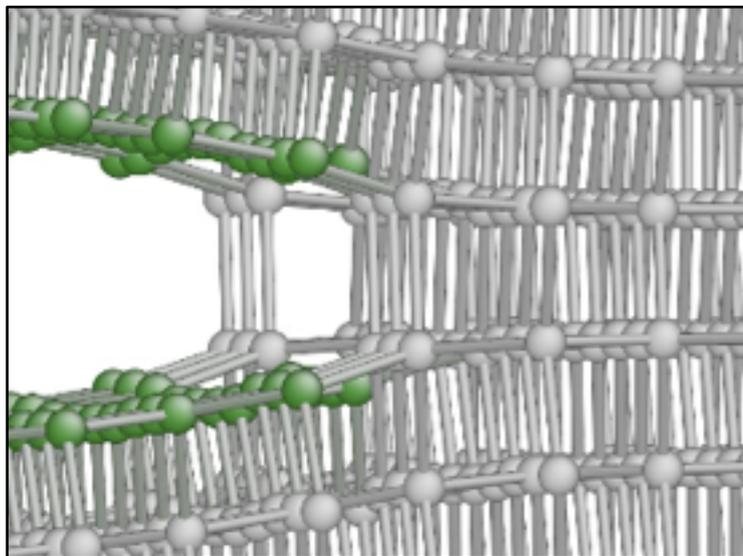
G Moras *et al.* Phys. Rev. Lett.  
**105**, 075502 (2010)

## Crack-dislocation interactions



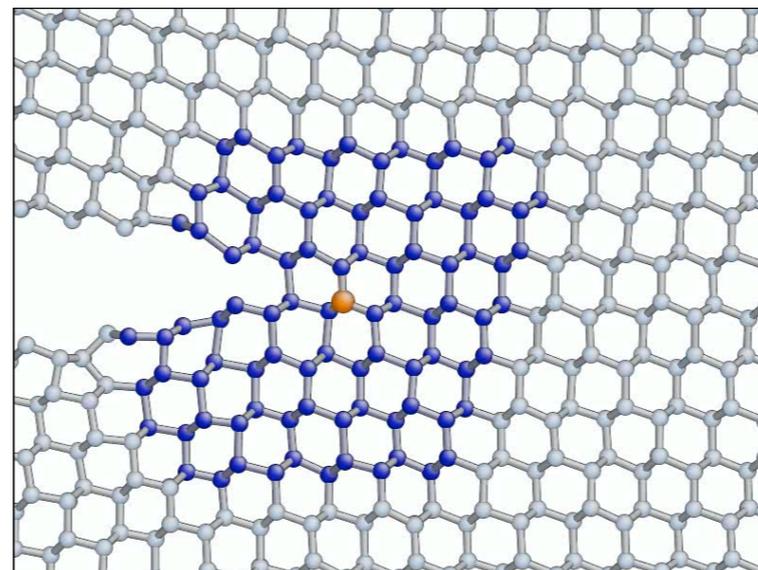
C Gattinoni, JR Kermode and  
A De Vita, *In prep* (2014)

## Three dimensional effects



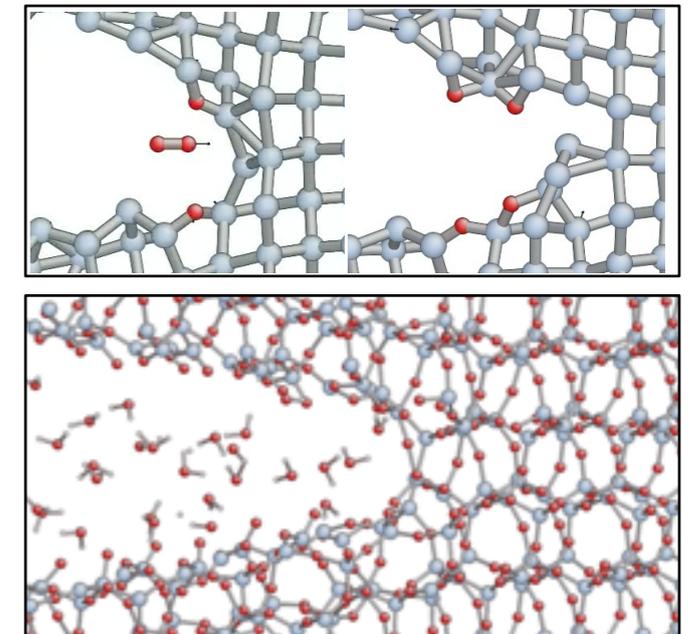
JR Kermode, A. Glazier, G Csányi,  
D Sherman and A De Vita, *In prep* (2014)

## Crack-impurity scattering



JR Kermode, L Ben-Bashat, F Atrash,  
JJ Cilliers, D Sherman and A. De Vita.,  
Nat. Commun. **4** 2441 (2013)

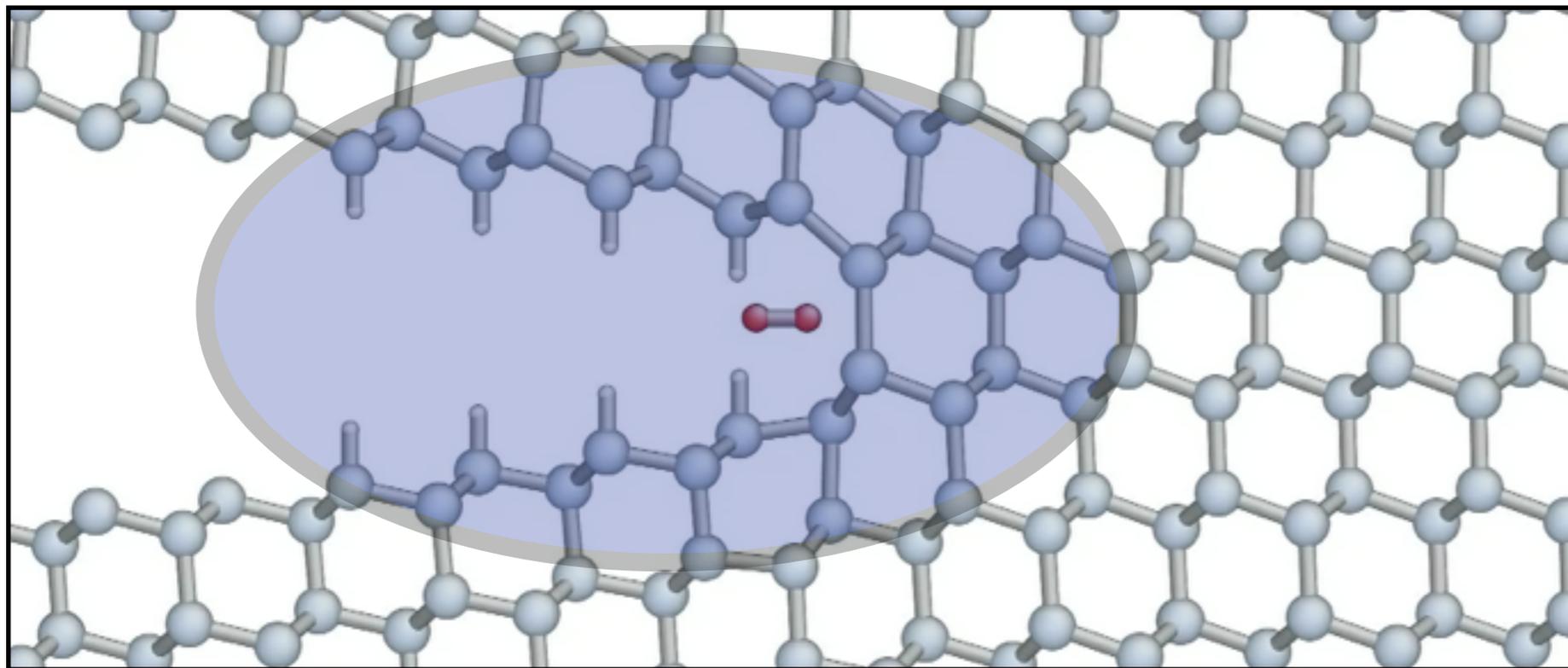
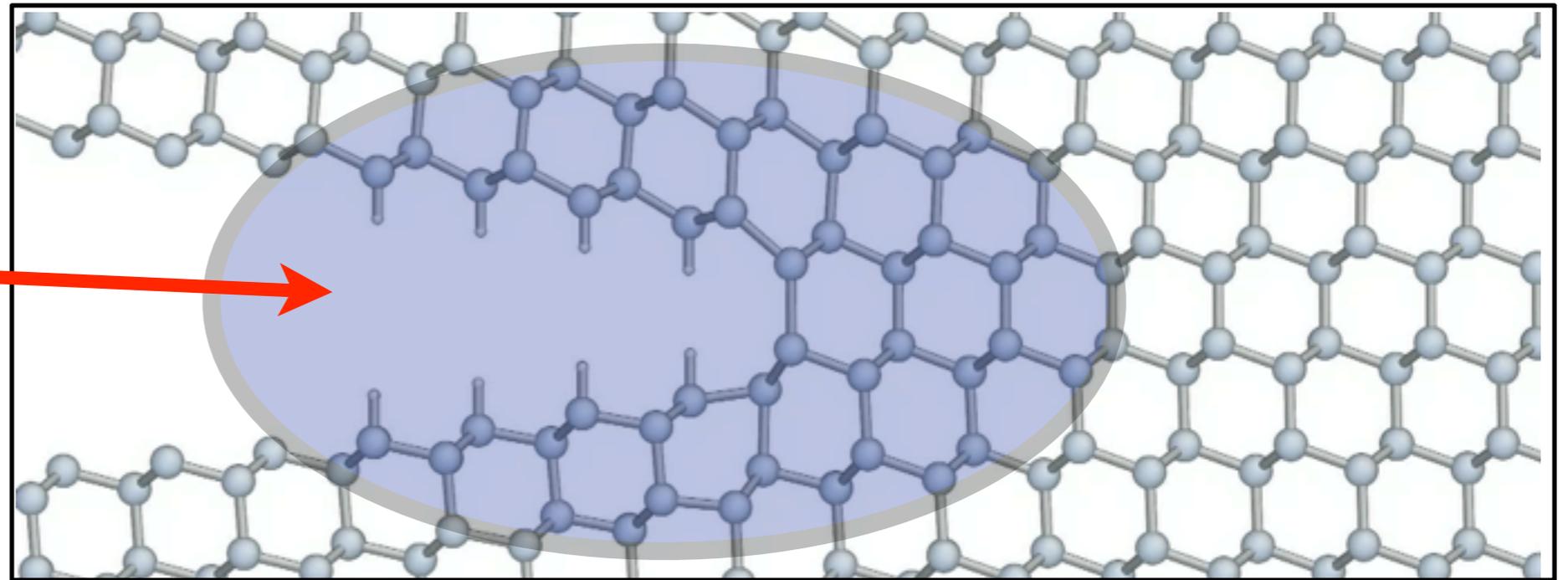
## Stress corrosion cracking



A Glazier, G Peralta, JR Kermode,  
A De Vita and D Sherman, Phys. Rev. Lett.,  
**112** 115501 (2014).

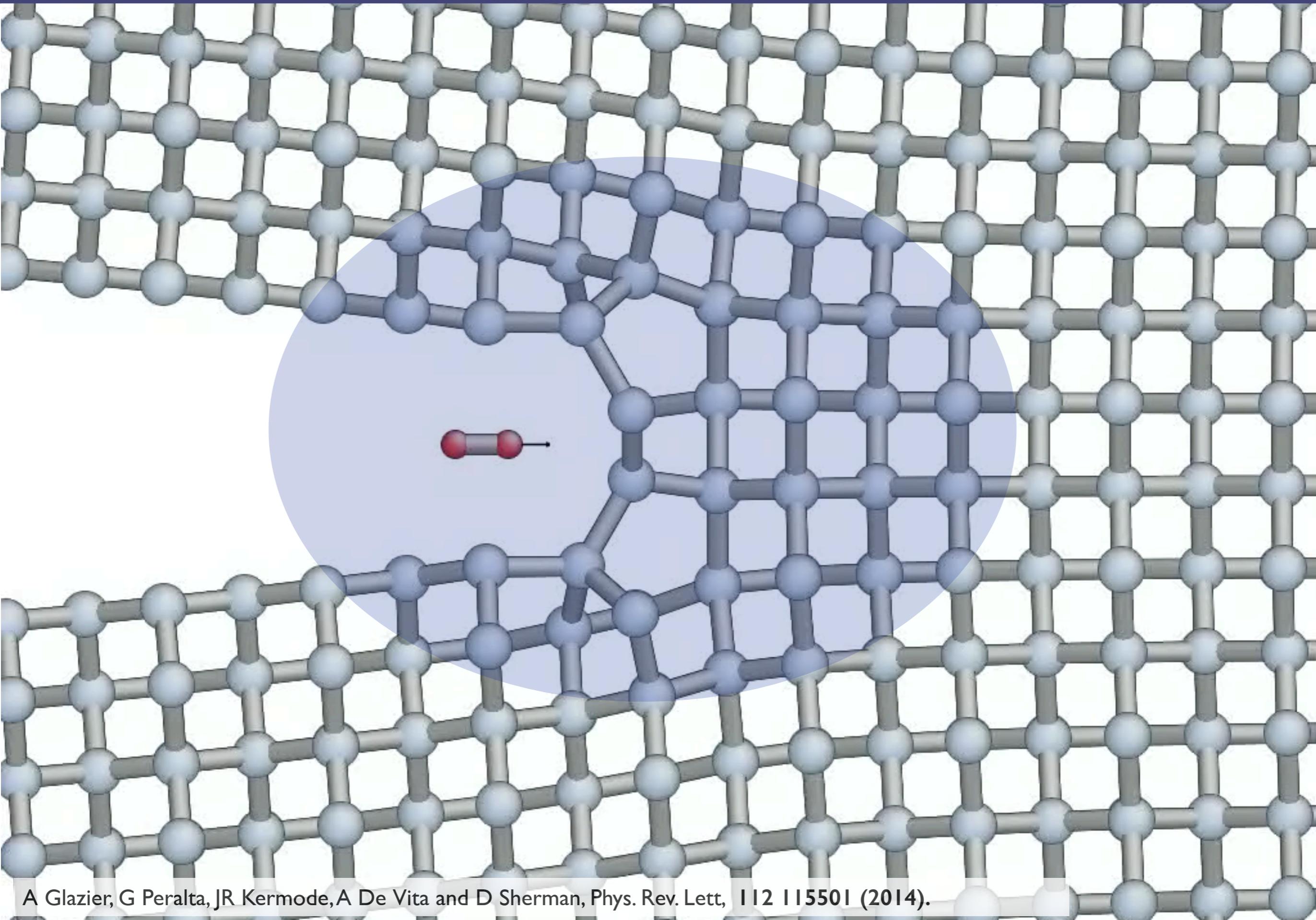
# Stress corrosion cracking – silicon (111) surface

- Si(111), sub-critical loading  $G = 2.70 \text{ J/m}^2 < G_c = 2.88 \text{ J/m}^2$
- QM (DFT) region: ~200 atoms
- Crack is lattice trapped at 300 K

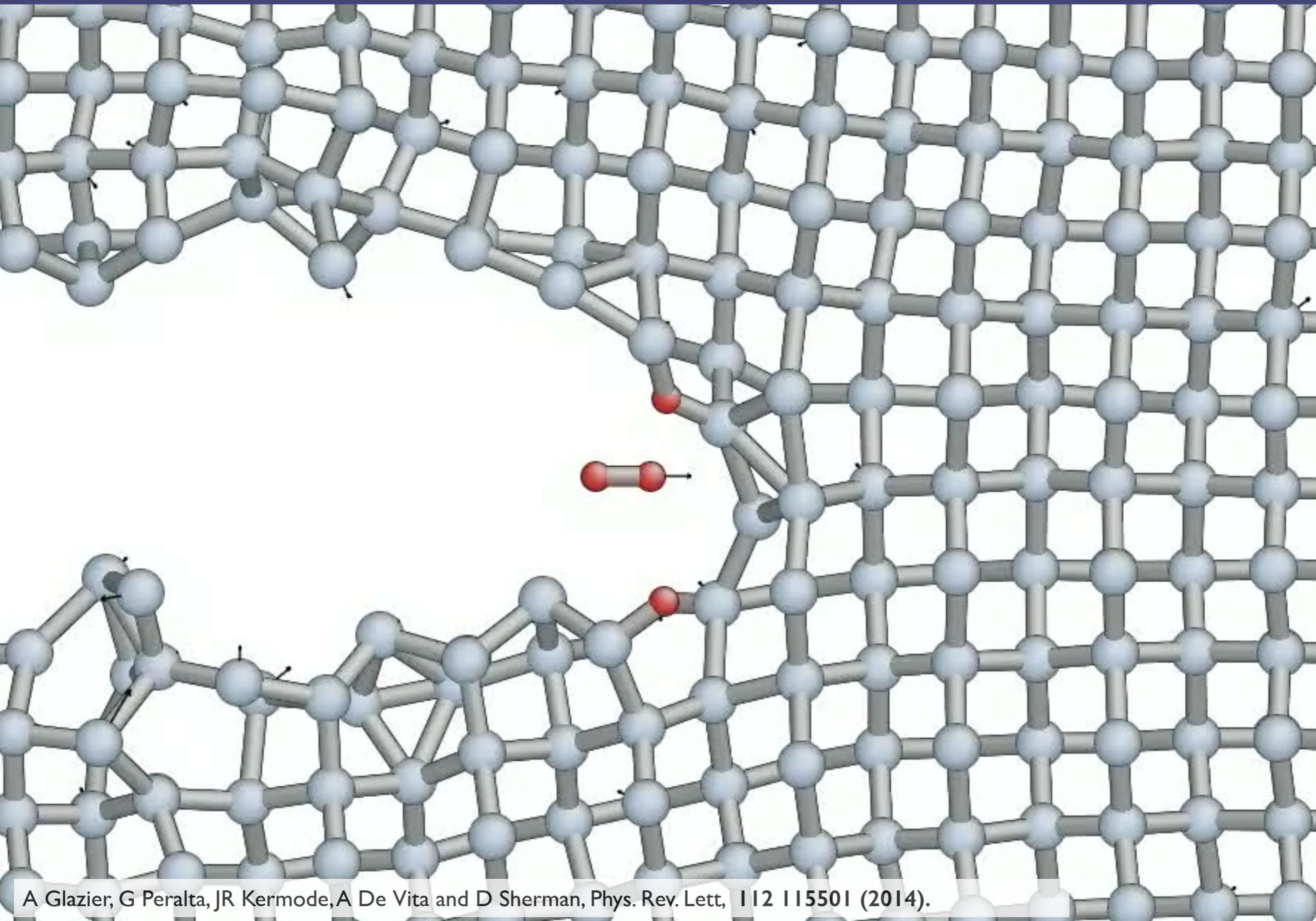


- Add  $\text{O}_2$ : dissociates, providing enough heat to break one Si–Si bond
- Diffusion limited regime: oxygen supply controls crack speed

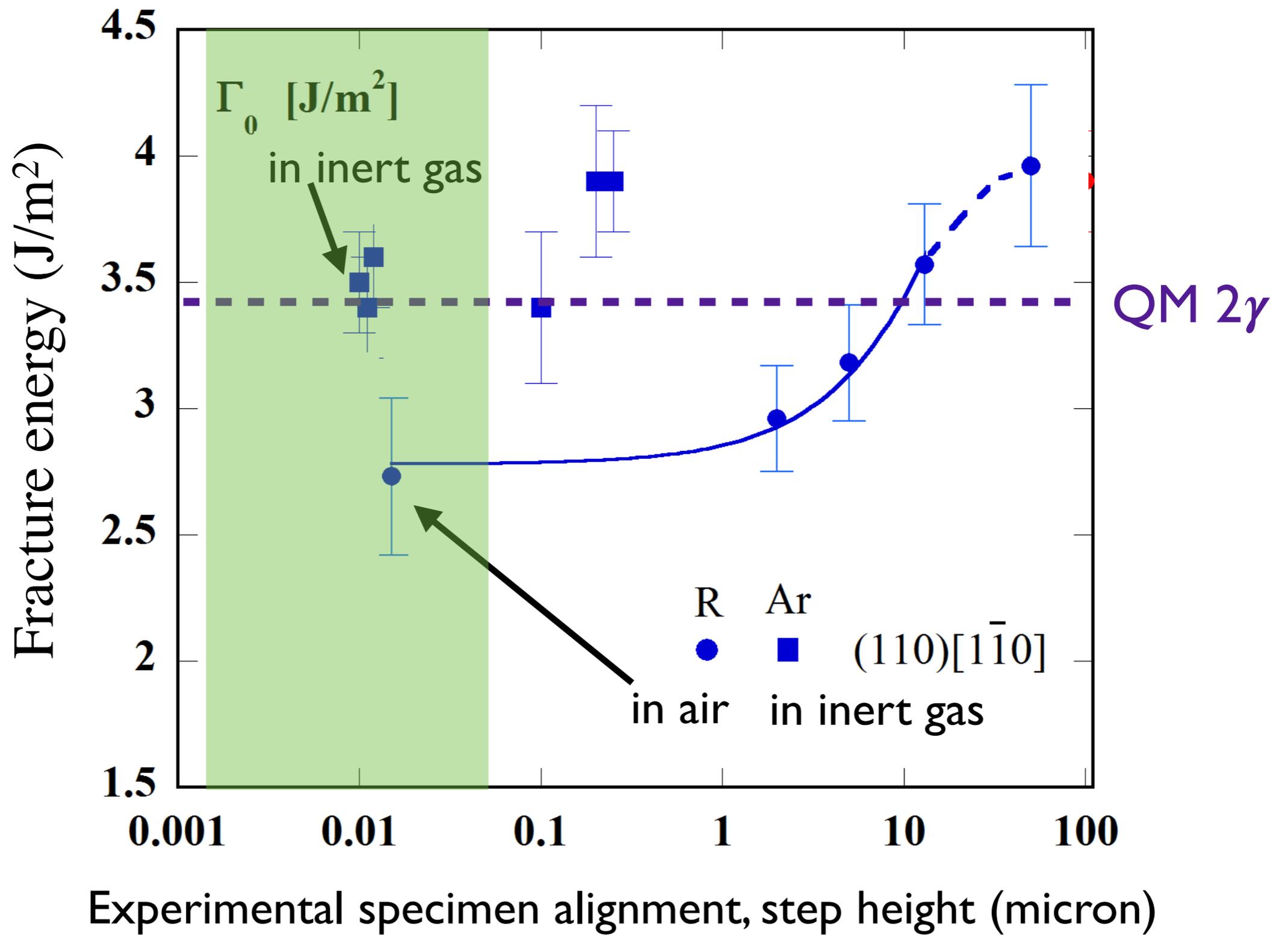
# Stress corrosion cracking – simulations



# Stress corrosion cracking – simulations

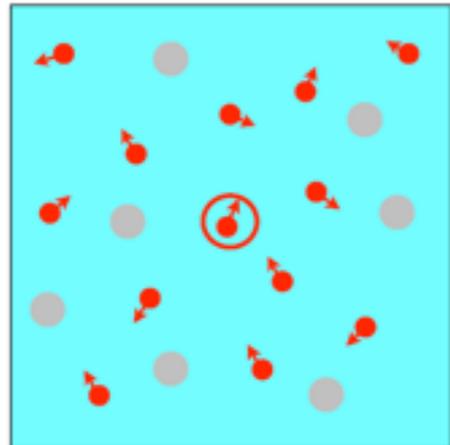


# Stress corrosion cracking – experiments



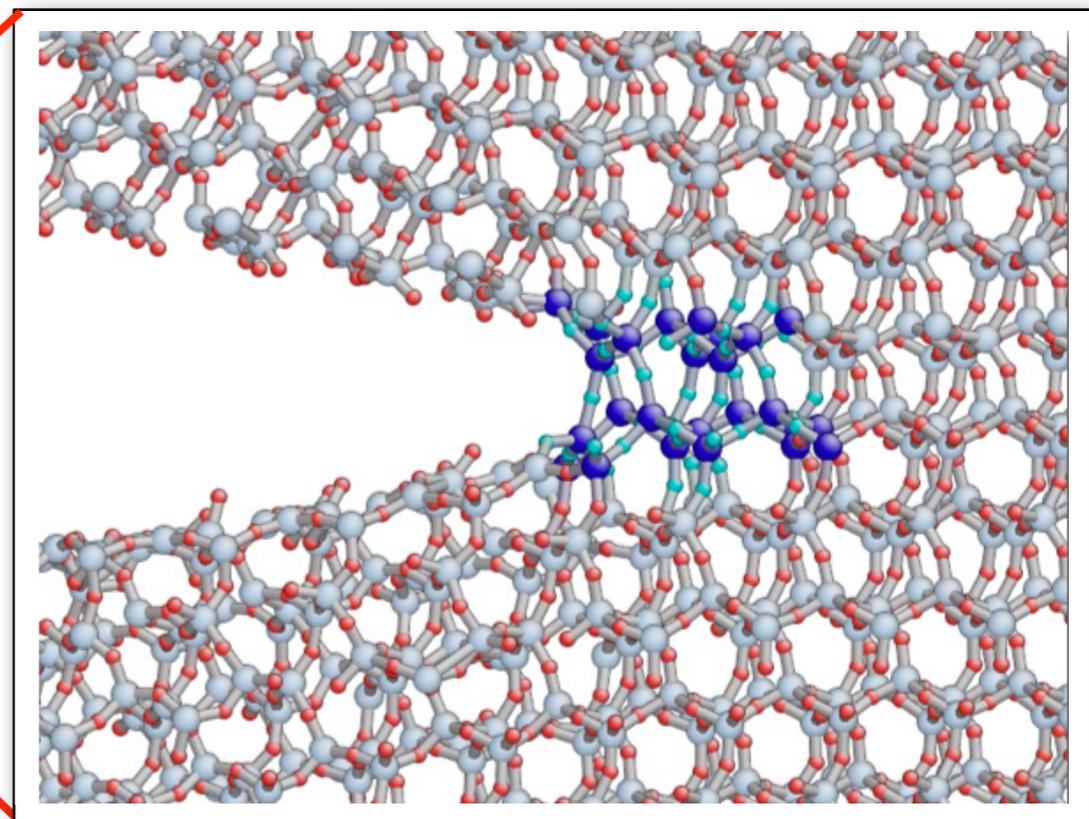
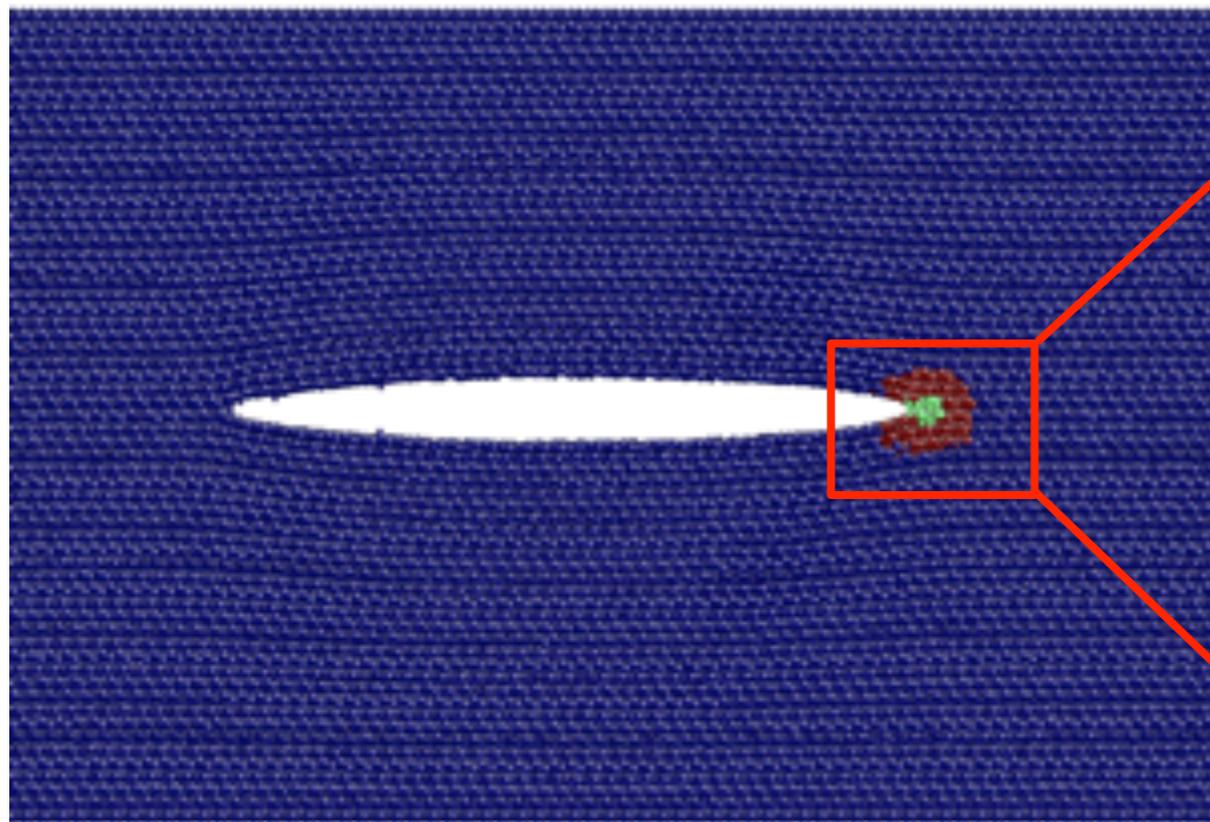
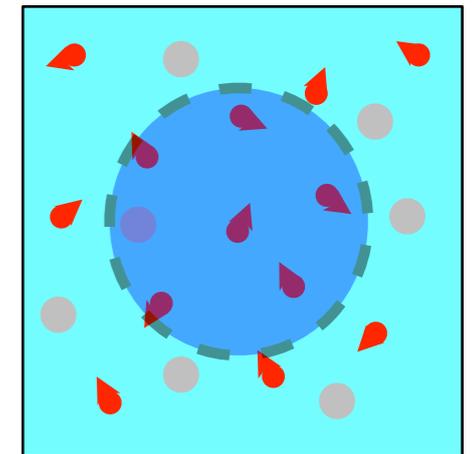
# Fracture of quartz – polarisable potential and QM/MM

Starting point: Tangney-Scandolo interatomic potential with self-consistent dipoles

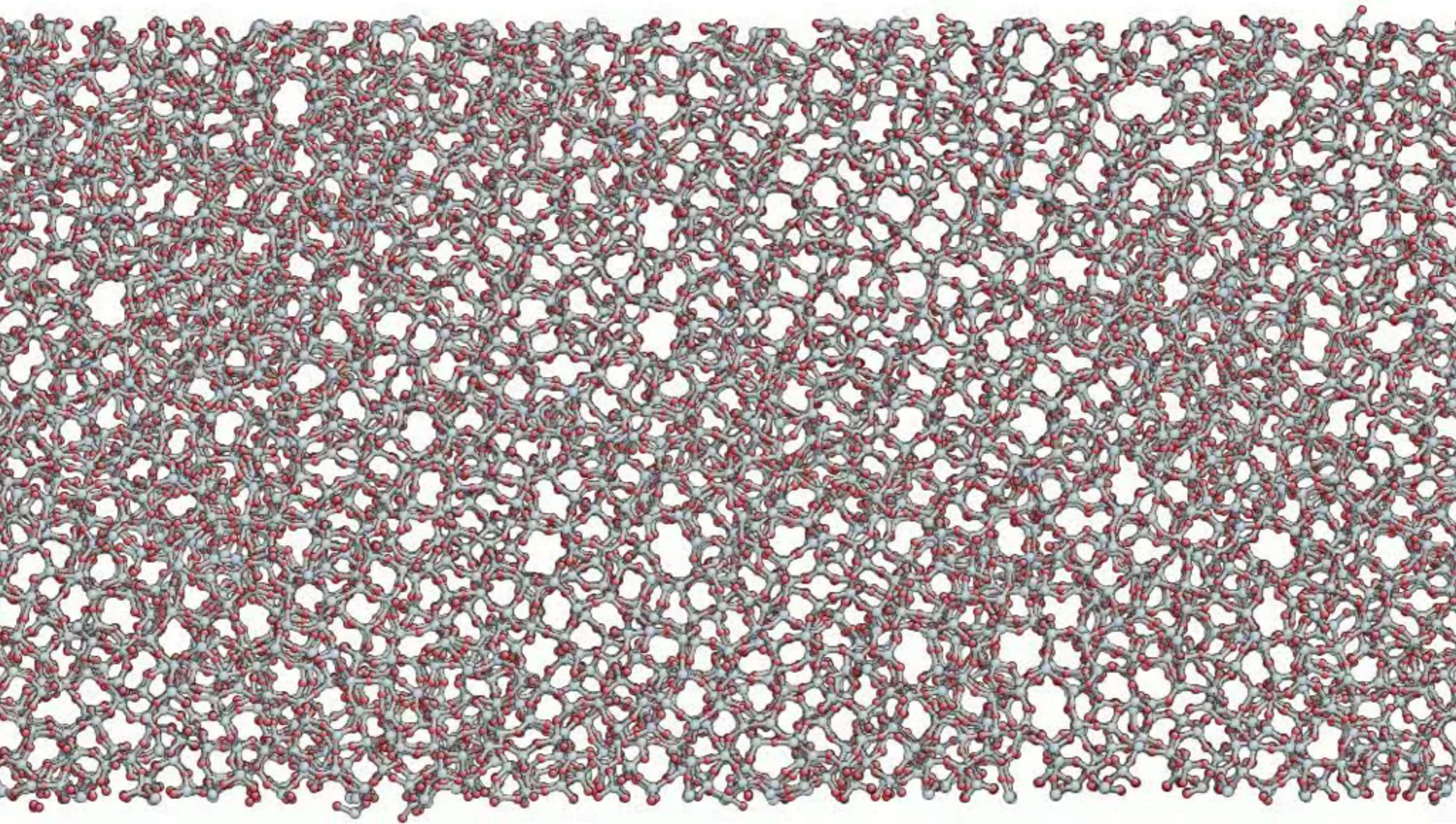


$$\mathbf{p}_i = \alpha_i \mathbf{E}_i(\{\mathbf{r}_j\}, \{\mathbf{p}_j\})$$

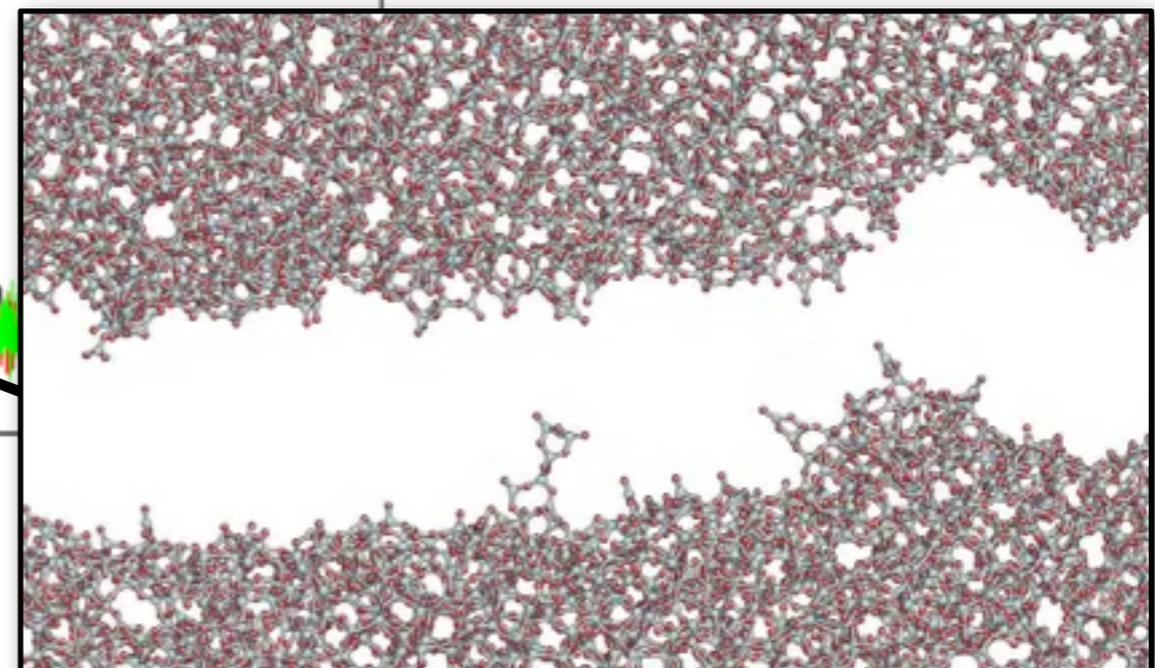
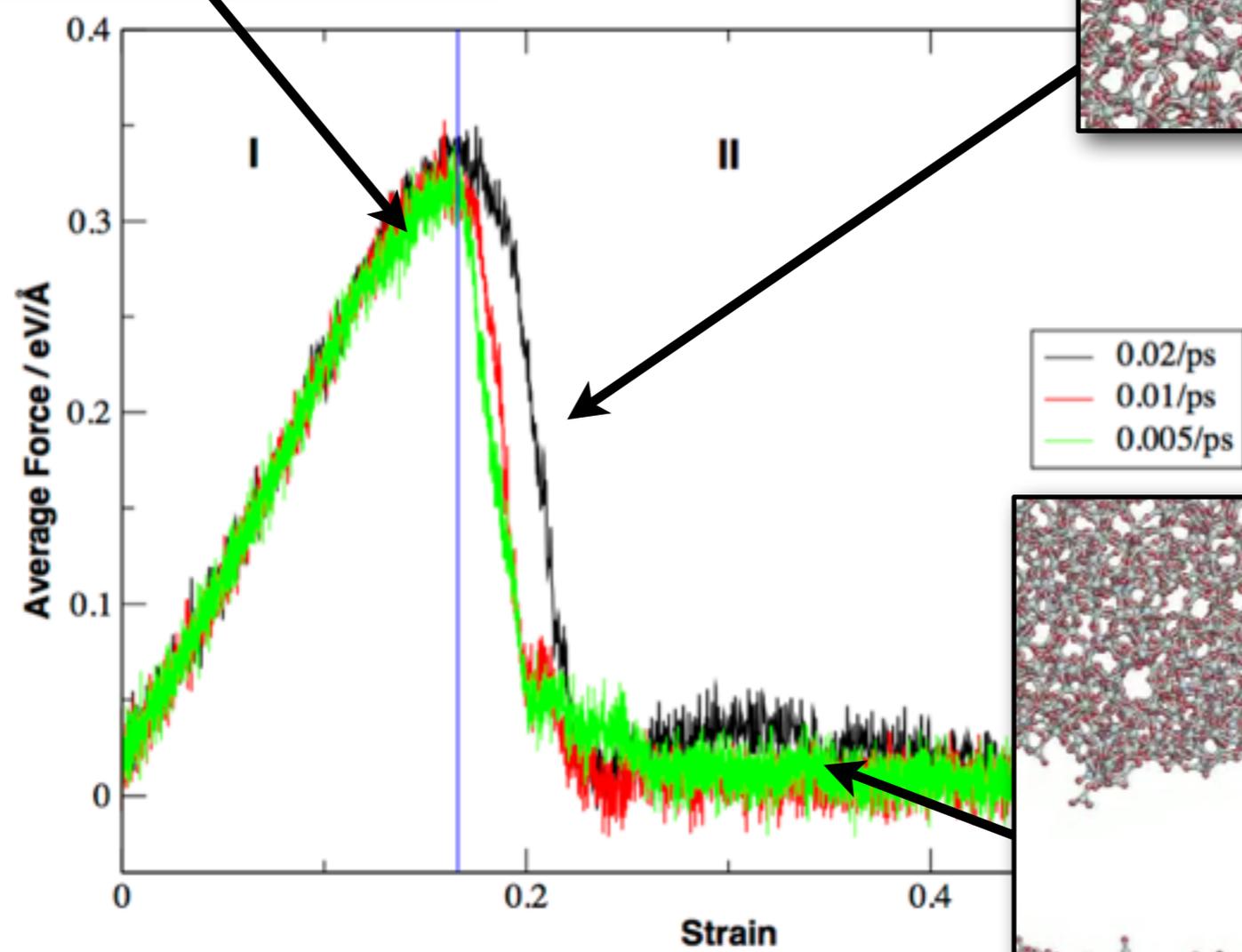
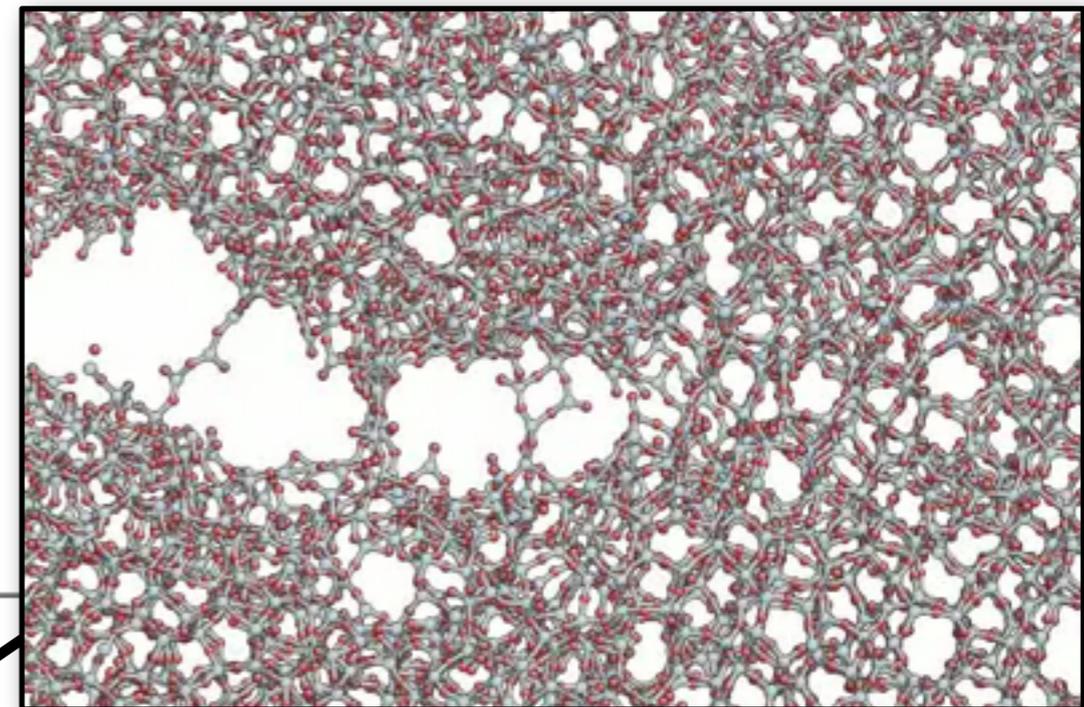
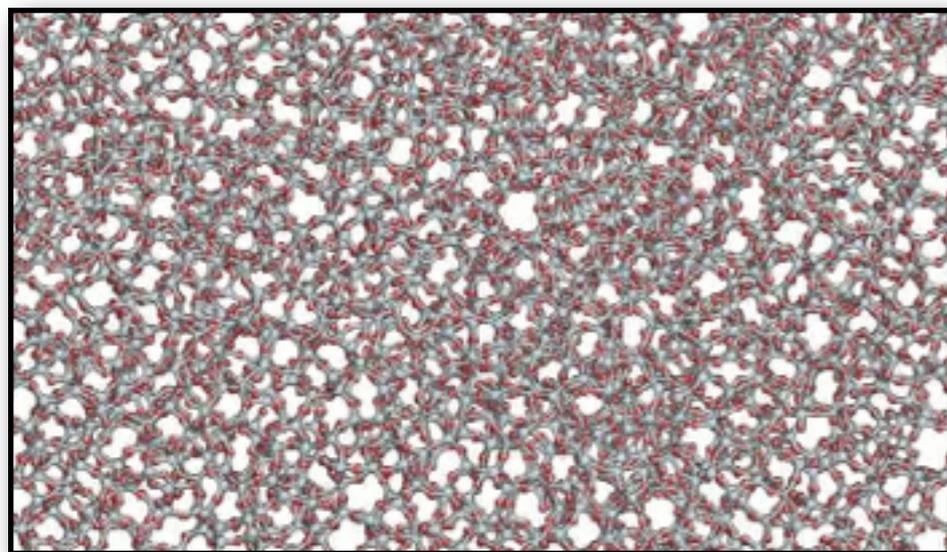
Short range (Yukawa):  $\frac{Q_i Q_j}{r_{ij}} \rightarrow \frac{Q_i Q_j}{r_{ij}} e^{-\alpha r}$



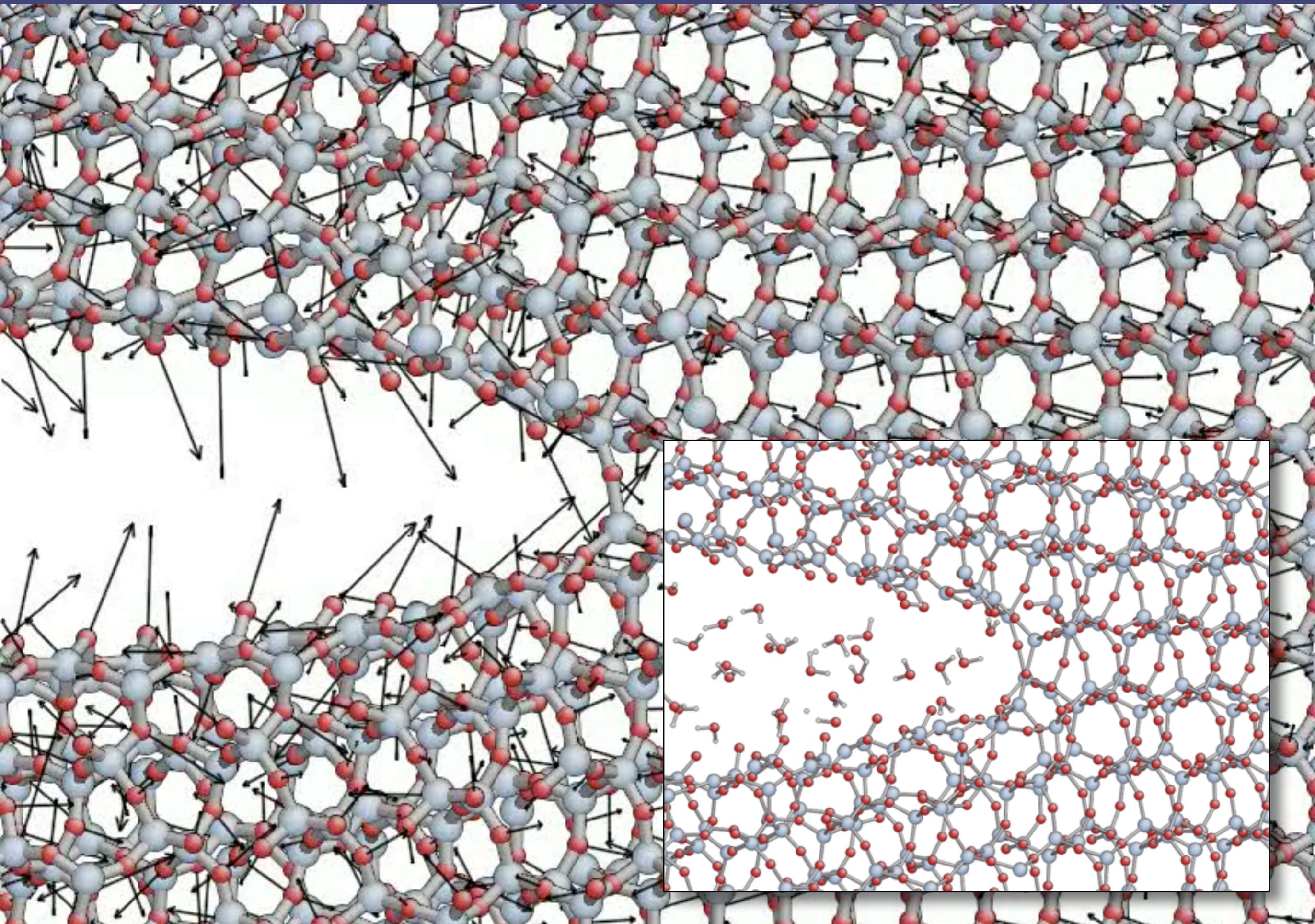
# Stress response of amorphous silica to applied strain



# Stress response of amorphous silica to applied strain

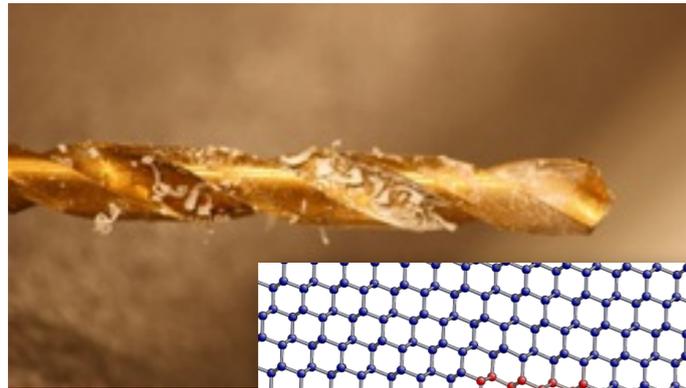


# QM-based simulations of brittle fracture in quartz

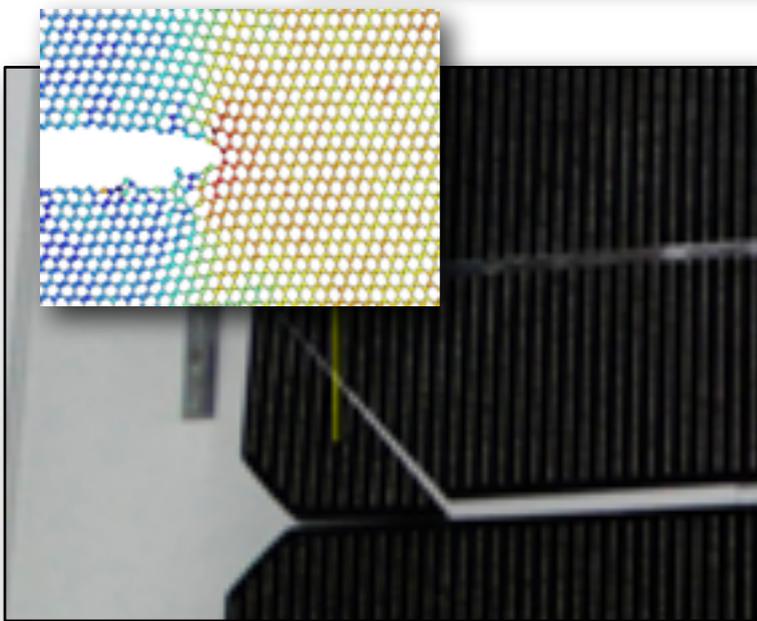
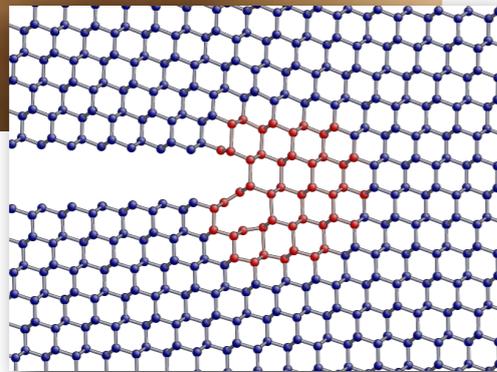


# Multiscale Modelling of “Chemomechanical” Materials Failure Processes

## Covalent Materials



Diamond

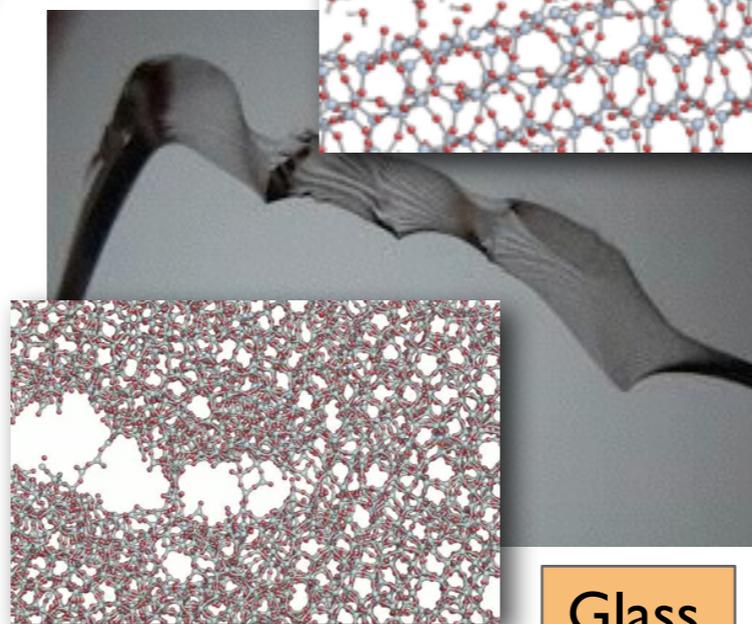
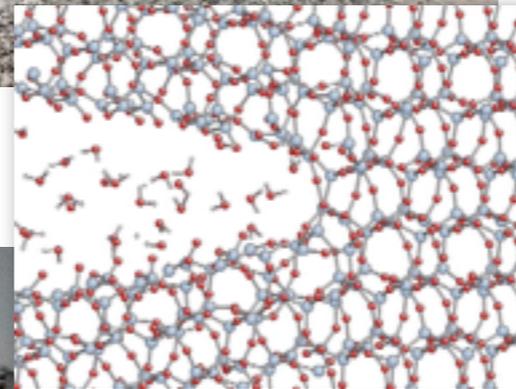


Silicon Photovoltaics

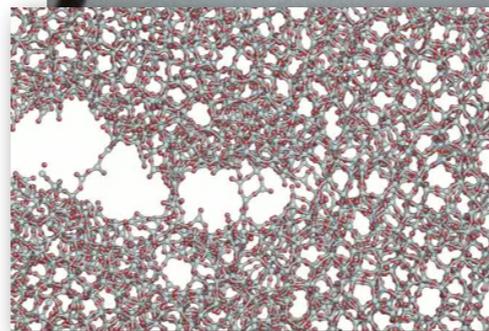
## Oxides



Rocks



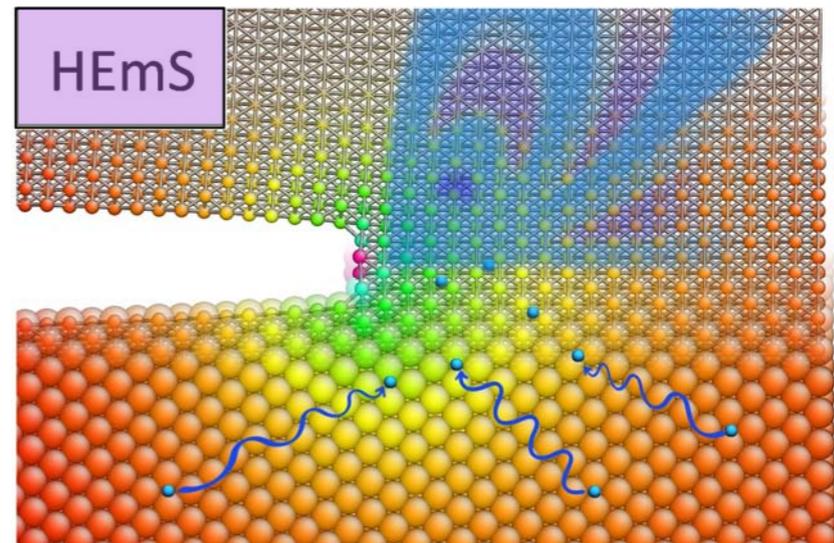
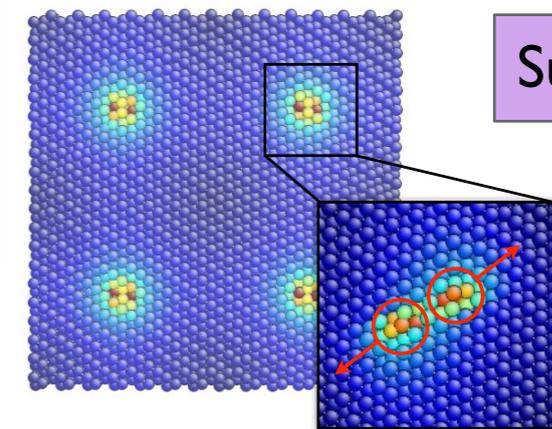
Glass



## Metals



Superalloys



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